

LOW SPEED USB 8-BIT MCU FAMILY WITH UP TO 8K FLASH/ROM AND SERIAL COMMUNICATION INTERFACE (SCI)

■ Memories

- 4 or 8 Kbytes Program Memory: High Density Flash (HDFlash), FastROM or ROM with Readout and Write Protection
- In-Application Programming (IAP) and In-Circuit programming (ICP)
- 384 bytes RAM memory (128-byte stack)

■ Clock, Reset and Supply Management

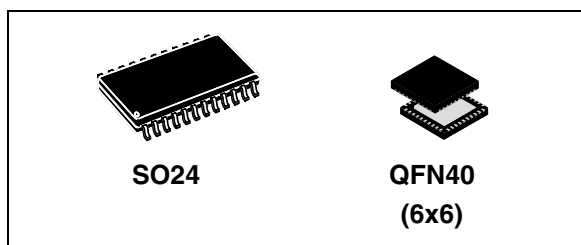
- Run, Wait, Slow and Halt CPU modes
- 12 or 24 MHz Oscillator
- RAM Retention mode
- Optional Low Voltage Detector (LVD)

■ USB (Universal Serial Bus) Interface

- DMA for low speed applications compliant with USB 1.5 Mbs (version 2.0) and HID specifications (version 1.0)
- Integrated 3.3 V voltage regulator and transceivers
- Supports USB DFU class specification
- Suspend and Resume operations
- 3 Endpoints with programmable In/Out configuration

■ Up to 19 I/O Ports

- Up to 8 high sink I/Os (10 mA at 1.3 V)
- 2 very high sink true open drain I/Os (25 mA at 1.5 V)
- Up to 8 lines individually programmable as interrupt inputs



■ 2 Timers

- Programmable Watchdog
- 16-bit Timer with 2 Input Captures, 2 Output Compares, PWM output and clock input

■ 1 Communication Interface

- Asynchronous Serial Communications Interface

■ Instruction Set

- 63 basic instructions
- 17 main addressing modes
- 8 x 8 unsigned multiply instruction
- True bit manipulation

■ Development Tools

- Versatile Development Tools (under Windows) including assembler, linker, C-compiler, archiver, source level debugger, software library, hardware emulator, programming boards and gang programmers, HID and DFU software layers

Table 1. Device Summary

Features	ST7260K2	ST7260K1	ST7260E2	ST7260E1
Program Memory -bytes (Flash or ROM)	8 K	4 K	8 K	4 K
RAM (stack) - bytes	384 (128)			
Standard Peripherals	Watchdog timer, 16-bit timer, USB			
Other Peripherals	SCI			
Operating Supply	4.0 V to 5.5 V			
CPU frequency	8 MHz (with 24 MHz oscillator) or 4 MHz (with 12 MHz oscillator)			
Operating temperature	0 °C to +70 °C			
Packages	QFN40 (6x6)	QFN40 (6x6)	SO24	

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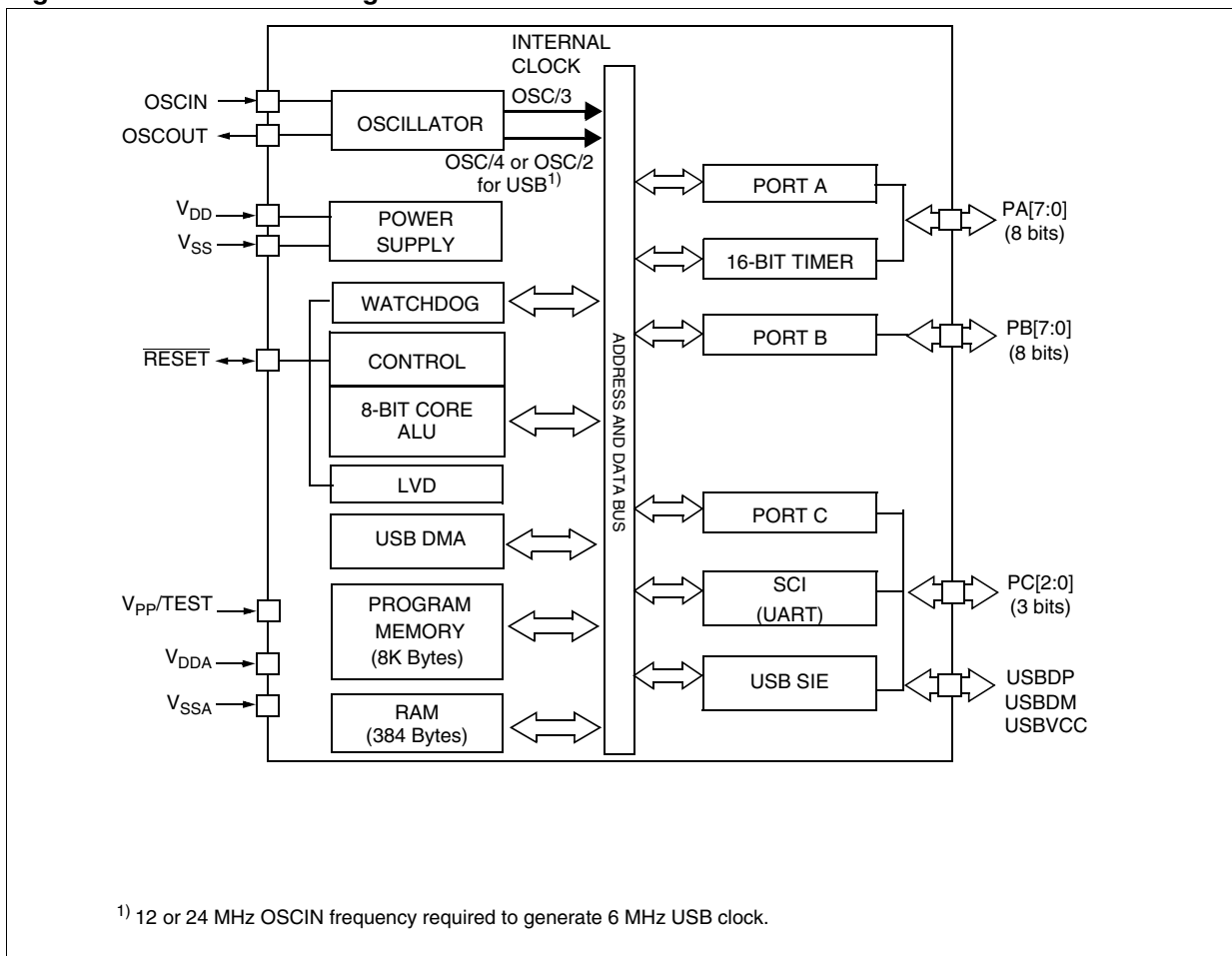
1 INTRODUCTION

The ST7260 Microcontrollers form a sub-family of the ST7 MCUs dedicated to USB applications. The devices are based on an industry-standard 8-bit core and feature an enhanced instruction set. They operate at a 24 MHz or 12 MHz oscillator frequency. Under software control, the ST7260 MCUs may be placed in either Wait or Halt modes, thus reducing power consumption. The enhanced instruction set and addressing modes afford real programming potential. In addition to standard 8-bit data management, the ST7260 MCUs feature true bit manipulation, 8x8 unsigned multiplication and indirect addressing modes. The devices include an ST7 Core, up to 8Kbytes of program memory, up to 384 bytes of RAM, 19 I/O lines and the following on-chip peripherals:

- USB low speed interface with 3 endpoints with programmable in/out configuration using the DMA architecture with embedded 3.3V voltage regulator and transceivers (no external components are needed).
- Industry standard asynchronous SCI serial interface
- Watchdog
- 16-bit Timer featuring an External clock input, 2 Input Captures, 2 Output Compares with Pulse Generator capabilities
- Low voltage reset (LVD) ensuring proper power-on or power-off of the device

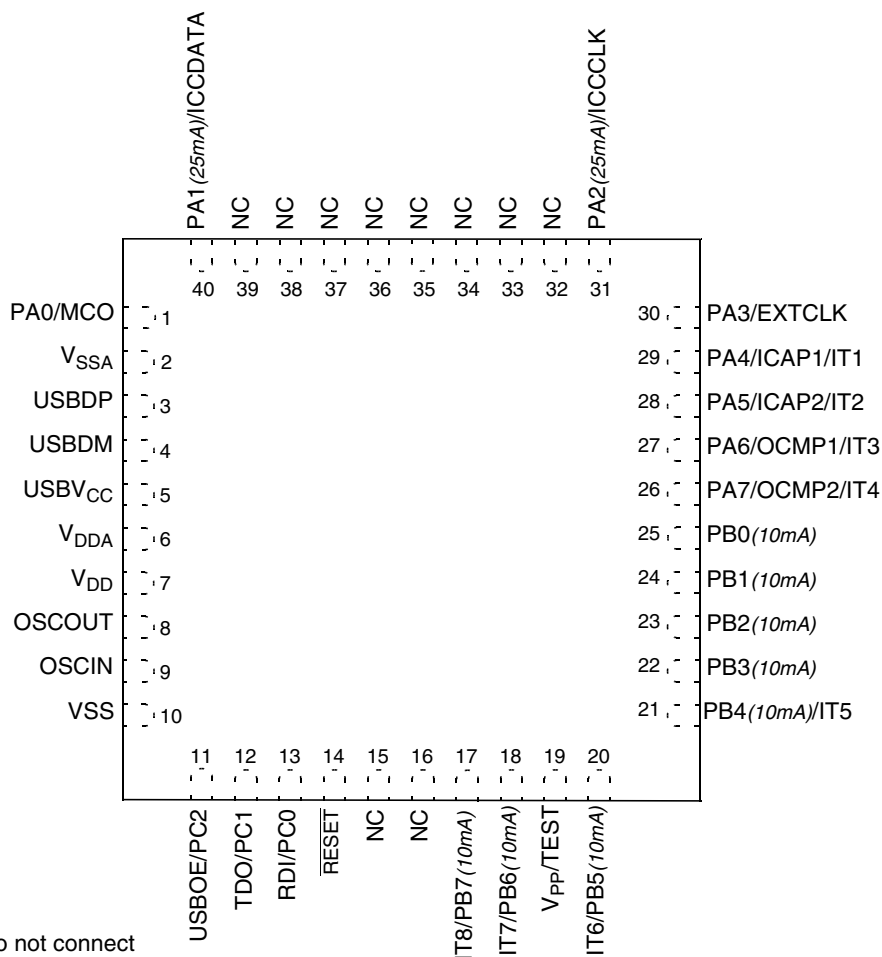
The ST72F60 devices are Flash versions. They support programming in IAP mode (In-application programming) via the on-chip USB interface.

Figure 1. General Block Diagram



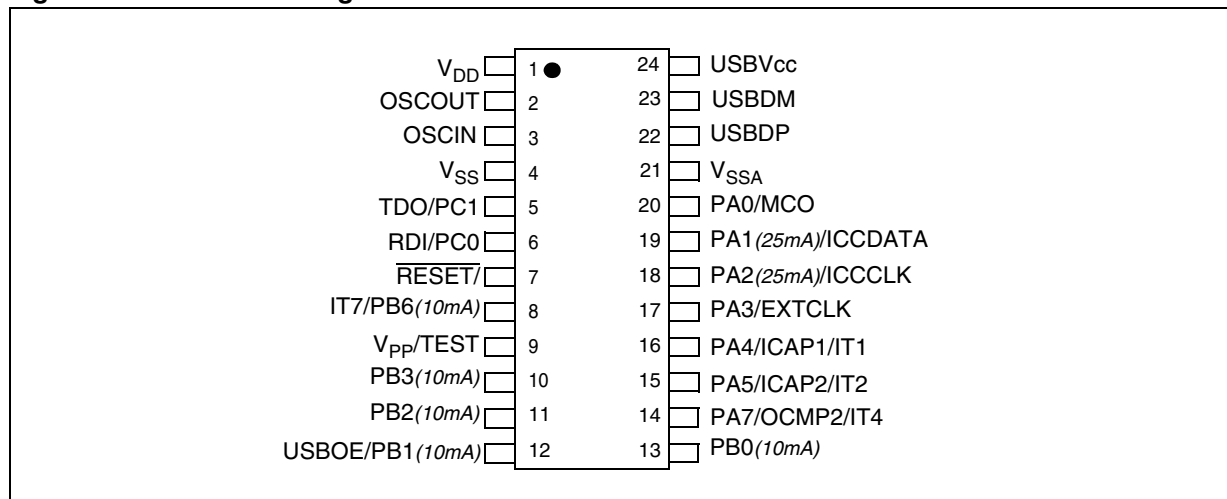
2 PIN DESCRIPTION

Figure 2. 40-Lead QFN Package Pinout



Note: NC=Do not connect

Figure 3. 24-Pin SO Package Pinout



PIN DESCRIPTION (Cont'd)

RESET (see Note 1): Bidirectional. This active low signal forces the initialization of the MCU. This event is the top priority non maskable interrupt. This pin is switched low when the Watchdog is triggered or the V_{DD} is low. It can be used to reset external peripherals.

OSCIN/OSCAUT: Input/Output Oscillator pin. These pins connect a parallel-resonant crystal, or an external source, to the on-chip oscillator.

V_{DD}/V_{SS} (see Note 2): Main Power Supply and Ground voltages.

V_{DDA}/V_{SSA} (see Note 2): Power Supply and Ground voltages for analog peripherals.

Alternate Functions: Several pins of the I/O ports assume software programmable alternate functions as shown in the pin description.

Legend / Abbreviations for Table 2, Table 3:

Type: I = input, O = output, S = supply

In/Output level: C_T = CMOS $0.3 V_{DD} / 0.7 V_{DD}$ with input trigger

Output level: 10 mA = 10 mA high sink (Fn N-buffer only)

25 mA = 25 mA very high sink (on N-buffer only)

Port and control configuration:

– Input: float = floating, wpu = weak pull-up, int = interrupt

– Output: OD = open drain, PP = push-pull, T = True open drain

The RESET configuration of each pin is shown in bold. This configuration is kept as long as the device is under reset state.

Note 1: Adding two 100 nF decoupling capacitors on the Reset pin (respectively connected to V_{DD} and V_{SS}) will significantly improve product electro-magnetic susceptibility performance.

Note 2: To enhance the reliability of operation, it is recommended that V_{DDA} and V_{DD} be connected together on the application board. This also applies to V_{SSA} and V_{SS} .

Note 3: The USBOE alternate function is mapped on Port C2 in QFN40 devices. In SO24 devices it is mapped on Port B1.

Note 4: The timer OCMP1 alternate function is mapped on Port A6 in QFN40 pin devices. In SO24 devices it is not available.

Table 2. Device Pin Description (QFN40)

Pin n°	Pin Name	Type	Level		Port / Control					Main Function (after reset)	Alternate Function
QFN40			Input	Output	Input			Output			
					float	wpu	int	OD	PP		
7	V _{DD}	S								Power supply voltage (4V - 5.5V)	
8	OSCOOUT	O								Oscillator output	
9	OSCIN	I								Oscillator input	
10	V _{SS}	S								Digital ground	
11	PC2/USBOE	I/O	C _T			X			X	Port C2	USB Output Enable
12	PC1/TDO	I/O	C _T			X			X	Port C1	SCI Transmit Data Output
13	PC0/RDI	I/O	C _T			X			X	Port C0	SCI Receive Data Input
14	$\overline{\text{RESET}}$	I/O				X		X		Reset	
15	NC	--								Not connected	
16	NC	--								Not connected	
17	PB7/IT8	I/O	C _T	10mA	X		X		X	Port B7	
18	PB6/IT7	I/O	C _T	10mA	X		X		X	Port B6	
19	V _{PP} /TEST	S								Programming supply	
20	PB5/IT6	I/O	C _T	10mA	X		X		X	Port B5	
21	PB4/IT5	I/O	C _T	10mA	X		X		X	Port B4	
22	PB3	I/O	C _T	10mA	X				X	Port B3	
23	PB2	I/O	C _T	10mA	X				X	Port B2	
24	PB1	I/O	C _T	10mA	X				X	Port B1	
25	PB0	I/O	C _T	10mA	X				X	Port B0	
26	PA7/OCMP2/IT4	I/O	C _T			X	X		X	Port A7	Timer Output Compare 2
27	PA6/OCMP1/IT3	I/O	C _T			X	X		X	Port A6	Timer Output Compare 1
28	PA5/ICAP2/IT2	I/O	C _T			X	X		X	Port A5	Timer Input Capture 2
29	PA4/ICAP1/IT1	I/O	C _T			X	X		X	Port A4	Timer Input Capture 1
30	PA3/EXTCLK	I/O	C _T			X			X	Port A3	Timer External Clock
31	PA2/ICCLK	I/O	C _T	25mA	X			T		Port A2	ICC Clock
32	NC	--								Do not connect	
33	NC	--								Do not connect	
34	NC	--								Do not connect	
35	NC	--								Do not connect	
36	NC	--								Do not connect	
37	NC	--								Do not connect	
38	NC	--								Do not connect	

Pin n°	Pin Name	Type	Level		Port / Control					Main Function (after reset)	Alternate Function
QFN40			Input	Output	Input			Output			
					float	wpu	int	OD	PP		
39	NC	--								Do not connect	
40	PA1/ICCDATA	I/O	C _T	25mA	X			T		Port A1	ICC Data
1	PA0/MCO	I/O	C _T				X		X	Port A0	Main Clock Output
2	V _{SSA}	S								Analog ground	
3	USBDP	I/O								USB bidirectional data (data +)	
4	USBDM	I/O								USB bidirectional data (data -)	
5	USBVCC	O								USB power supply	
6	V _{DDA}	S								Analog supply voltage	

Table 3. Device Pin Description (SO24)

Pin n°	Pin Name	Type	Level		Port / Control					Main Function (after reset)	Alternate Function
SO24			Input	Output	Input			Output			
					float	wpu	int	OD	PP		
1	V _{DD}	S								Power supply voltage (4V - 5.5V)	
2	OSCOUT	O								Oscillator output	
3	OSCIN	I								Oscillator input	
4	V _{SS}	S								Digital ground	
5	PC1/TDO	I/O	C _T			X			X	Port C1	SCI Transmit Data Output
6	PC0/RDI	I/O	C _T			X			X	Port C0	SCI Receive Data Input
7	RESET	I/O				X		X		Reset	
8	PB6/IT7	I/O	C _T	10mA	X		X		X	Port B6	
9	V _{PP} /TEST	S								Programming supply	
10	PB3	I/O	C _T	10mA	X				X	Port B3	
11	PB2	I/O	C _T	10mA	X				X	Port B2	
12	PB1/USBOE	I/O	C _T	10mA	X				X	Port B1	USB Output Enable
13	PB0	I/O	C _T	10mA	X				X	Port B0	
14	PA7/OCMP2/IT4	I/O	C _T			X	X		X	Port A7	Timer Output Compare 2
15	PA5/ICAP2/IT2	I/O	C _T			X	X		X	Port A5	Timer Input Capture 2
16	PA4/ICAP1/IT1	I/O	C _T			X	X		X	Port A4	Timer Input Capture 1
17	PA3/EXTCLK	I/O	C _T			X			X	Port A3	Timer External Clock
18	PA2/ICCCCLK	I/O	C _T	25mA	X			T		Port A2	ICC Clock
19	PA1/ICCDATA	I/O	C _T	25mA	X			T		Port A1	ICC Data

Pin n°	Pin Name	Type	Level		Port / Control					Main Function (after reset)	Alternate Function
SO24			Input	Output	Input			Output			
					float	wpu	int	OD	PP		
20	PA0/MCO	I/O	C _T				X		X	Port A0	Main Clock Output
21	V _{SSA}	S								Analog ground	
22	USBDP	I/O								USB bidirectional data (data +)	
23	USBDM	I/O								USB bidirectional data (data -)	
24	USBVCC	O								USB power supply	

3 REGISTER & MEMORY MAP

As shown in Figure 4, the MCU is capable of addressing 8 Kbytes of memories and I/O registers.

The available memory locations consist of up to 384 bytes of RAM including 64 bytes of register locations, and up to 8K bytes of user program memory in which the upper 32 bytes are reserved for interrupt vectors. The RAM space includes up to 128 bytes for the stack from 0100h to 017Fh.

The highest address bytes contain the user reset and interrupt vectors.

IMPORTANT: Memory locations noted “Reserved” must never be accessed. Accessing a reserved area can have unpredictable effects on the device.

Figure 4. Memory Map

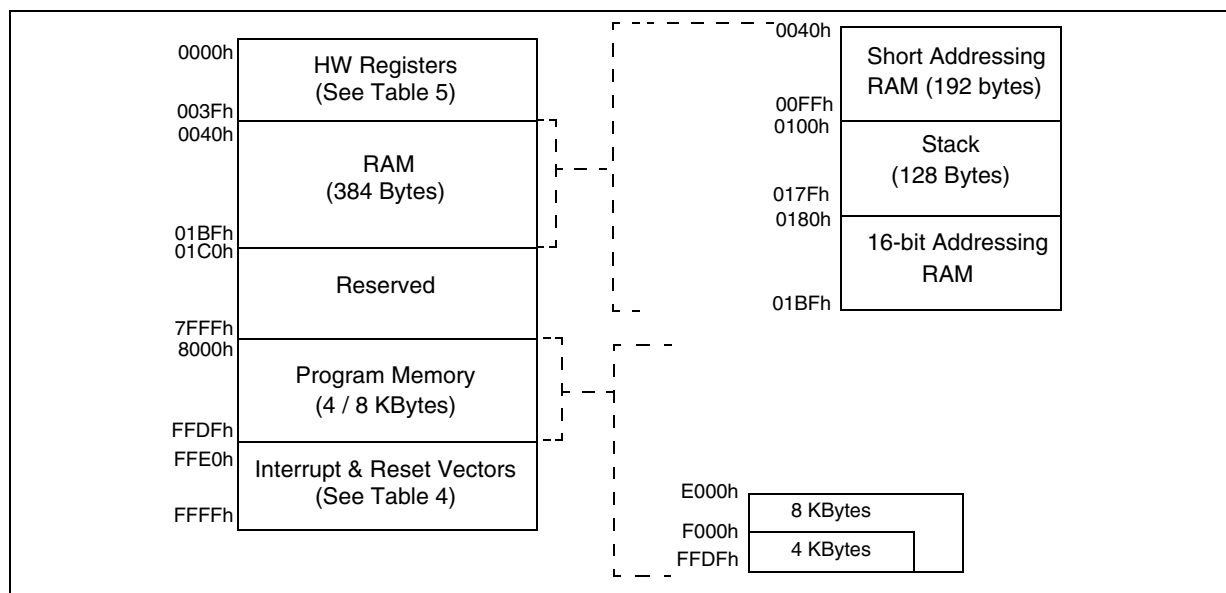


Table 4. Interrupt Vector Map

Vector Address	Description	Masked by	Remarks	Exit from Halt Mode
FFE0h-FFEDh	Reserved Area			
FFEEh-FFEFh	USB Interrupt Vector	I- bit	Internal Interrupt	No
FFF0h-FFF1h	SCI Interrupt Vector	I- bit	Internal Interrupt	No
FFF2h-FFF3h	Reserved Area			
FFF4h-FFF5h	TIMER Interrupt Vector	I- bit	Internal Interrupt	No
FFF6h-FFF7h	IT1 to IT8 Interrupt Vector	I- bit	External Interrupt	Yes
FFF8h-FFF9h	USB End Suspend Mode Interrupt Vector	I- bit	External Interrupts	Yes
FFFAh-FFFBh	Flash Start Programming Interrupt Vector	I- bit	Internal Interrupt	Yes
FFFC h-FFFDh	TRAP (software) Interrupt Vector	None	CPU Interrupt	No
FFFEh-FFFFh	RESET Vector	None		Yes

Table 5. Hardware Register Memory Map

Address	Block	Register Label	Register name	Reset Status	Remarks
0000h 0001h	Port A	PADR	Port A Data Register	00h	R/W
		PADDR	Port A Data Direction Register	00h	R/W
0002h 0003h	Port B	PBDR	Port B Data Register	00h	R/W
		PBDDR	Port B Data Direction Register	00h	R/W
0004h 0005h	Port C	PCDR	Port C Data Register	1111 x000b	R/W
		PCDDR	Port C Data Direction Register	1111 x000b	R/W
0006h to 0007h	Reserved (2 bytes)				
0008h	ITC	ITIFRE	Interrupt Register	00h	R/W
0009h	MISC	MISCR	Miscellaneous Register	00h	R/W
000Ah to 000Bh	Reserved (2 bytes)				
000Ch	WDG	WDGCR	Watchdog Control Register	7Fh	R/W
000Dh to 0010h	Reserved (4 bytes)				
0011h	TIM	TCR2	Timer Control Register 2	00h	R/W
0012h		TCR1	Timer Control Register 1	00h	R/W
0013h		TCSR	Timer Control/Status Register	00h	R/W
0014h		TIC1HR	Timer Input Capture High Register 1	xxh	Read only
0015h		TIC1LR	Timer Input Capture Low Register 1	xxh	Read only
0016h		TOC1HR	Timer Output Compare High Register 1	80h	R/W
0017h		TOC1LR	Timer Output Compare Low Register 1	00h	R/W
0018h		TCHR	Timer Counter High Register	FFh	Read only
0019h		TCLR	Timer Counter Low Register	FCh	R/W
001Ah		TACHR	Timer Alternate Counter High Register	FFh	Read only
001Bh		TACL	Timer Alternate Counter Low Register	FCh	R/W
001Ch		TIC2HR	Timer Input Capture High Register 2	xxh	Read only
001Dh		TIC2LR	Timer Input Capture Low Register 2	xxh	Read only
001Eh		TOC2HR	Timer Output Compare High Register 2	80h	R/W
001Fh		TOC2LR	Timer Output Compare Low Register 2	00h	R/W
0020h	SCI	SCISR	SCI Status Register	C0h	Read only
0021h		SCIDR	SCI Data Register	xxh	R/W
0022h		SCIBRR	SCI Baud Rate Register	00h	R/W
0023h		SCICR1	SCI Control Register 1	x000 0000b	R/W
0024h		SCICR2	SCI Control Register 2	00h	R/W

Address	Block	Register Label	Register name	Reset Status	Remarks
0025h	USB	USBPIDR	USB PID Register	x0h	Read only
0026h		USBDMAR	USB DMA address Register	xxh	R/W
0027h		USBIDR	USB Interrupt/DMA Register	x0h	R/W
0028h		USBISTR	USB Interrupt Status Register	00h	R/W
0029h		USBIMR	USB Interrupt Mask Register	00h	R/W
002Ah		USBCTLR	USB Control Register	06h	R/W
002Bh		USBDADDR	USB Device Address Register	00h	R/W
002Ch		USBEP0RA	USB Endpoint 0 Register A	0000 xxxxb	R/W
002Dh		USBEP0RB	USB Endpoint 0 Register B	80h	R/W
002Eh		USBEP1RA	USB Endpoint 1 Register A	0000 xxxxb	R/W
002Fh		USBEP1RB	USB Endpoint 1 Register B	0000 xxxxb	R/W
0030h		USBEP2RA	USB Endpoint 2 Register A	0000 xxxxb	R/W
0031h		USBEP2RB	USB Endpoint 2 Register B	0000 xxxxb	R/W
0032h 0036h	Reserved (5 Bytes)				
0037h	Flash	FCSR	Flash Control /Status Register	00h	R/W
0038h to 003Fh	Reserved (8 bytes)				

4 FLASH PROGRAM MEMORY

4.1 INTRODUCTION

The ST7 dual voltage High Density Flash (HDFlash) is a non-volatile memory that can be electrically erased as a single block or by individual sectors and programmed on a Byte-by-Byte basis using an external V_{PP} supply.

The HDFlash devices can be programmed and erased off-board (plugged in a programming tool) or on-board using ICP (In-Circuit Programming) or IAP (In-Application Programming).

The array matrix organisation allows each sector to be erased and reprogrammed without affecting other sectors.

4.2 MAIN FEATURES

- 3 Flash programming modes:
 - Insertion in a programming tool. In this mode, all sectors including option bytes can be programmed or erased.
 - ICP (In-Circuit Programming). In this mode, all sectors including option bytes can be programmed or erased without removing the device from the application board.
 - IAP (In-Application Programming) In this mode, all sectors except Sector 0, can be programmed or erased without removing the device from the application board and while the application is running.
- ICT (In-Circuit Testing) for downloading and executing user application test patterns in RAM
- Read-out protection
- Register Access Security System (RASS) to prevent accidental programming or erasing

4.3 STRUCTURE

The Flash memory is organised in sectors and can be used for both code and data storage.

Depending on the overall Flash memory size in the microcontroller device, there are up to three user sectors (see Table 6). Each of these sectors can be erased independently to avoid unnecessary erasing of the whole Flash memory when only a partial erasing is required.

The first two sectors have a fixed size of 4 Kbytes (see Figure 5). They are mapped in the upper part of the ST7 addressing space so the reset and interrupt vectors are located in Sector 0 (F000h-FFFFh).

Table 6. Sectors available in Flash devices

Flash Size (bytes)	Available Sectors
4K	Sector 0
8K	Sectors 0,1
> 8K	Sectors 0,1, 2

4.3.1 Read-out Protection

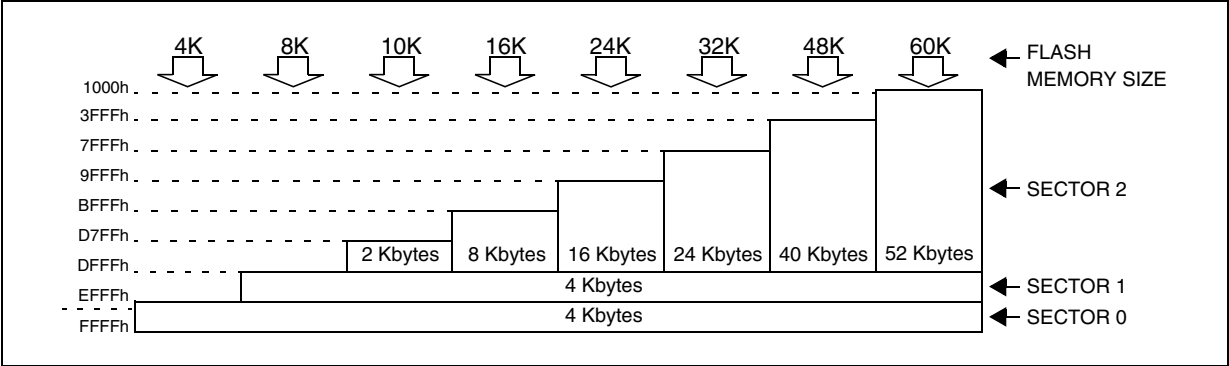
Read-out protection, when selected, provides a protection against Program Memory content extraction and against write access to Flash memory. Even if no protection can be considered as totally unbreakable, the feature provides a very high level of protection for a general purpose microcontroller.

In Flash devices, this protection is removed by re-programming the option. In this case, the entire program memory is first automatically erased and the device can be reprogrammed.

Read-out protection selection depends on the device type:

- In Flash devices it is enabled and removed through the FMP_R bit in the option byte.
- In ROM devices it is enabled by mask option specified in the Option List.

Figure 5. Memory Map and Sector Address



FLASH PROGRAM MEMORY (Cont'd)

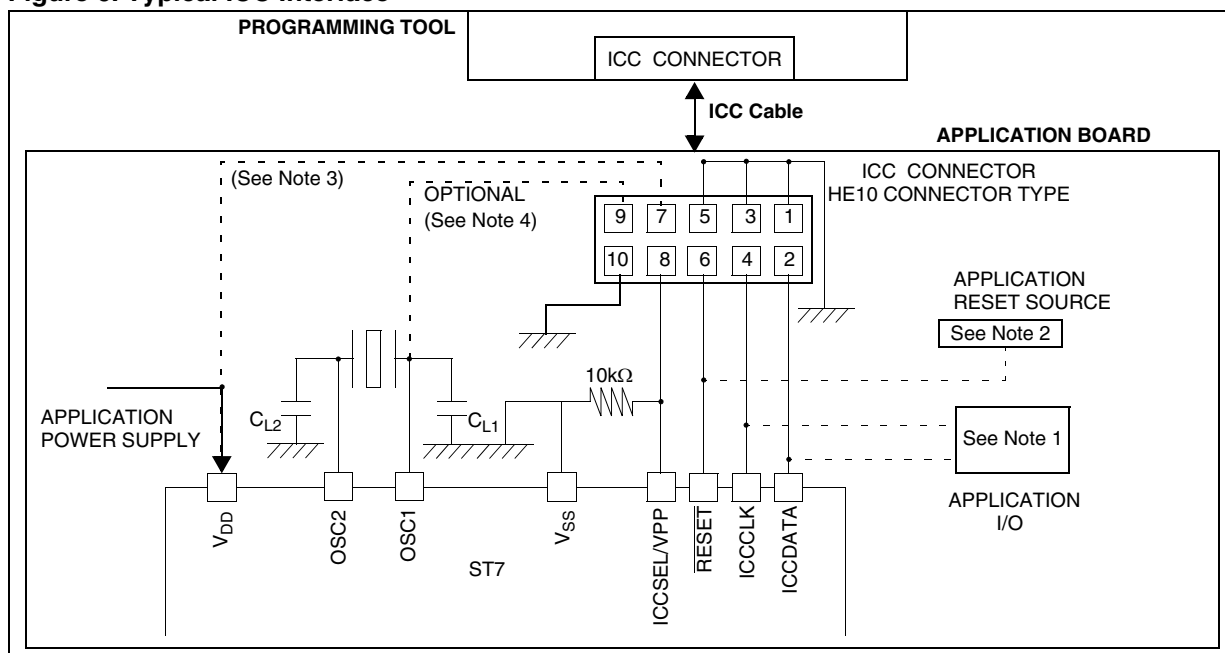
4.4 ICC INTERFACE

ICC (In-Circuit Communication) needs a minimum of four and up to six pins to be connected to the programming tool (see Figure 6). These pins are:

- RESET: device reset
- V_{SS}: device power supply ground

- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input/output serial data pin
- ICCSEL/V_{PP}: programming voltage
- OSC1(or OSCIN): main clock input for external source (optional)
- V_{DD}: application board power supply (see Figure 6, Note 3)

Figure 6. Typical ICC Interface



Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to be implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the ICC session, the programming tool must control the RESET pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor < 1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with R > 1K or a reset man-

agement IC with open drain output and pull-up resistor > 1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

3. The use of Pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 or OSCIN pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multi-oscillator capability need to have OSC2 grounded in this case.

FLASH PROGRAM MEMORY (Cont'd)

4.5 ICP (IN-CIRCUIT PROGRAMMING)

To perform ICP the microcontroller must be switched to ICC (In-Circuit Communication) mode by an external controller or programming tool.

Depending on the ICP code downloaded in RAM, Flash memory programming can be fully customized (number of bytes to program, program locations, or selection serial communication interface for downloading).

When using an STMicroelectronics or third-party programming tool that supports ICP and the specific microcontroller device, the user needs only to implement the ICP hardware interface on the application board (see [Figure 6](#)). For more details on the pin locations, refer to the device pinout description.

4.6 IAP (IN-APPLICATION PROGRAMMING)

This mode uses a BootLoader program previously stored in Sector 0 by the user (in ICP mode or by plugging the device in a programming tool).

This mode is fully controlled by user software. This allows it to be adapted to the user application, (user-defined strategy for entering programming mode, choice of communications protocol used to fetch the data to be stored, etc.). For example, it is possible to download code from the SPI, SCI or other type of serial interface and program it in the Flash. IAP mode can be used to program any of the Flash sectors except Sector 0, which is write/erase protected to allow recovery in case errors occur during the programming operation.

4.7 RELATED DOCUMENTATION

For details on Flash programming and ICC protocol, refer to the *ST7 Flash Programming Reference Manual* and to the *ST7 ICC Protocol Reference Manual*.

4.8 REGISTER DESCRIPTION

FLASH CONTROL/STATUS REGISTER (FCSR)

Read/Write

Reset Value: 0000 0000 (00h)

7				0			
0	0	0	0	0	0	0	0

This register is reserved for use by Programming Tool software. It controls the Flash programming and erasing operations.

5 CENTRAL PROCESSING UNIT

5.1 INTRODUCTION

This CPU has a full 8-bit architecture and contains six internal registers allowing efficient 8-bit data manipulation.

5.2 MAIN FEATURES

- 63 basic instructions
- Fast 8-bit by 8-bit multiply
- 17 main addressing modes
- Two 8-bit index registers
- 16-bit stack pointer
- Low power modes
- Maskable hardware interrupts
- Non-maskable software interrupt

5.3 CPU REGISTERS

The six CPU registers shown in [Figure 7](#) are not present in the memory mapping and are accessed by specific instructions.

Accumulator (A)

The Accumulator is an 8-bit general purpose register used to hold operands and the results of the arithmetic and logic calculations and to manipulate data.

Index Registers (X and Y)

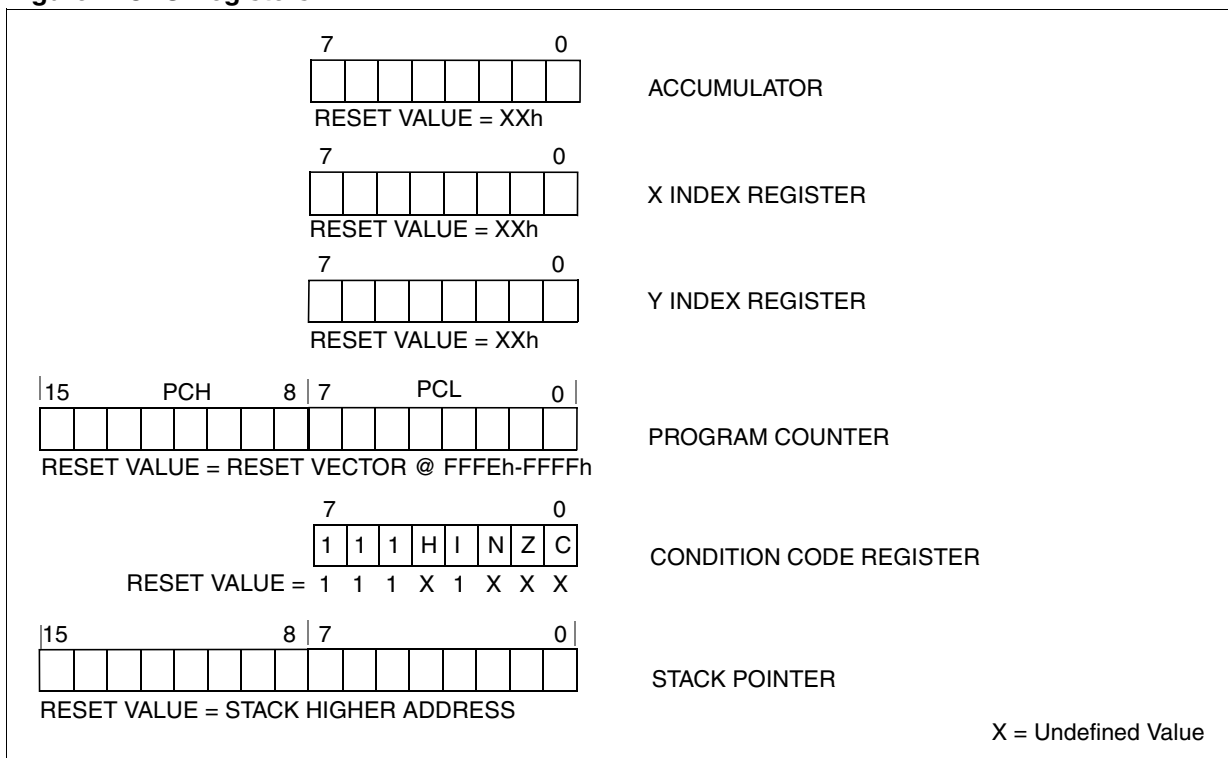
In indexed addressing modes, these 8-bit registers are used to create either effective addresses or temporary storage areas for data manipulation. (The Cross-Assembler generates a precede instruction (PRE) to indicate that the following instruction refers to the Y register.)

The Y register is not affected by the interrupt automatic procedures (not pushed to and popped from the stack).

Program Counter (PC)

The program counter is a 16-bit register containing the address of the next instruction to be executed by the CPU. It is made of two 8-bit registers PCL (Program Counter Low which is the LSB) and PCH (Program Counter High which is the MSB).

Figure 7. CPU Registers



CPU REGISTERS (Cont'd)**CONDITION CODE REGISTER (CC)**

Read/Write

Reset Value: 111x1xxx

7							0
1	1	1	H	I	N	Z	C

The 8-bit Condition Code register contains the interrupt mask and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Bit 4 = H Half carry

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instruction. It is reset by hardware during the same instructions.

0: No half carry has occurred.

1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 3 = I Interrupt mask

This bit is set by hardware when entering in interrupt or by software to disable all interrupts except the TRAP software interrupt. This bit is cleared by software.

0: Interrupts are enabled.

1: Interrupts are disabled.

This bit is controlled by the RIM, SIM and IRET instructions and is tested by the JRM and JRNM instructions.

Note: Interrupts requested while I is set are latched and can be processed when I is cleared. By default an interrupt routine is not interruptible

because the I bit is set by hardware at the start of the routine and reset by the IRET instruction at the end of the routine. If the I bit is cleared by software in the interrupt routine, pending interrupts are serviced regardless of the priority level of the current interrupt routine.

Bit 2 = N Negative

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It is a copy of the 7th bit of the result.

0: The result of the last operation is positive or null.

1: The result of the last operation is negative (that is, the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = Z Zero

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.

0: The result of the last operation is different from zero.

1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = C Carry/borrow

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.

0: No overflow or underflow has occurred.

1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

CPU REGISTERS (Cont'd)**STACK POINTER (SP)**

Read/Write

Reset Value: 017Fh

15							8
0	0	0	0	0	0	0	1
7							0
0	SP6	SP5	SP4	SP3	SP2	SP1	SP0

The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see [Figure 8](#)).

Since the stack is 128 bytes deep, the 9 most significant bits are forced by hardware. Following an MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP6 to SP0 bits are set) which is the stack higher address.

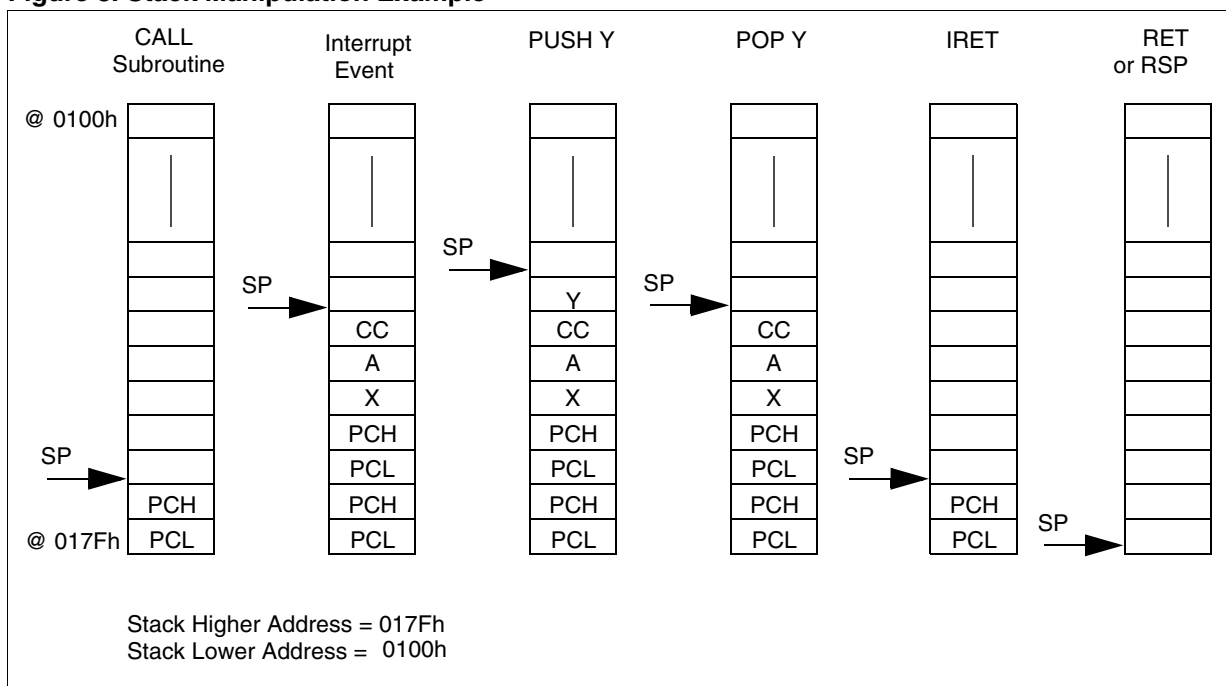
The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in [Figure 8](#).

- When an interrupt is received, the SP is decremented and the context is pushed on the stack.
- On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 8. Stack Manipulation Example

6 RESET AND CLOCK MANAGEMENT

6.1 RESET

The Reset procedure is used to provide an orderly software start-up or to exit low power modes.

Three reset modes are provided: a low voltage (LVD) reset, a watchdog reset and an external reset at the $\overline{\text{RESET}}$ pin.

A reset causes the reset vector to be fetched from addresses FFFEH and FFFFh in order to be loaded into the PC and with program execution starting from this point.

An internal circuitry provides a 4096 CPU clock cycle delay from the time that the oscillator becomes active.

6.1.1 Low Voltage Detector (LVD)

Low voltage reset circuitry generates a reset when V_{DD} is:

- below V_{IT+} when V_{DD} is rising,
- below V_{IT-} when V_{DD} is falling.

During low voltage reset, the $\overline{\text{RESET}}$ pin is held low, thus permitting the MCU to reset other devices.

It is recommended to make sure that the V_{DD} supply voltage rises monotonously when the device is exiting from Reset, to ensure the application functions properly.

6.1.2 Watchdog Reset

When a watchdog reset occurs, the $\overline{\text{RESET}}$ pin is pulled low permitting the MCU to reset other devices in the same way as the low voltage reset (Figure 9).

6.1.3 External Reset

The external reset is an active low input signal applied to the $\overline{\text{RESET}}$ pin of the MCU.

As shown in Figure 12, the $\overline{\text{RESET}}$ signal must stay low for a minimum of one and a half CPU clock cycles.

An internal Schmitt trigger at the $\overline{\text{RESET}}$ pin is provided to improve noise immunity.

Figure 9. Low Voltage Detector functional Diagram

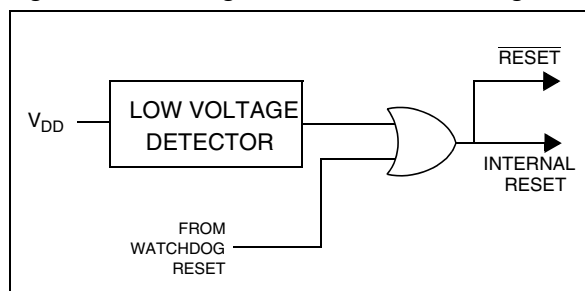
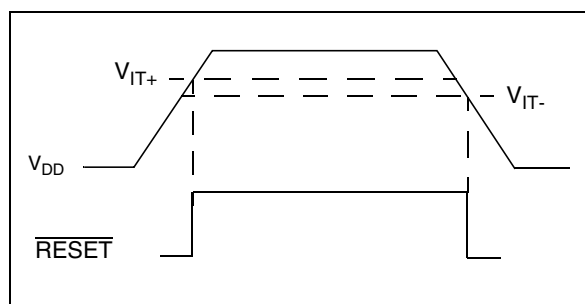
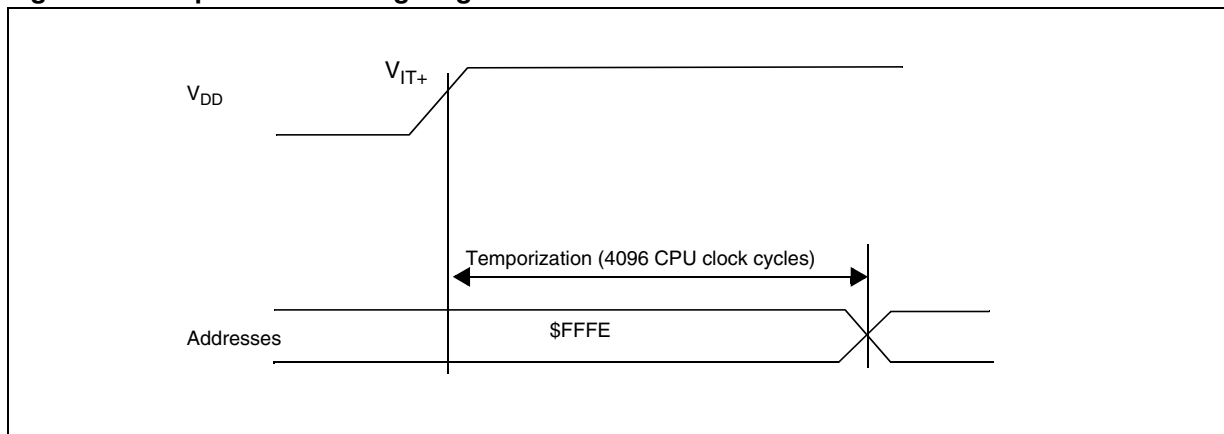


Figure 10. Low Voltage Reset Signal Output



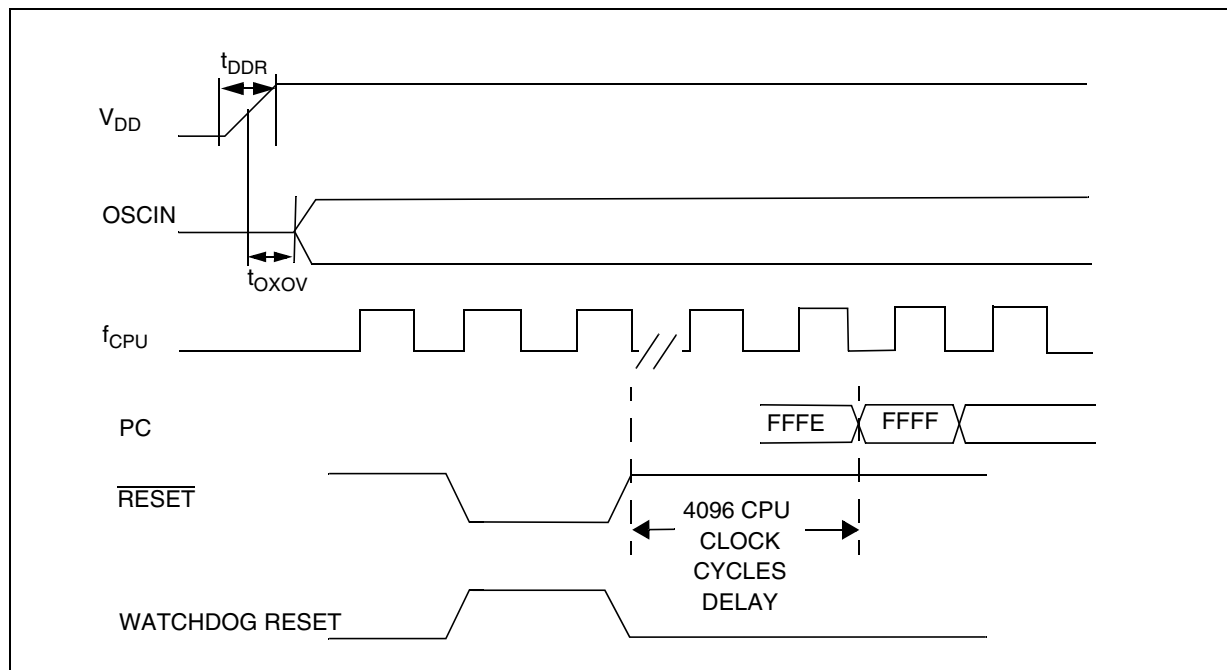
Note: Hysteresis ($V_{IT+} - V_{IT-}$) = V_{hys}

Figure 11. Temporization timing diagram after an internal Reset



RESET (Cont'd)

Figure 12. Reset Timing Diagram



Note: Refer to Electrical Characteristics for values of t_{DDR} , t_{OXOV} , V_{IT+} , V_{IT-} and V_{hys}

6.2 CLOCK SYSTEM

6.2.1 General Description

The MCU accepts either a Crystal or Ceramic resonator, or an external clock signal to drive the internal oscillator. The internal clock (f_{CPU}) is derived from the external oscillator frequency (f_{OSC}), which is divided by 3 (and by 2 or 4 for USB, depending on the external clock used). The internal clock is further divided by 2 by setting the SMS bit in the Miscellaneous Register.

Using the OSC24/12 bit in the option byte, a 12 MHz or a 24 MHz external clock can be used to provide an internal frequency of either 2, 4 or 8 MHz while maintaining a 6 MHz for the USB (refer to Figure 15).

The internal clock signal (f_{CPU}) is also routed to the on-chip peripherals. The CPU clock signal consists of a square wave with a duty cycle of 50%.

The internal oscillator is designed to operate with an AT-cut parallel resonant quartz or ceramic resonator in the frequency range specified for f_{OSC} . The circuit shown in Figure 14 is recommended when using a crystal, and Table 7, "Recommended Values for 24 MHz Crystal Resonator" lists the recommended capacitance. The crystal and associated components should be mounted as close as possible to the input pins in order to minimize output distortion and start-up stabilisation time.

Table 7. Recommended Values for 24 MHz Crystal Resonator

$R_{S_{MAX}}$	20 Ω	25 Ω	70 Ω
C_{OSCIN}	56pF	47pF	22pF
C_{OSCOUT}	56pF	47pF	22pF
R_P	1-10 M Ω	1-10 M Ω	1-10 M Ω

Note: $R_{S_{MAX}}$ is the equivalent serial resistor of the crystal (see crystal specification).

6.2.2 External Clock

An external clock may be applied to the OSCIN input with the OSCOUT pin not connected, as shown on Figure 13. The t_{OXOV} specifications do not apply when using an external clock input. The equivalent specification of the external clock

source should be used instead of t_{OXOV} (see Section 6.5 CONTROL TIMING).

Figure 13. External Clock Source Connections

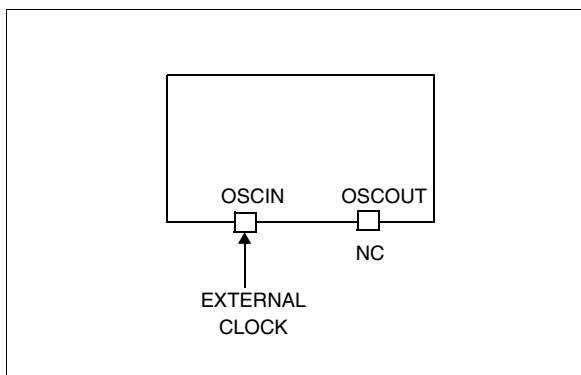


Figure 14. Crystal/Ceramic Resonator

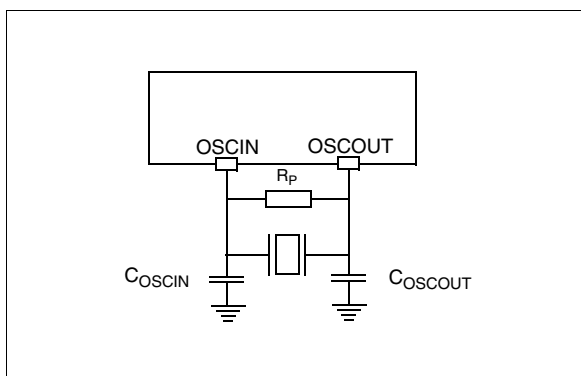
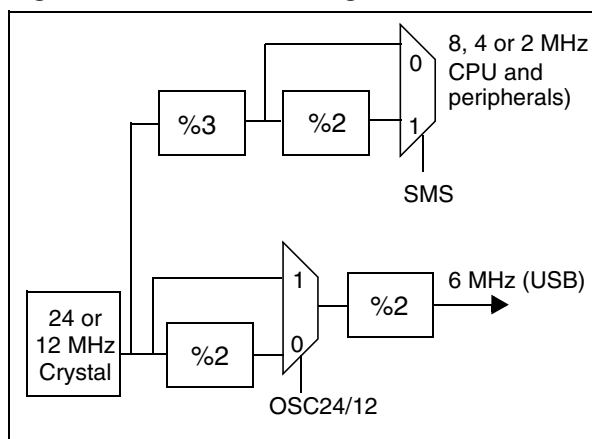


Figure 15. Clock Block Diagram



7 INTERRUPTS

The ST7 core may be interrupted by one of two different methods: maskable hardware interrupts as listed in [Table 8, "Interrupt Mapping"](#) and a non-maskable software interrupt (TRAP). The Interrupt processing flowchart is shown in [Figure 16](#).

The maskable interrupts must be enabled clearing the I bit in order to be serviced. However, disabled interrupts may be latched and processed when they are enabled (see external interrupts subsection).

When an interrupt has to be serviced:

- Normal processing is suspended at the end of the current instruction execution.
- The PC, X, A and CC registers are saved onto the stack.
- The I bit of the CC register is set to prevent additional interrupts.
- The PC is then loaded with the interrupt vector of the interrupt to service and the first instruction of the interrupt service routine is fetched (refer to [Table 8, "Interrupt Mapping"](#) for vector addresses).

The interrupt service routine should finish with the IRET instruction which causes the contents of the saved registers to be recovered from the stack.

Note: As a consequence of the IRET instruction, the I bit will be cleared and the main program will resume.

Priority Management

By default, a servicing interrupt cannot be interrupted because the I bit is set by hardware entering in interrupt routine.

In the case several interrupts are simultaneously pending, a hardware priority defines which one will be serviced first (see [Table 8, "Interrupt Mapping"](#)).

Non-maskable Software Interrupts

This interrupt is entered when the TRAP instruction is executed regardless of the state of the I bit. It will be serviced according to the flowchart on [Figure 16](#).

Interrupts and Low Power Mode

All interrupts allow the processor to leave the Wait low power mode. Only external and specific mentioned interrupts allow the processor to leave the Halt low power mode (refer to the "Exit from HALT" column in [Table 8, "Interrupt Mapping"](#)).

External Interrupts

The pins ITi/PAk and ITj/PBk ($i=1,2$; $j=5,6$; $k=4,5$) can generate an interrupt when a rising edge occurs on this pin. Conversely, the ITl/PAn and ITm/PBn pins ($l=3,4$; $m=7,8$; $n=6,7$) can generate an interrupt when a falling edge occurs on this pin.

Interrupt generation will occur if it is enabled with the ITiE bit ($i=1$ to 8) in the ITRFRE register and if the I bit of the CCR is reset.

Peripheral Interrupts

Different peripheral interrupt flags in the status register are able to cause an interrupt when they are active if both:

- The I bit of the CC register is cleared.
- The corresponding enable bit is set in the control register.

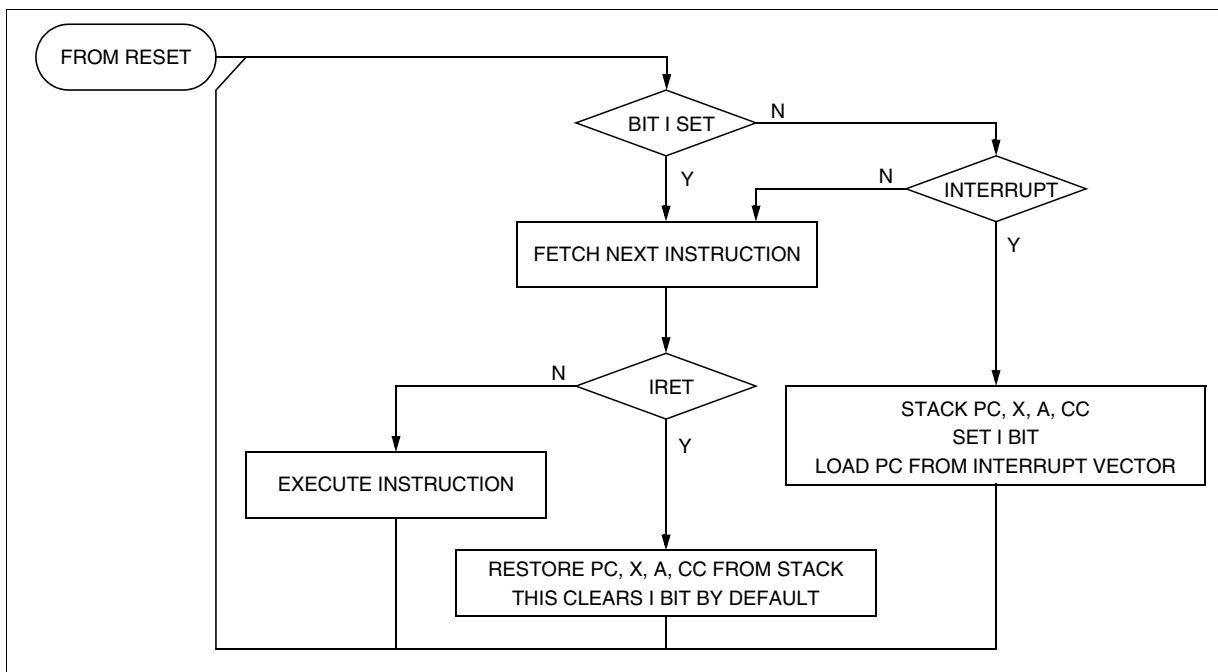
If any of these two conditions is false, the interrupt is latched and thus remains pending.

Clearing an interrupt request is done by one of the two following operations:

- Writing "0" to the corresponding bit in the status register.
- Accessing the status register while the flag is set followed by a read or write of an associated register.

Notes:

1. The clearing sequence resets the internal latch. A pending interrupt (i.e. waiting to be enabled) will therefore be lost if the clear sequence is executed.
2. All interrupts allow the processor to leave the Wait low power mode.
3. Exit from Halt mode may only be triggered by an External Interrupt on one of the ITi ports (PA4-PA7 and PB4-PB7), an end suspend mode Interrupt coming from USB peripheral, or a reset.

INTERRUPTS (Cont'd)**Figure 16. Interrupt Processing Flowchart****Table 8. Interrupt Mapping**

N°	Source Block	Description	Register Label	Priority Order	Exit from HALT	Vector Address
	RESET	Reset	N/A	Highest Priority	yes	FFFEh-FFFFh
	TRAP	Software Interrupt			no	FFFCCh-FFFDh
	FLASH	Flash Start Programming Interrupt		↓	yes	FFFAh-FFFBh
	USB	End Suspend Mode	ISTR		yes	FFF8h-FFF9h
1	ITi	External Interrupts	ITRFRE			FFF6h-FFF7h
2	TIMER	Timer Peripheral Interrupts	TIMSR		no	FFF4h-FFF5h
3	Reserved					FFF2h-FFF3h
4	SCI	SCI Peripheral Interrupts	SCISR			FFF0h-FFF1h
5	USB	USB Peripheral Interrupts	ISTR			FFEEh-FFEFh

INTERRUPTS (Cont'd)**7.1 Interrupt Register****INTERRUPTS REGISTER (ITRFRE)**

Address: 0008h — Read/Write

Reset Value: 0000 0000 (00h)

7								0
IT8E	IT7E	IT6E	IT5E	IT4E	IT3E	IT2E	IT1E	

Bit 7:0 = **ITiE (i=1 to 8)**. *Interrupt Enable Control Bits.*

If an ITiE bit is set, the corresponding interrupt is generated when

– a rising edge occurs on the pin PA4/IT1 or PA5/IT2 or PB4/IT5 or PB5/IT6

or

– a falling edge occurs on the pin PA6/IT3 or PA7/IT4 or PB6/IT7 or PB7/IT8

No interrupt is generated elsewhere.

8 POWER SAVING MODES

8.1 Introduction

To give a large measure of flexibility to the application in terms of power consumption, two main power saving modes are implemented in the ST7.

After a RESET, the normal operating mode is selected by default (RUN mode). This mode drives the device (CPU and embedded peripherals) by means of a master clock which is based on the main oscillator frequency divided by 3 (f_{CPU}).

From Run mode, the different power saving modes may be selected by setting the relevant register bits or by calling the specific ST7 software instruction whose action depends on the oscillator status.

8.2 HALT Mode

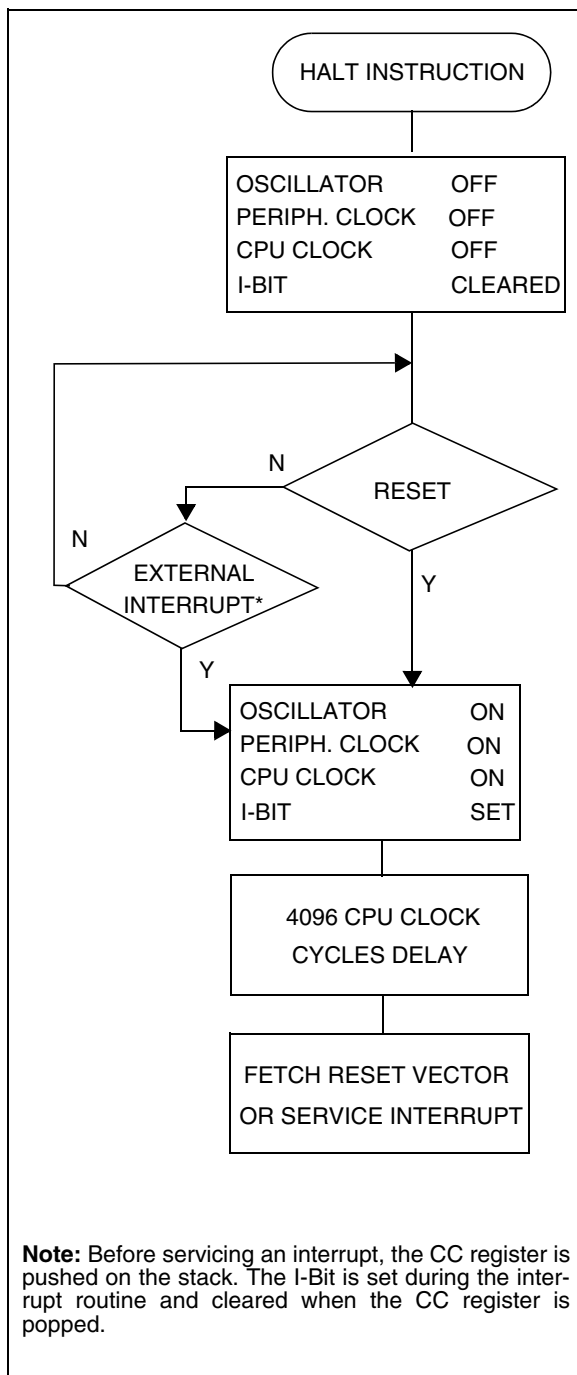
The MCU consumes the least amount of power in HALT mode. The HALT mode is entered by executing the HALT instruction. The internal oscillator is then turned off, causing all internal processing to be stopped, including the operation of the on-chip peripherals.

When entering HALT mode, the I bit in the Condition Code Register is cleared. Thus, all external interrupts (ITi or USB end suspend mode) are allowed and if an interrupt occurs, the CPU clock becomes active.

The MCU can exit HALT mode on reception of either an external interrupt on ITi, an end suspend mode interrupt coming from USB peripheral, or a reset. The oscillator is then turned on and a stabilization time is provided before releasing CPU operation. The stabilization time is 4096 CPU clock cycles.

After the start up delay, the CPU continues operation by servicing the interrupt which wakes it up or by fetching the reset vector if a reset wakes it up.

Figure 17. HALT Mode Flow Chart



POWER SAVING MODES (Cont'd)

8.3 SLOW Mode

In Slow mode, the oscillator frequency can be divided by 2 as selected by the SMS bit in the Miscellaneous Register. The CPU and peripherals are clocked at this lower frequency. Slow mode is used to reduce power consumption, and enables the user to adapt the clock frequency to the available supply voltage.

8.4 WAIT Mode

WAIT mode places the MCU in a low power consumption mode by stopping the CPU.

This power saving mode is selected by calling the "WFI" ST7 software instruction.

All peripherals remain active. During WAIT mode, the I bit of the CC register is forced to 0 to enable all interrupts. All other registers and memory remain unchanged. The MCU remains in WAIT mode until an interrupt or Reset occurs, whereupon the Program Counter branches to the starting address of the interrupt or Reset service routine. The MCU will remain in WAIT mode until a Reset or an Interrupt occurs, causing it to wake up.

Refer to [Figure 18](#).

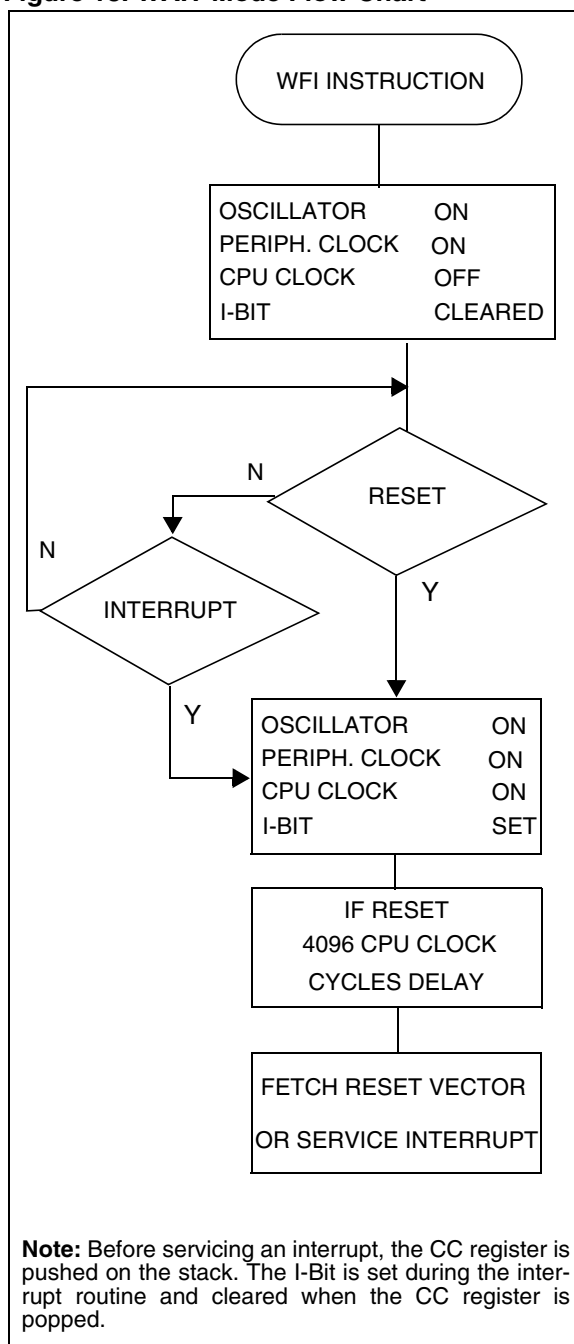
Related Documentation

AN 980: ST7 Keypad Decoding Techniques, Implementing Wake-Up on Keystroke

AN1014: How to Minimize the ST7 Power Consumption

AN1605: Using an active RC to wakeup the ST7LITE0 from power saving mode

Figure 18. WAIT Mode Flow Chart



9 I/O PORTS

9.1 Introduction

The I/O ports offer different functional modes:

- Transfer of data through digital inputs and outputs and for specific pins
- Alternate signal input/output for the on-chip peripherals
- External interrupt generation

An I/O port consists of up to 8 pins. Each pin can be programmed independently as a digital input (with or without interrupt generation) or a digital output.

9.2 Functional description

Each port is associated to 2 main registers:

- Data Register (DR)
- Data Direction Register (DDR)

Each I/O pin may be programmed using the corresponding register bits in DDR register: bit X corresponding to pin X of the port. The same correspondence is used for the DR register.

Table 9. I/O Pin Functions

DDR	MODE
0	Input
1	Output

Input Modes

The input configuration is selected by clearing the corresponding DDR register bit.

In this case, reading the DR register returns the digital value applied to the external I/O pin.

Note 1: All the inputs are triggered by a Schmitt trigger.

Note 2: When switching from input mode to output mode, the DR register should be written first to output the correct value as soon as the port is configured as an output.

Interrupt function

When an I/O is configured as an Input with Interrupt, an event on this I/O can generate an external Interrupt request to the CPU. The interrupt sensitivity is given independently according to the de-

scription mentioned in the ITRFRE interrupt register.

Each pin can independently generate an Interrupt request.

Each external interrupt vector is linked to a dedicated group of I/O port pins (see Interrupts section). If more than one input pin is selected simultaneously as an interrupt source, this is logically ORed. For this reason if one of the interrupt pins is tied low, the other ones are masked.

Output Mode

The pin is configured in output mode by setting the corresponding DDR register bit (see Table 7).

In this mode, writing “0” or “1” to the DR register applies this digital value to the I/O pin through the latch. Therefore, the previously saved value is restored when the DR register is read.

Note: The interrupt function is disabled in this mode.

Digital Alternate Function

When an on-chip peripheral is configured to use a pin, the alternate function is automatically selected. This alternate function takes priority over standard I/O programming. When the signal is coming from an on-chip peripheral, the I/O pin is automatically configured in output mode (push-pull or open drain according to the peripheral).

When the signal is going to an on-chip peripheral, the I/O pin has to be configured in input mode. In this case, the pin's state is also digitally readable by addressing the DR register.

Notes:

1. Input pull-up configuration can cause an unexpected value at the input of the alternate peripheral input.
2. When the on-chip peripheral uses a pin as input and output, this pin must be configured as an input (DDR = 0).

Warning: The alternate function must not be activated as long as the pin is configured as an input with interrupt in order to avoid generating spurious interrupts.

I/O PORTS (Cont'd)

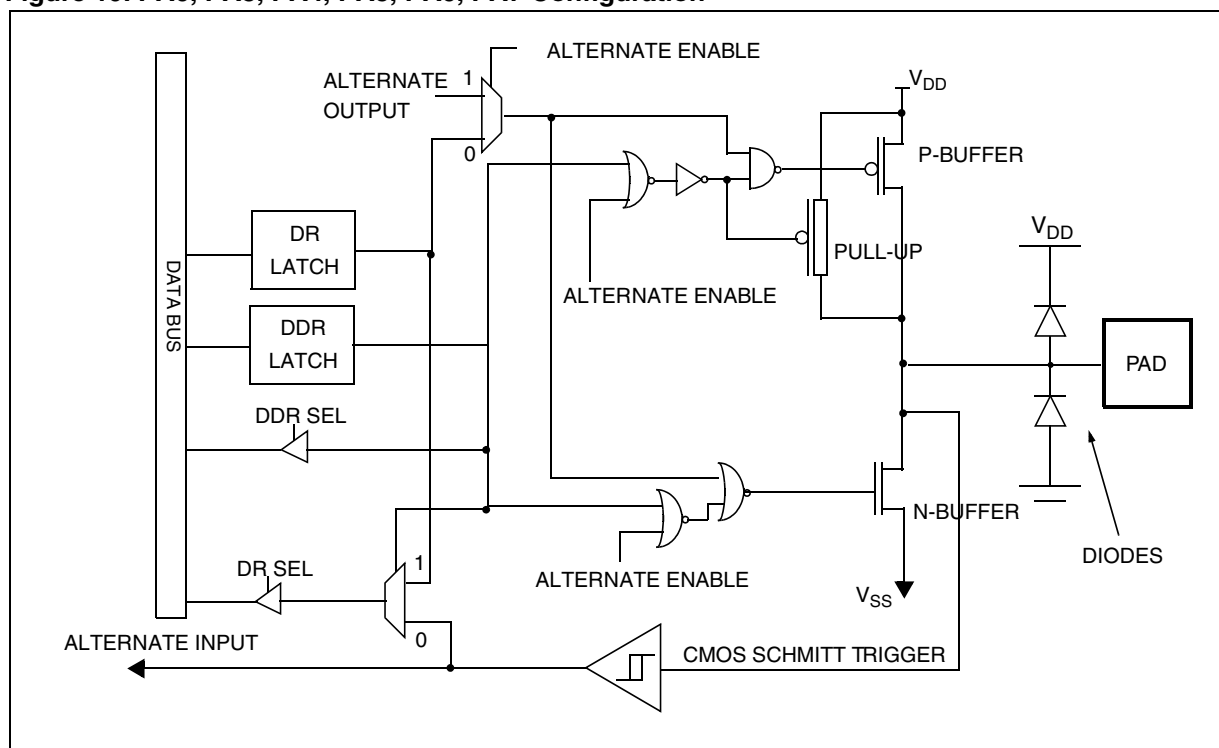
9.2.1 Port A

Table 10. Port A0, A3, A4, A5, A6, A7 Description

PORT A	I / O		Alternate Function	
	Input ¹	Output	Signal	Condition
PA0	with pull-up	push-pull	MCO (Main Clock Output)	MCO = 1 (MISCR)
PA3	with pull-up	push-pull	Timer EXTCLK	CC1 = 1 CC0 = 1 (Timer CR2)
PA4	with pull-up	push-pull	Timer ICAP1	
			IT1 Schmitt triggered input	IT1E = 1 (ITIFRE)
PA5	with pull-up	push-pull	Timer ICAP2	
			IT2 Schmitt triggered input	IT2E = 1 (ITIFRE)
PA6 ²	with pull-up	push-pull	Timer OCMP1	OC1E = 1
			IT3 Schmitt triggered input	IT3E = 1 (ITIFRE)
PA7	with pull-up	push-pull	Timer OCMP2	OC2E = 1
			IT4 Schmitt triggered input	IT4E = 1 (ITIFRE)

¹Reset State²Not available on SO24

Figure 19. PA0, PA3, PA4, PA5, PA6, PA7 Configuration



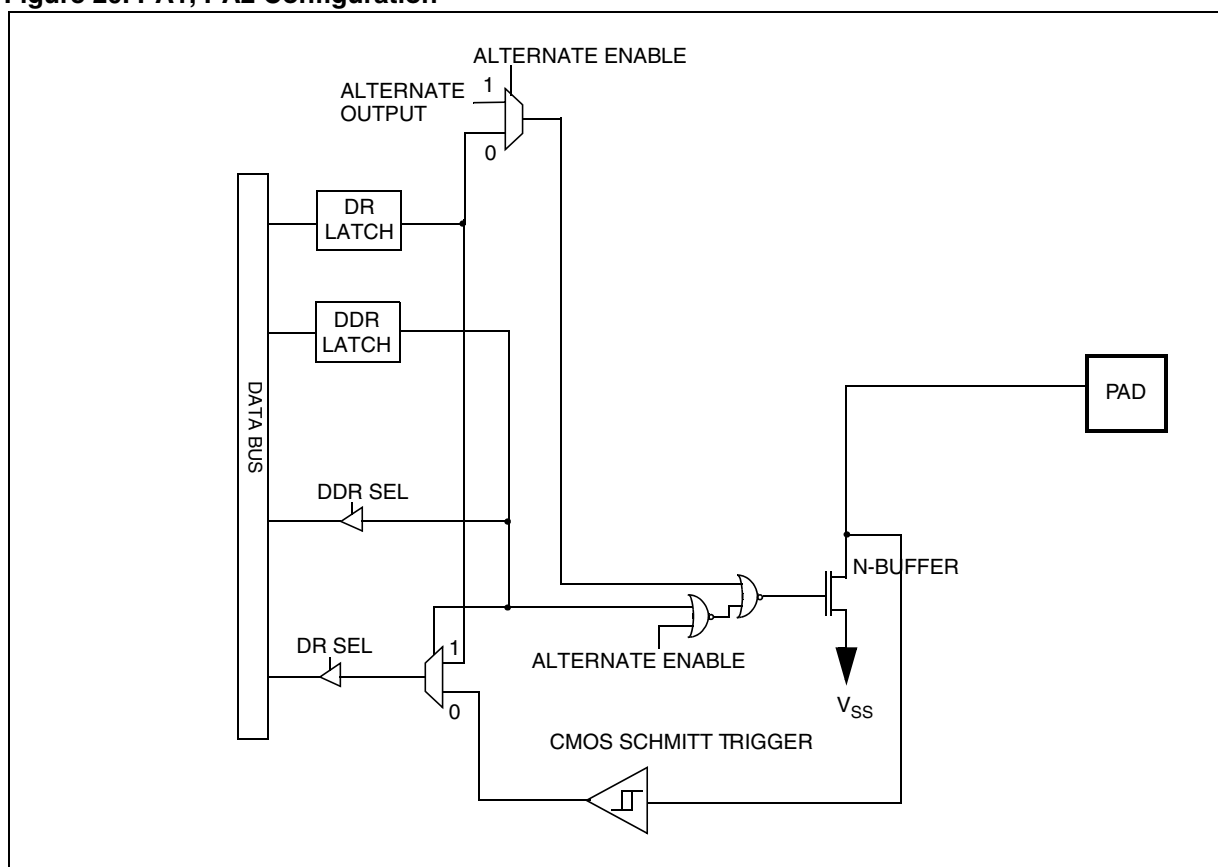
I/O PORTS (Cont'd)

Table 11. PA1, PA2 Description

PORT A	I / O		Alternate Function	
	Input ¹	Output	Signal	Condition
PA1	without pull-up	Very High Current open drain		
PA2	without pull-up	Very High Current open drain		

¹Reset State

Figure 20. PA1, PA2 Configuration



I/O PORTS (Cont'd)

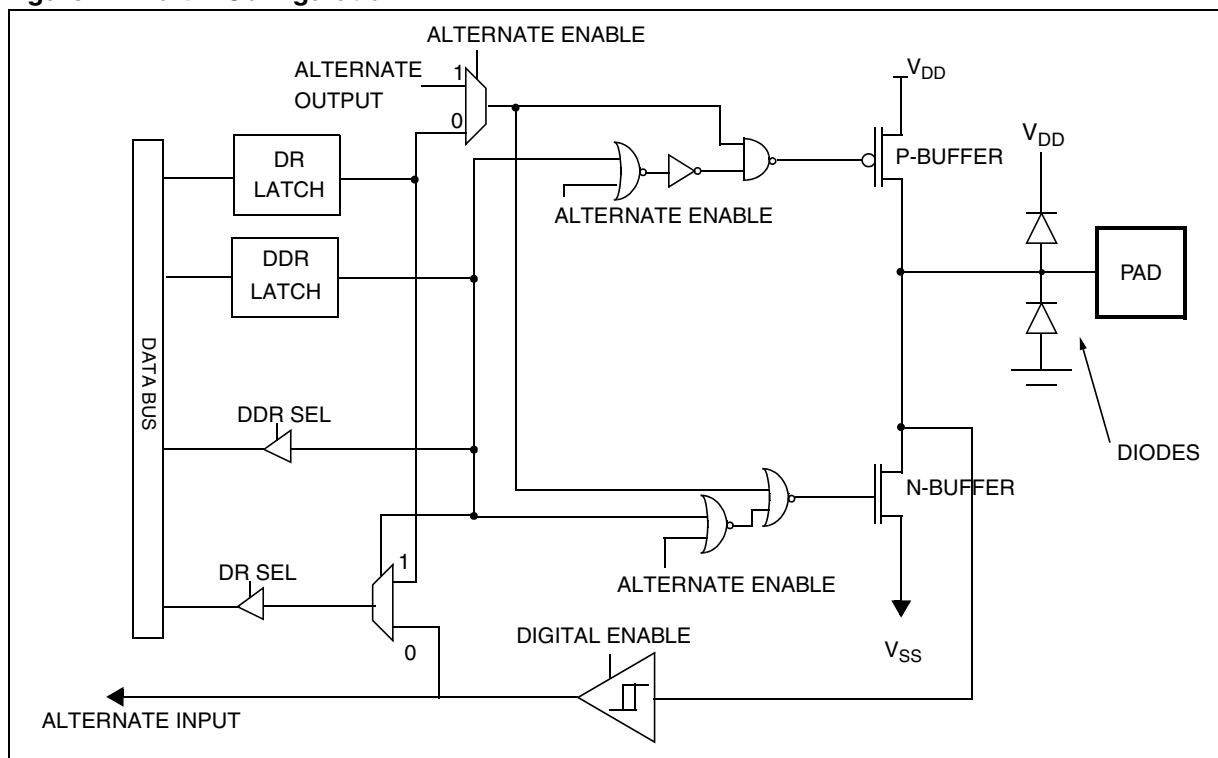
9.2.2 Port B

Table 12. Port B Description

PORT B	I/O		Alternate Function	
	Input ¹	Output	Signal	Condition
PB0	without pull-up	push-pull		
PB1	without pull-up	push-pull		
			USBOE (USB output enable) ²	USBOE = 1 (MISCR)
PB2	without pull-up	push-pull		
PB3	without pull-up	push-pull		
PB4	without pull-up	push-pull		
			IT5 Schmitt triggered input	IT4E = 1 (ITIFRE)
PB5	without pull-up	push-pull		
			IT6 Schmitt triggered input	IT5E = 1 (ITIFRE)
PB6	without pull-up	push-pull		
			IT7 Schmitt triggered input	IT6E = 1 (ITIFRE)
PB7	without pull-up	push-pull		
			IT8 Schmitt triggered input	IT7E = 1 (ITIFRE)

¹Reset State²On SO24 only

Figure 21. Port B Configuration



I/O PORTS (Cont'd)

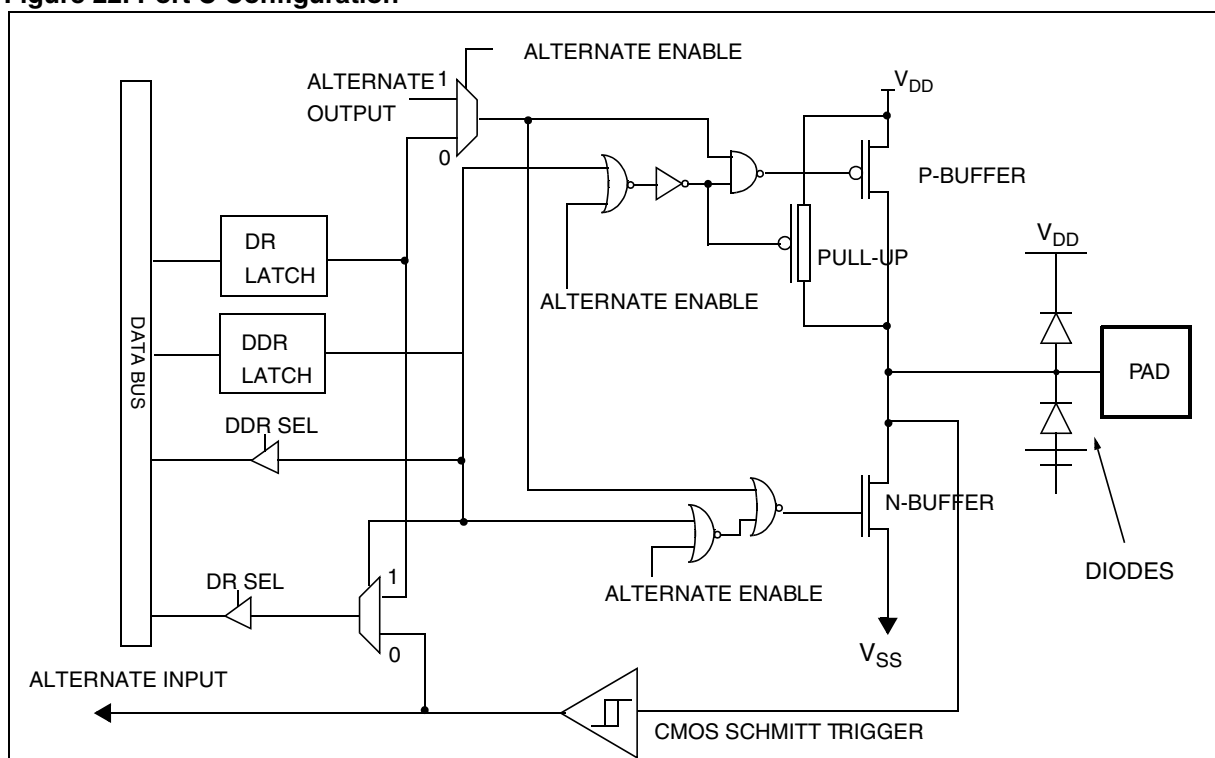
9.2.3 Port C

Table 13. Port C Description

PORT C	I / O		Alternate Function	
	Input ¹	Output	Signal	Condition
PC0	with pull-up	push-pull	RDI (SCI input)	
PC1	with pull-up	push-pull	TDO (SCI output)	SCI enable
PC2 ²	with pull-up	push-pull	USBOE (USB output enable)	USBOE = 1 (MISCR)

¹Reset State²Not available on SO24

Figure 22. Port C Configuration



I/O PORTS (Cont'd)**9.2.4 Register Description****DATA REGISTERS (PxDR)**

Port A Data Register (PADR): 0000h

Port B Data Register (PBDR): 0002h

Port C Data Register (PCDR): 0004h

Read/Write

Reset Value Port A: 0000 0000 (00h)

Reset Value Port B: 0000 0000 (00h)

Reset Value Port C: 1111 x000 (FXh)

Note: For Port C, unused bits (7-3) are not accessible.

7							0
D7	D6	D5	D4	D3	D2	D1	D0

Bit 7:0 = D[7:0] Data Register 8 bits.

The DR register has a specific behaviour according to the selected input/output configuration. Writing the DR register is always taken into account even if the pin is configured as an input. Reading the DR register returns either the DR register latch content (pin configured as output) or the digital value applied to the I/O pin (pin configured as input).

Note: When using open-drain I/Os in output configuration, the value read in DR is the digital value applied to the I/O pin.

DATA DIRECTION REGISTER (PxDDR)

Port A Data Direction Register (PADDDR): 0001h

Port B Data Direction Register (PBDDR): 0003h

Port C Data Direction Register (PCDDR): 0005h

Read/Write

Reset Value Port A: 0000 0000 (00h)

Reset Value Port B: 0000 0000 (00h)

Reset Value Port C: 1111 x000 (FXh)

Note: For Port C, unused bits (7-3) are not accessible

7							0
DD7	DD6	DD5	DD4	DD3	DD2	DD1	DD0

Bit 7:0 = DD[7:0] Data Direction Register 8 bits.

The DDR register gives the input/output direction configuration of the pins. Each bit is set and cleared by software.

0: Input mode

1: Output mode

Table 14. I/O Ports Register Map

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
00	PADR	MSB							LSB
01	PADDR	MSB							LSB
02	PBDR	MSB							LSB
03	PBDDR	MSB							LSB
04	PCDR	MSB							LSB
05	PCDDR	MSB							LSB
06	Reserved								
07	Reserved								

Related Documentation

AN 970: SPI Communication between ST7 and EEPROM

AN1048: Software LCD driver

10 MISCELLANEOUS REGISTER

Address: 0009h — Read/Write
Reset Value: 0000 0000 (00h)

7							0
-	-	-	-	-	SMS	USBOE	MCO

Bit 7:3 = Reserved

Bit 2 = **SMS** *Slow Mode Select*.

This bit is set by software and only cleared by hardware after a reset. If this bit is set, it enables the use of an internal divide-by-2 clock divider (refer to [Figure 15 on page 22](#)). The SMS bit has no effect on the USB frequency.

0: Divide-by-2 disabled and CPU clock frequency is standard

1: Divide-by-2 enabled and CPU clock frequency is halved.

Bit 1 = **USBOE** *USB enable*.

If this bit is set, the port PC2 (PB1 on SO24) outputs the USB output enable signal (at “1” when the ST7 USB is transmitting data).

Unused bits 7-4 are set.

Bit 0 = **MCO** *Main Clock Out selection*

This bit enables the MCO alternate function on the PA0 I/O port. It is set and cleared by software.

0: MCO alternate function disabled (I/O pin free for general-purpose I/O)

1: MCO alternate function enabled (f_{CPU} on I/O port)

11 ON-CHIP PERIPHERALS

11.1 WATCHDOG TIMER (WDG)

11.1.1 Introduction

The Watchdog timer is used to detect the occurrence of a software fault, usually generated by external interference or by unforeseen logical conditions, which causes the application program to abandon its normal sequence. The Watchdog circuit generates an MCU reset on expiry of a programmed time period, unless the program refreshes the counter's contents before the T6 bit becomes cleared.

11.1.2 Main Features

- Programmable free-running counter (64 increments of 49,152 CPU cycles)
- Programmable reset
- Reset (if watchdog activated) when the T6 bit reaches zero
- Optional reset on HALT instruction (configurable by option byte)
- Hardware Watchdog selectable by option byte.

11.1.3 Functional Description

The counter value stored in the CR register (bits T6:T0), is decremented every 49,152 machine cy-

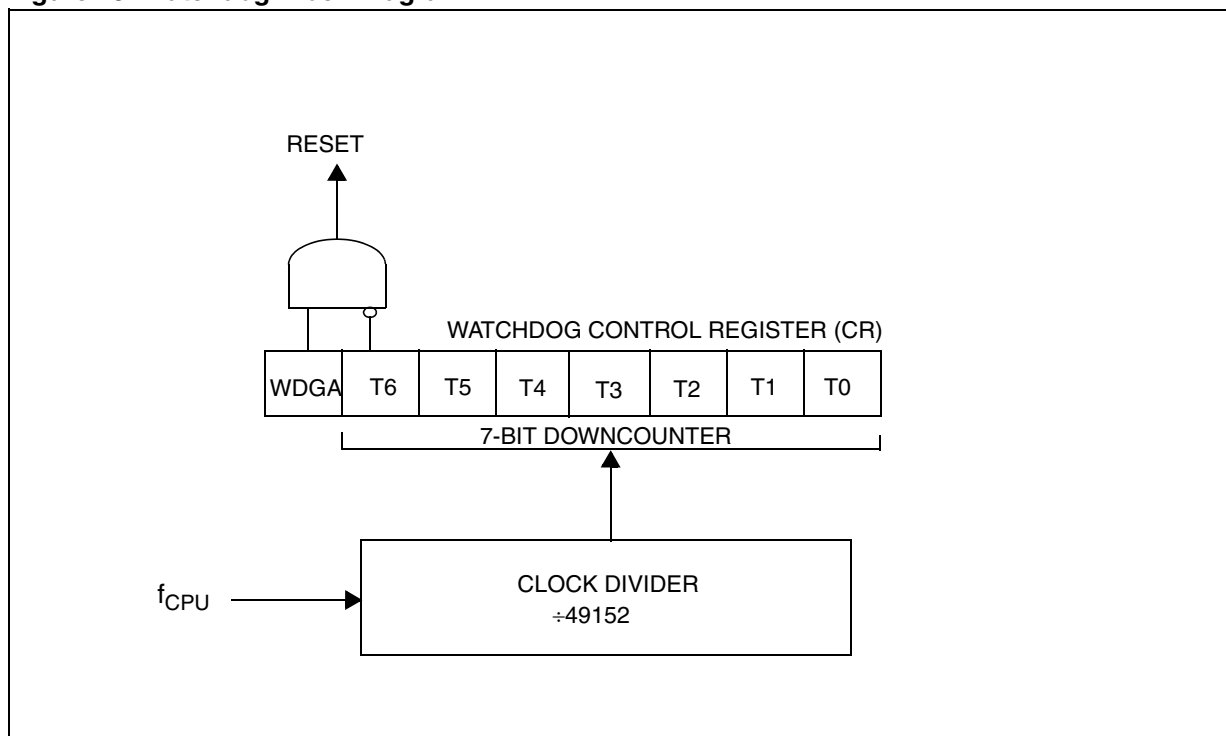
cles, and the length of the timeout period can be programmed by the user in 64 increments.

If the watchdog is activated (the WDGA bit is set) and when the 7-bit timer (bits T6:T0) rolls over from 40h to 3Fh (T6 becomes cleared), it initiates a reset cycle pulling low the reset pin for typically 30µs.

The application program must write in the CR register at regular intervals during normal operation to prevent an MCU reset. This downcounter is free-running: it counts down even if the watchdog is disabled. The value to be stored in the CR register must be between FFh and C0h (see [Table 15, "Watchdog Timing \(fCPU = 8 MHz\)"](#)):

- The WDGA bit is set (watchdog enabled)
- The T6 bit is set to prevent generating an immediate reset
- The T5:T0 bits contain the number of increments which represents the time delay before the watchdog produces a reset.

Figure 23. Watchdog Block Diagram



WATCHDOG TIMER (Cont'd)

Table 15. Watchdog Timing ($f_{CPU} = 8\text{ MHz}$)

	CR Register initial value	WDG timeout period (ms)
Max	FFh	393.216
Min	C0h	6.144

Notes: Following a reset, the watchdog is disabled. Once activated it cannot be disabled, except by a reset.

The T6 bit can be used to generate a software reset (the WDGA bit is set and the T6 bit is cleared).

11.1.4 Software Watchdog Option

If Software Watchdog is selected by option byte, the watchdog is disabled following a reset. Once activated it cannot be disabled, except by a reset.

The T6 bit can be used to generate a software reset (the WDGA bit is set and the T6 bit is cleared).

11.1.5 Hardware Watchdog Option

If Hardware Watchdog is selected by option byte, the watchdog is always active and the WDGA bit in the CR is not used.

11.1.6 Low Power Modes**WAIT Instruction**

No effect on Watchdog.

HALT Instruction

If the Watchdog reset on HALT option is selected by option byte, a HALT instruction causes an immediate reset generation if the Watchdog is activated (WDGA bit is set).

11.1.6.1 Using Halt Mode with the WDG (option)

If the Watchdog reset on HALT option is not selected by option byte, the Halt mode can be used when the watchdog is enabled.

In this case, the HALT instruction stops the oscillator. When the oscillator is stopped, the WDG stops counting and is no longer able to generate a reset until the microcontroller receives an external interrupt or a reset.

If an external interrupt is received, the WDG restarts counting after 4096 CPU clocks. If a reset is generated, the WDG is disabled (reset state).

Recommendations

- Make sure that an external event is available to wake up the microcontroller from Halt mode.
- Before executing the HALT instruction, refresh the WDG counter, to avoid an unexpected WDG reset immediately after waking up the microcontroller.
- When using an external interrupt to wake up the microcontroller, reinitialize the corresponding I/O as “Input Pull-up with Interrupt” before executing the HALT instruction. The main reason for this is that the I/O may be wrongly configured due to external interference or by an unforeseen logical condition.
- For the same reason, reinitialize the level sensitivity of each external interrupt as a precautionary measure.
- The opcode for the HALT instruction is 0x8E. To avoid an unexpected HALT instruction due to a program counter failure, it is advised to clear all occurrences of the data value 0x8E from memory. For example, avoid defining a constant in ROM with the value 0x8E.
- As the HALT instruction clears the I bit in the CC register to allow interrupts, the user may choose to clear all pending interrupt bits before executing the HALT instruction. This avoids entering other peripheral interrupt routines after executing the external interrupt routine corresponding to the wake-up event (reset or external interrupt).

11.1.7 Interrupts

None.

WATCHDOG TIMER (Cont'd)

11.1.8 Register Description

CONTROL REGISTER (CR)

Read/Write

Reset Value: 0111 1111 (7Fh)

7							0
WDGA	T6	T5	T4	T3	T2	T1	T0

Bit 7 = **WDGA** *Activation bit.*
This bit is set by software and only cleared by

hardware after a reset. When WDGA = 1, the watchdog can generate a reset.
0: Watchdog disabled
1: Watchdog enabled

Bit 6:0 = **T[6:0]** *7-bit timer (MSB to LSB).*
These bits contain the decremented value. A reset is produced when it rolls over from 40h to 3Fh (T6 becomes cleared).

Table 16. Watchdog Timer Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0Ch	WDGCR Reset Value	WDGA 0	T6 1	T5 1	T4 1	T3 1	T2 1	T1 1	T0 1

11.2 16-BIT TIMER

11.2.1 Introduction

The timer consists of a 16-bit free-running counter driven by a programmable prescaler.

It may be used for a variety of purposes, including pulse length measurement of up to two input signals (*input capture*) or generation of up to two output waveforms (*output compare* and *PWM*).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the CPU clock prescaler.

Some ST7 devices have two on-chip 16-bit timers. They are completely independent, and do not share any resources. They are synchronized after a MCU reset as long as the timer clock frequencies are not modified.

This description covers one or two 16-bit timers. In ST7 devices with two timers, register names are prefixed with TA (Timer A) or TB (Timer B).

11.2.2 Main Features

- Programmable prescaler: f_{CPU} divided by 2, 4 or 8
- Overflow status flag and maskable interrupt
- External clock input (must be at least four times slower than the CPU clock speed) with the choice of active edge
- 1 or 2 Output Compare functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated programmable signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- 1 or 2 Input Capture functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated active edge selection signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- Pulse width modulation mode (PWM)
- One Pulse mode
- Reduced Power Mode
- 5 alternate functions on I/O ports (ICAP1, ICAP2, OCMP1, OCMP2, EXTCLK)*

The Block Diagram is shown in [Figure 24](#).

***Note:** Some timer pins may not be available (not bonded) in some ST7 devices. Refer to the device pin out description.

When reading an input signal on a non-bonded pin, the value will always be '1'.

11.2.3 Functional Description

11.2.3.1 Counter

The main block of the Programmable Timer is a 16-bit free running upcounter and its associated 16-bit registers. The 16-bit registers are made up of two 8-bit registers called high and low.

Counter Register (CR):

- Counter High Register (CHR) is the most significant byte (MS Byte).
- Counter Low Register (CLR) is the least significant byte (LS Byte).

Alternate Counter Register (ACR)

- Alternate Counter High Register (ACHR) is the most significant byte (MS Byte).
- Alternate Counter Low Register (ACLR) is the least significant byte (LS Byte).

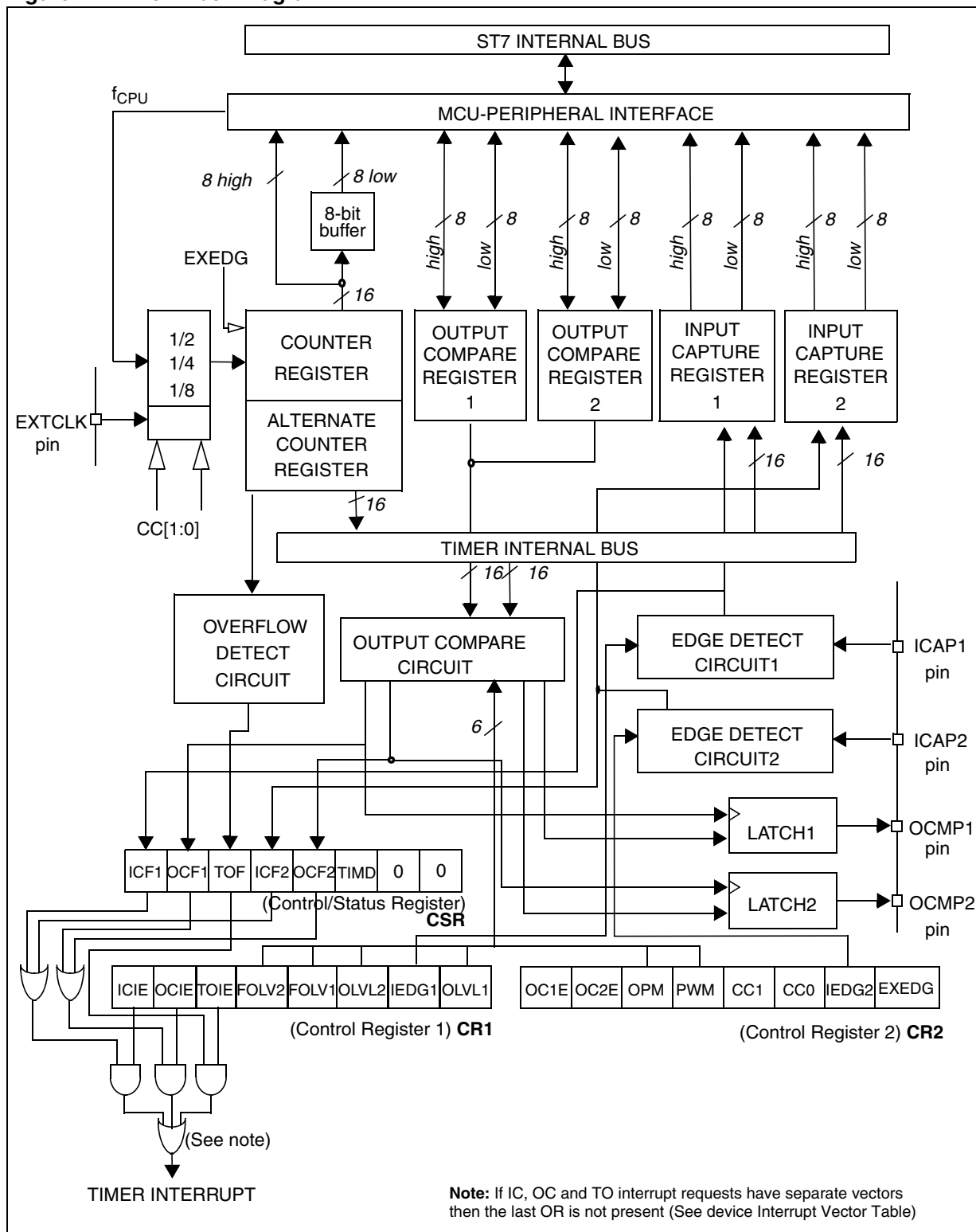
These two read-only 16-bit registers contain the same value but with the difference that reading the ACLR register does not clear the TOF bit (Timer overflow flag), located in the Status register, (SR), (see note at the end of paragraph titled 16-bit read sequence).

Writing in the CLR register or ACLR register resets the free running counter to the FFFCh value. Both counters have a reset value of FFFCh (this is the only value which is reloaded in the 16-bit timer). The reset value of both counters is also FFFCh in One Pulse mode and PWM mode.

The timer clock depends on the clock control bits of the CR2 register, as illustrated in [Table 17, "Clock Control Bits"](#). The value in the counter register repeats every 131072, 262144 or 524288 CPU clock cycles depending on the CC[1:0] bits. The timer frequency can be $f_{CPU}/2$, $f_{CPU}/4$, $f_{CPU}/8$ or an external frequency.

16-BIT TIMER (Cont'd)

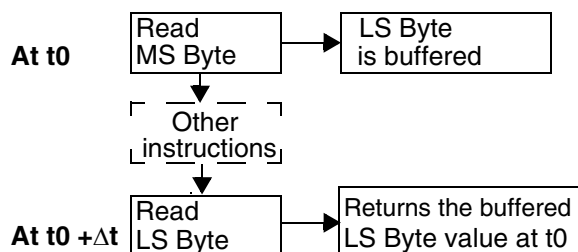
Figure 24. Timer Block Diagram



16-BIT TIMER (Cont'd)

16-bit read sequence: (from either the Counter Register or the Alternate Counter Register).

Beginning of the sequence



Sequence completed

The user must read the MS Byte first, then the LS Byte value is buffered automatically.

This buffered value remains unchanged until the 16-bit read sequence is completed, even if the user reads the MS Byte several times.

After a complete reading sequence, if only the CLR register or ACLR register are read, they return the LS Byte of the count value at the time of the read.

Whatever the timer mode used (input capture, output compare, One Pulse mode or PWM mode) an overflow occurs when the counter rolls over from FFFFh to 0000h then:

- The TOF bit of the SR register is set.
- A timer interrupt is generated if:
 - TOIE bit of the CR1 register is set and
 - I bit of the CC register is cleared.

If one of these conditions is false, the interrupt remains pending to be issued as soon as they are both true.

Clearing the overflow interrupt request is done in two steps:

1. Reading the SR register while the TOF bit is set.
2. An access (read or write) to the CLR register.

Notes: The TOF bit is not cleared by accesses to ACLR register. The advantage of accessing the ACLR register rather than the CLR register is that it allows simultaneous use of the overflow function and reading the free running counter at random times (for example, to measure elapsed time) without the risk of clearing the TOF bit erroneously.

The timer is not affected by WAIT mode.

In HALT mode, the counter stops counting until the mode is exited. Counting then resumes from the previous count (MCU awakened by an interrupt) or from the reset count (MCU awakened by a Reset).

11.2.3.2 External Clock

The external clock (where available) is selected if CC0 = 1 and CC1 = 1 in the CR2 register.

The status of the EXEDG bit in the CR2 register determines the type of level transition on the external clock pin EXTCLK that will trigger the free running counter.

The counter is synchronized with the falling edge of the internal CPU clock.

A minimum of four falling edges of the CPU clock must occur between two consecutive active edges of the external clock; thus the external clock frequency must be less than a quarter of the CPU clock frequency.

16-BIT TIMER (Cont'd)

Figure 25. Counter Timing Diagram, Internal Clock Divided by 2

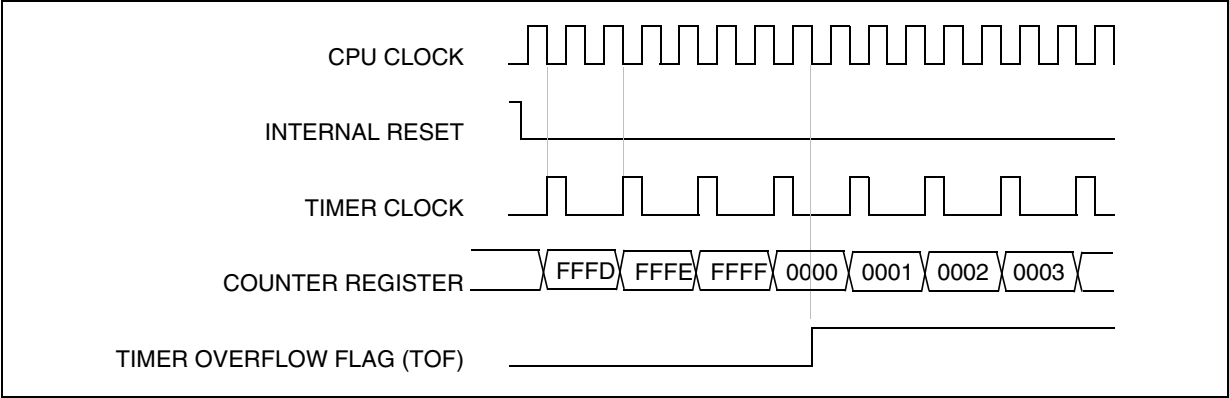


Figure 26. Counter Timing Diagram, Internal Clock Divided by 4

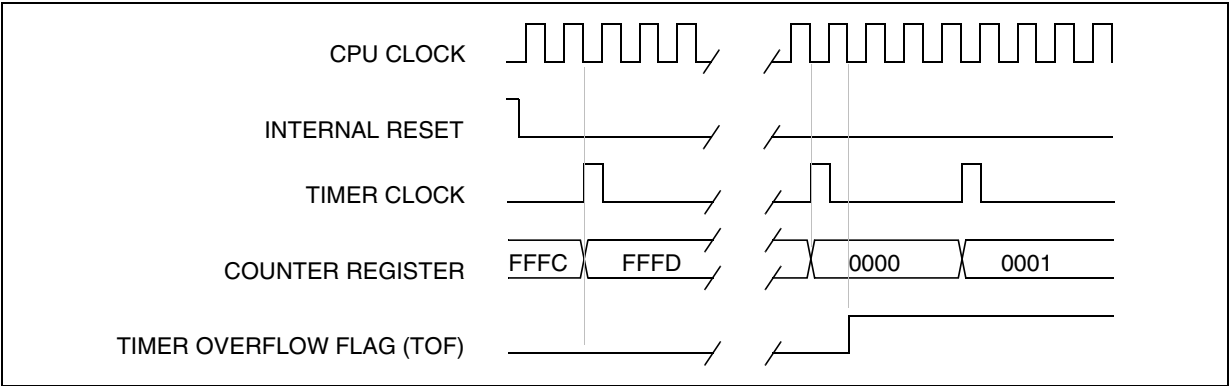
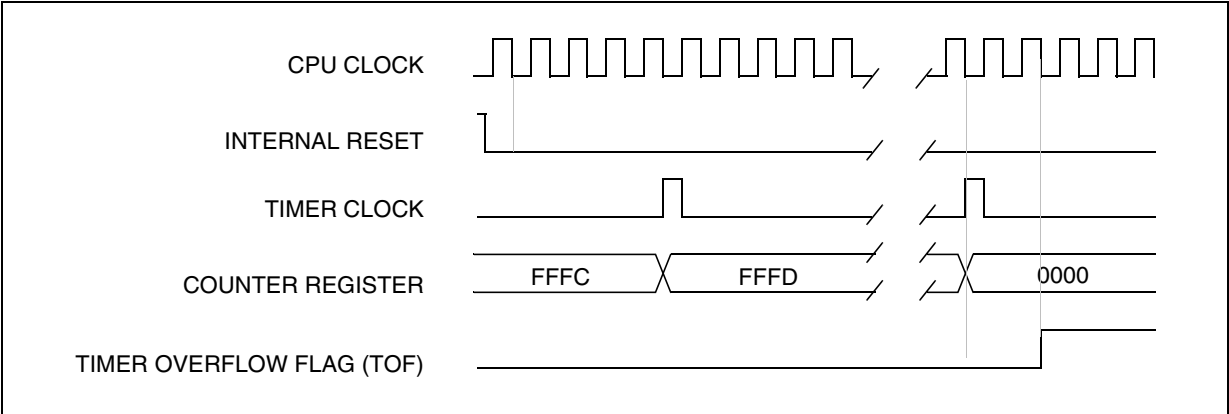


Figure 27. Counter Timing Diagram, Internal Clock Divided By 8



Note: The MCU is in reset state when the internal reset signal is high, when it is low the MCU is running.

16-BIT TIMER (Cont'd)

11.2.3.3 Input Capture

In this section, the index, i , may be 1 or 2 because there are two input capture functions in the 16-bit timer.

The two 16-bit input capture registers (IC1R and IC2R) are used to latch the value of the free running counter after a transition is detected on the ICAP i pin (see [Figure 28](#)).

	MS Byte	LS Byte
ICiR	ICiHR	ICiLR

IC/R register is a read-only register.

The active transition is software programmable through the IEDG i bit of Control Registers (CR i).

Timing resolution is one count of the free running counter: ($f_{CPU}/CC[1:0]$).

Procedure:

To use the input capture function select the following in the CR2 register:

- Select the timer clock (CC[1:0]) (see [Table 17](#), "Clock Control Bits").
- Select the edge of the active transition on the ICAP2 pin with the IEDG2 bit (the ICAP2 pin must be configured as floating input or input with pull-up without interrupt if this configuration is available).

And select the following in the CR1 register:

- Set the ICIE bit to generate an interrupt after an input capture coming from either the ICAP1 pin or the ICAP2 pin
- Select the edge of the active transition on the ICAP1 pin with the IEDG1 bit (the ICAP1 pin must be configured as floating input or input with pull-up without interrupt if this configuration is available).

When an input capture occurs:

- ICF i bit is set.
- The IC/R register contains the value of the free running counter on the active transition on the ICAP i pin (see [Figure 29](#)).
- A timer interrupt is generated if the ICIE bit is set and the I bit is cleared in the CC register. Otherwise, the interrupt remains pending until both conditions become true.

Clearing the Input Capture interrupt request (that is, clearing the ICF i bit) is done in two steps:

1. Reading the SR register while the ICF i bit is set.
2. An access (read or write) to the ICiLR register.

Notes:

1. After reading the ICiHR register, transfer of input capture data is inhibited and ICF i will never be set until the ICiLR register is also read.
2. The IC/R register contains the free running counter value which corresponds to the most recent input capture.
3. The two input capture functions can be used together even if the timer also uses the two output compare functions.
4. In One Pulse mode and PWM mode only Input Capture 2 can be used.
5. The alternate inputs (ICAP1 and ICAP2) are always directly connected to the timer. So any transitions on these pins activates the input capture function.
Moreover if one of the ICAP i pins is configured as an input and the second one as an output, an interrupt can be generated if the user toggles the output pin and if the ICIE bit is set. This can be avoided if the input capture function i is disabled by reading the ICiHR (see note 1).
6. The TOF bit can be used with interrupt generation in order to measure events that go beyond the timer range (FFFFh).

16-BIT TIMER (Cont'd)

Figure 28. Input Capture Block Diagram

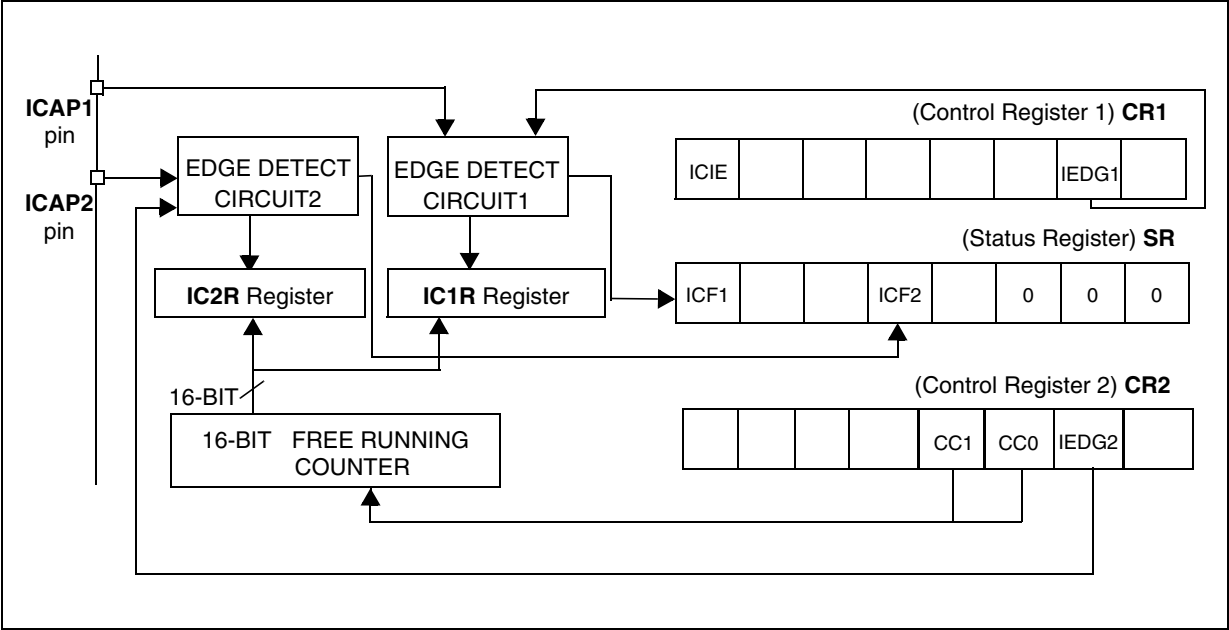
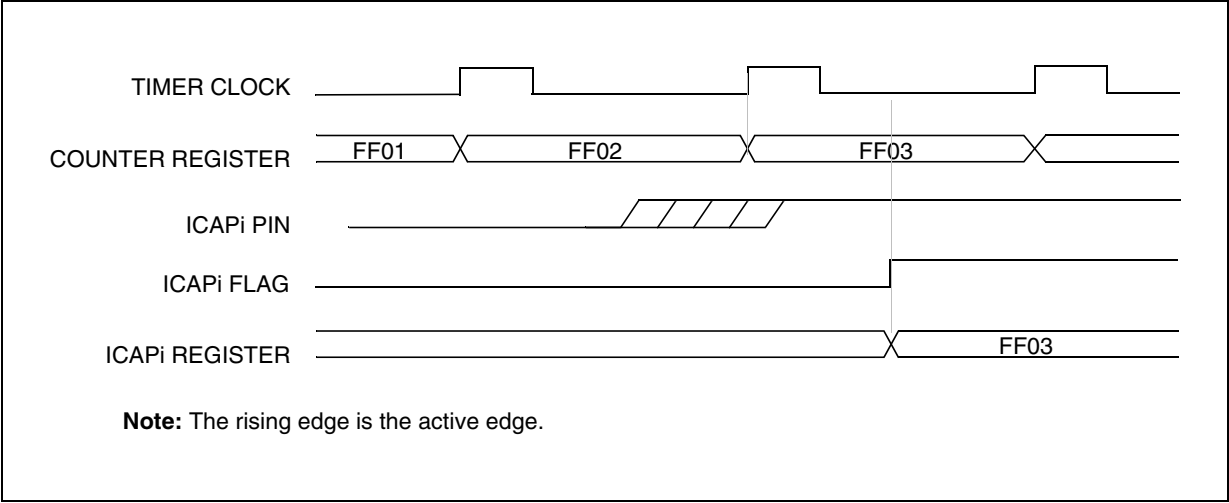


Figure 29. Input Capture Timing Diagram



16-BIT TIMER (Cont'd)

11.2.3.4 Output Compare

In this section, the index, i , may be 1 or 2 because there are two output compare functions in the 16-bit timer.

This function can be used to control an output waveform or indicate when a period of time has elapsed.

When a match is found between the Output Compare register and the free running counter, the output compare function:

- Assigns pins with a programmable value if the OC $\overline{E}$ bit is set
- Sets a flag in the status register
- Generates an interrupt if enabled

Two 16-bit registers Output Compare Register 1 (OC1R) and Output Compare Register 2 (OC2R) contain the value to be compared to the counter register each timer clock cycle.

	MS Byte	LS Byte
OC $\overline{R}$	OC $\overline{H}$ R	OC $\overline{L}$ R

These registers are readable and writable and are not affected by the timer hardware. A reset event changes the OC $\overline{R}$ value to 8000h.

Timing resolution is one count of the free running counter: ($f_{\text{CPU}}/\text{CC}[1:0]$).

Procedure:

To use the output compare function, select the following in the CR2 register:

- Set the OC $\overline{E}$ bit if an output is needed then the OCMP $\overline{i}$ pin is dedicated to the output compare i signal.
- Select the timer clock (CC[1:0]) (see [Table 17, "Clock Control Bits"](#)).

And select the following in the CR1 register:

- Select the OLVL $\overline{i}$ bit to applied to the OCMP $\overline{i}$ pins after the match occurs.
- Set the OCIE bit to generate an interrupt if it is needed.

When a match is found between OCR $\overline{i}$ register and CR register:

- OCF $\overline{i}$ bit is set.

- The OCMP $\overline{i}$ pin takes OLVL $\overline{i}$ bit value (OCMP $\overline{i}$ pin latch is forced low during reset).
- A timer interrupt is generated if the OCIE bit is set in the CR1 register and the I bit is cleared in the CC register (CC).

The OC $\overline{R}$ register value required for a specific timing application can be calculated using the following formula:

$$\Delta \text{OC}\overline{R} = \frac{\Delta t * f_{\text{CPU}}}{\text{PRESC}}$$

Where:

Δt = Output compare period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see [Table 17, "Clock Control Bits"](#))

If the timer clock is an external clock, the formula is:

$$\Delta \text{OC}\overline{R} = \Delta t * f_{\text{EXT}}$$

Where:

Δt = Output compare period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

Clearing the output compare interrupt request (that is, clearing the OCF $\overline{i}$ bit) is done by:

1. Reading the SR register while the OCF $\overline{i}$ bit is set.
2. An access (read or write) to the OC $\overline{L}$ R register.

The following procedure is recommended to prevent the OCF $\overline{i}$ bit from being set between the time it is read and the write to the OC $\overline{R}$ register:

- Write to the OC $\overline{H}$ R register (further compares are inhibited).
- Read the SR register (first step of the clearance of the OCF $\overline{i}$ bit, which may be already set).
- Write to the OC $\overline{L}$ R register (enables the output compare function and clears the OCF $\overline{i}$ bit).

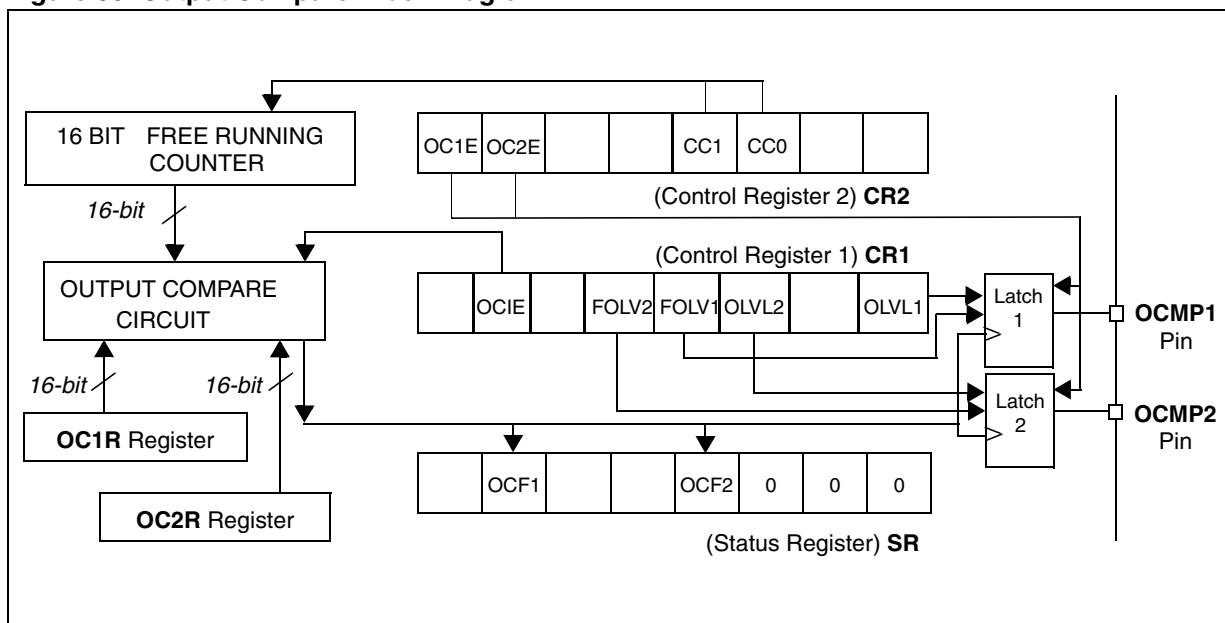
16-BIT TIMER (Cont'd)**Notes:**

1. After a processor write cycle to the OC/HR register, the output compare function is inhibited until the OC/LR register is also written.
2. If the OC/E bit is not set, the OCMP*i* pin is a general I/O port and the OLV*L**i* bit will not appear when a match is found but an interrupt could be generated if the OCIE bit is set.
3. When the timer clock is $f_{CPU}/2$, OCF*i* and OCMP*i* are set while the counter value equals the OC/R register value (see [Figure 31 on page 47](#)). This behavior is the same in OPM or PWM mode.
When the timer clock is $f_{CPU}/4$, $f_{CPU}/8$ or in external clock mode, OCF*i* and OCMP*i* are set while the counter value equals the OC/R register value (see [Figure 32 on page 47](#)).
4. The output compare functions can be used both for generating external events on the OCMP*i* pins even if the input capture mode is also used.
5. The value in the 16-bit OC/R register and the OLV*i* bit should be changed after each successful comparison in order to control an output waveform or establish a new elapsed timeout.

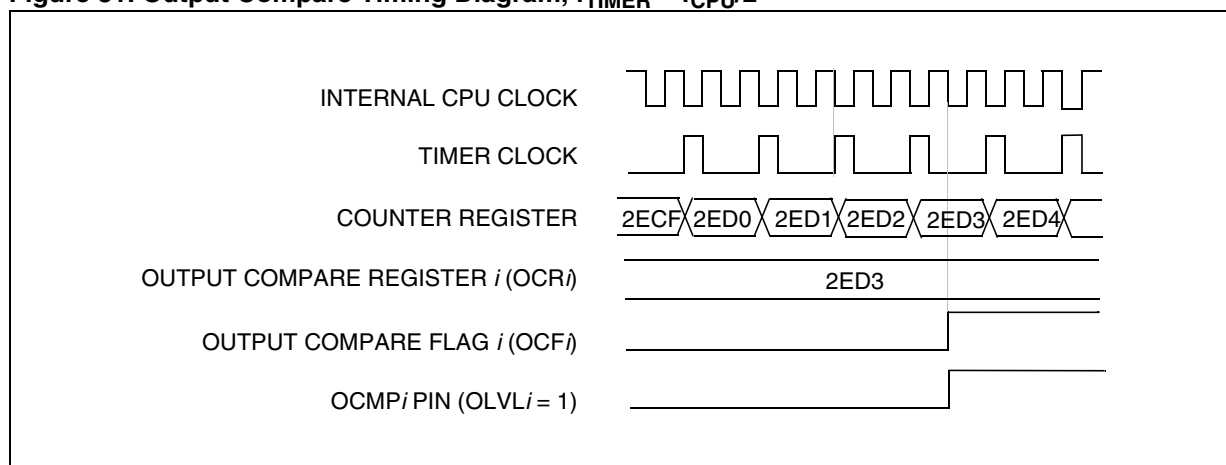
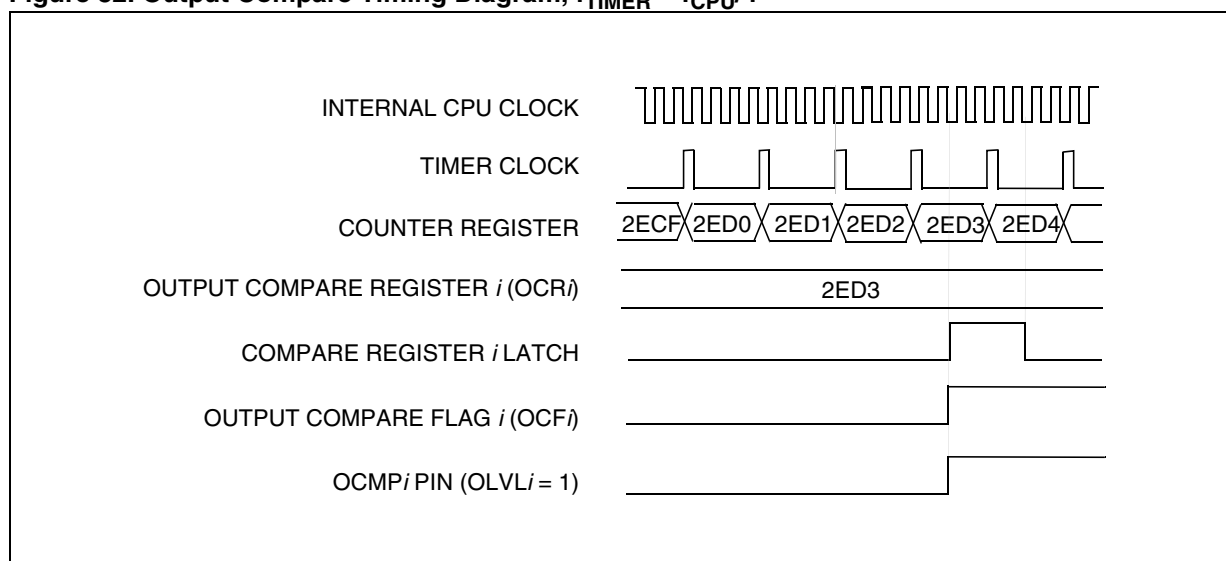
Forced Compare Output capability

When the FOLV*i* bit is set by software, the OLV*L**i* bit is copied to the OCMP*i* pin. The OLV*i* bit has to be toggled in order to toggle the OCMP*i* pin when it is enabled (OC/E bit = 1). The OCF*i* bit is then not set by hardware, and thus no interrupt request is generated.

The FOLVL*i* bits have no effect in both One Pulse mode and PWM mode.

Figure 30. Output Compare Block Diagram

16-BIT TIMER (Cont'd)

Figure 31. Output Compare Timing Diagram, $f_{\text{TIMER}} = f_{\text{CPU}}/2$ Figure 32. Output Compare Timing Diagram, $f_{\text{TIMER}} = f_{\text{CPU}}/4$ 

16-BIT TIMER (Cont'd)

11.2.3.5 One Pulse Mode

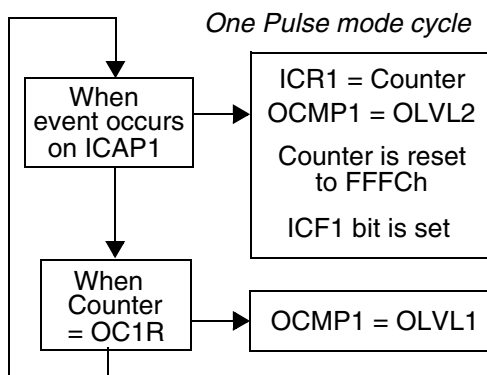
One Pulse mode enables the generation of a pulse when an external event occurs. This mode is selected via the OPM bit in the CR2 register.

The One Pulse mode uses the Input Capture1 function and the Output Compare1 function.

Procedure:

To use One Pulse mode:

1. Load the OC1R register with the value corresponding to the length of the pulse (see the formula in the opposite column).
2. Select the following in the CR1 register:
 - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after the pulse.
 - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin during the pulse.
 - Select the edge of the active transition on the ICAP1 pin with the IEDG1 bit (the ICAP1 pin must be configured as floating input).
3. Select the following in the CR2 register:
 - Set the OC1E bit, the OCMP1 pin is then dedicated to the Output Compare 1 function.
 - Set the OPM bit.
 - Select the timer clock CC[1:0] (see [Table 17, "Clock Control Bits"](#)).



Then, on a valid event on the ICAP1 pin, the counter is initialized to FFFCh and OLVL2 bit is loaded on the OCMP1 pin, the ICF1 bit is set and the value FFFDh is loaded in the IC1R register.

Because the ICF1 bit is set when an active edge occurs, an interrupt can be generated if the ICIE bit is set.

Clearing the Input Capture interrupt request (that is, clearing the ICF1 bit) is done in two steps:

1. Reading the SR register while the ICF1 bit is set.
2. An access (read or write) to the IC1LR register.

The OC1R register value required for a specific timing application can be calculated using the following formula:

$$\text{OC1R Value} = \frac{t * f_{\text{CPU}}}{\text{PRESC}} - 5$$

Where:

t = Pulse period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on the CC[1:0] bits, see [Table 17, "Clock Control Bits"](#))

If the timer clock is an external clock the formula is:

$$\text{OC1R} = t * f_{\text{EXT}} - 5$$

Where:

t = Pulse period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

When the value of the counter is equal to the value of the contents of the OC1R register, the OLVL1 bit is output on the OCMP1 pin, (See [Figure 33](#)).

Notes:

1. The OCF1 bit cannot be set by hardware in One Pulse mode but the OCF2 bit can generate an Output Compare interrupt.
2. When the Pulse Width Modulation (PWM) and One Pulse mode (OPM) bits are both set, the PWM mode is the only active one.
3. If OLVL1 = OLVL2 a continuous signal will be seen on the OCMP1 pin.
4. The ICAP1 pin can not be used to perform input capture. The ICAP2 pin can be used to perform input capture (ICF2 can be set and IC2R can be loaded) but the user must take care that the counter is reset each time a valid edge occurs on the ICAP1 pin and ICF1 can also generates interrupt if ICIE is set.
5. When One Pulse mode is used OC1R is dedicated to this mode. Nevertheless OC2R and OCF2 can be used to indicate a period of time has been elapsed but cannot generate an output waveform because the level OLVL2 is dedicated to the One Pulse mode.

16-BIT TIMER (Cont'd)

Figure 33. One Pulse Mode Timing Example

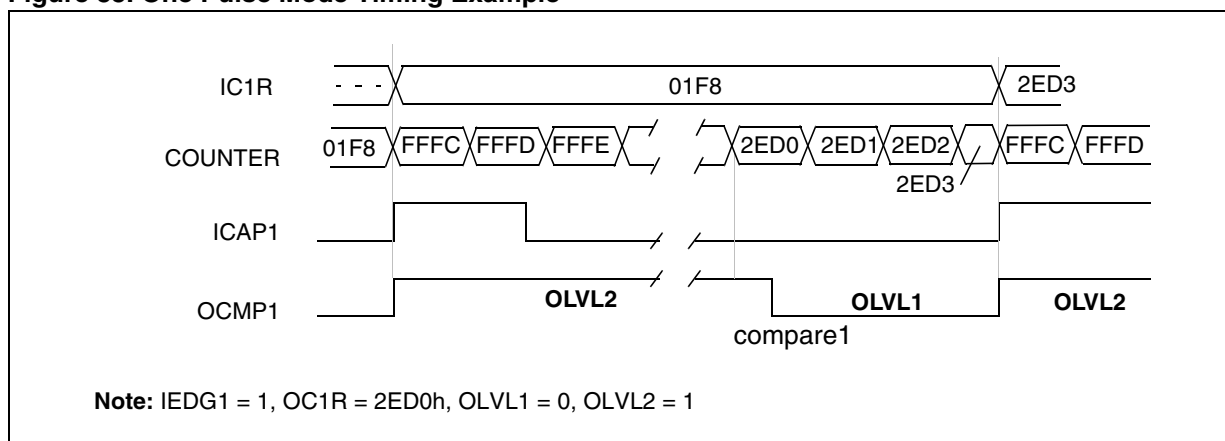
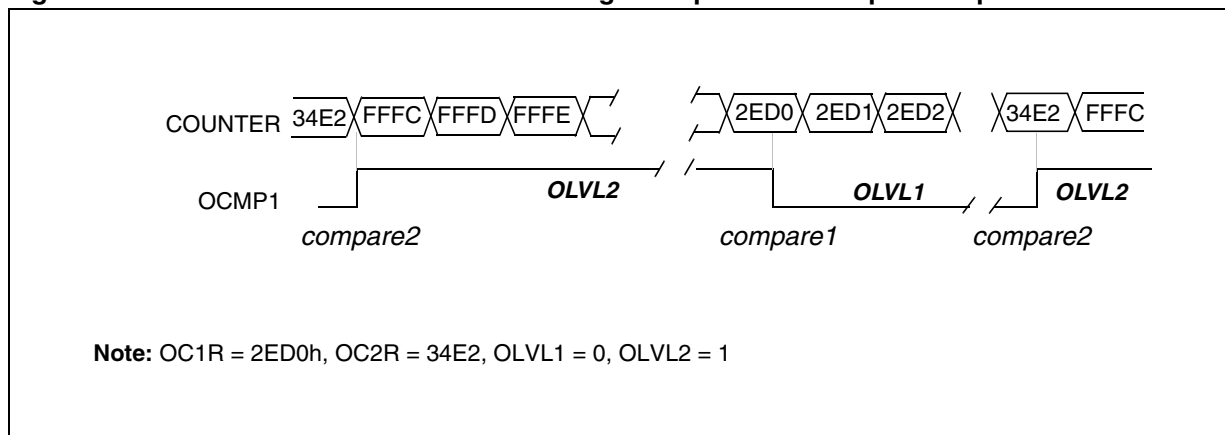


Figure 34. Pulse Width Modulation Mode Timing Example with 2 Output Compare Functions



Note: On timers with only one Output Compare register, a fixed frequency PWM signal can be generated using the output compare and the counter overflow to define the pulse length.

16-BIT TIMER (Cont'd)

11.2.3.6 Pulse Width Modulation Mode

Pulse Width Modulation (PWM) mode enables the generation of a signal with a frequency and pulse length determined by the value of the OC1R and OC2R registers.

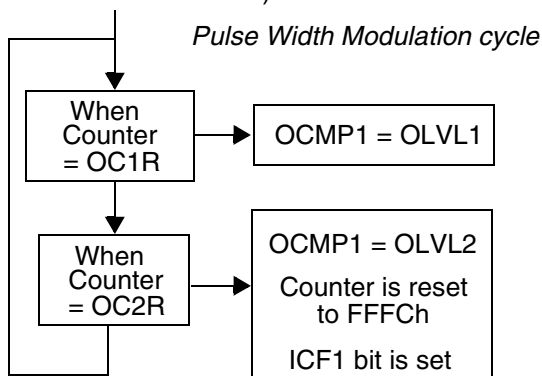
Pulse Width Modulation mode uses the complete Output Compare 1 function plus the OC2R register, and so this functionality can not be used when PWM mode is activated.

In PWM mode, double buffering is implemented on the output compare registers. Any new values written in the OC1R and OC2R registers are taken into account only at the end of the PWM period (OC2) to avoid spikes on the PWM output pin (OCMP1).

Procedure

To use Pulse Width Modulation mode:

1. Load the OC2R register with the value corresponding to the period of the signal using the formula in the opposite column.
2. Load the OC1R register with the value corresponding to the period of the pulse if (OLVL1 = 0 and OLVL2 = 1) using the formula in the opposite column.
3. Select the following in the CR1 register:
 - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC1R register.
 - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC2R register.
4. Select the following in the CR2 register:
 - Set OC1E bit: the OCMP1 pin is then dedicated to the output compare 1 function.
 - Set the PWM bit.
 - Select the timer clock (CC[1:0]) (see [Table 17, "Clock Control Bits"](#)).



If OLVL1 = 1 and OLVL2 = 0 the length of the positive pulse is the difference between the OC2R and OC1R registers.

If OLVL1 = OLVL2 a continuous signal will be seen on the OCMP1 pin.

The OC/R register value required for a specific timing application can be calculated using the following formula:

$$\text{OC/R Value} = \frac{t * f_{\text{CPU}}}{\text{PRESC}} - 5$$

Where:

t = Signal or pulse period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see [Table 17, "Clock Control Bits"](#))

If the timer clock is an external clock the formula is:

$$\text{OC/R} = t * f_{\text{EXT}} - 5$$

Where:

t = Signal or pulse period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

The Output Compare 2 event causes the counter to be initialized to FFFCh (See [Figure 34](#))

Notes:

1. After a write instruction to the OC/HR register, the output compare function is inhibited until the OC/LR register is also written.
2. The OCF1 and OCF2 bits cannot be set by hardware in PWM mode therefore the Output Compare interrupt is inhibited.
3. The ICF1 bit is set by hardware when the counter reaches the OC2R value and can produce a timer interrupt if the ICIE bit is set and the I bit is cleared.
4. In PWM mode the ICAP1 pin can not be used to perform input capture because it is disconnected to the timer. The ICAP2 pin can be used to perform input capture (ICF2 can be set and IC2R can be loaded) but the user must take care that the counter is reset each period and ICF1 can also generates interrupt if ICIE is set.
5. When the Pulse Width Modulation (PWM) and One Pulse mode (OPM) bits are both set, the PWM mode is the only active one.

16-BIT TIMER (Cont'd)

11.2.4 Low Power Modes

Mode	Description
WAIT	No effect on 16-bit Timer. Timer interrupts cause the device to exit from WAIT mode.
HALT	16-bit Timer registers are frozen. In HALT mode, the counter stops counting until Halt mode is exited. Counting resumes from the previous count when the MCU is woken up by an interrupt with “exit from HALT mode” capability or from the counter reset value when the MCU is woken up by a RESET. If an input capture event occurs on the ICAP _i pin, the input capture detection circuitry is armed. Consequently, when the MCU is woken up by an interrupt with “exit from HALT mode” capability, the ICF _i bit is set, and the counter value present when exiting from HALT mode is captured into the IC _i R register.

11.2.5 Interrupts

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
Input Capture 1 event/Counter reset in PWM mode	ICF1	ICIE	Yes	No
Input Capture 2 event	ICF2			
Output Compare 1 event (not available in PWM mode)	OCF1	OCIE		
Output Compare 2 event (not available in PWM mode)	OCF2			
Timer Overflow event	TOF	TOIE		

Note: The 16-bit Timer interrupt events are connected to the same interrupt vector (see Interrupts chapter). These events generate an interrupt if the corresponding Enable Control Bit is set and the interrupt mask in the CC register is reset (RIM instruction).

11.2.6 Summary of Timer Modes

MODES	TIMER RESOURCES			
	Input Capture 1	Input Capture 2	Output Compare 1	Output Compare 2
Input Capture (1 and/or 2)	Yes	Yes	Yes	Yes
Output Compare (1 and/or 2)				
One Pulse Mode	No	Not Recommended ¹⁾	No	Partially ²⁾
PWM Mode		Not Recommended ³⁾		No

1) See note 4 in [Section 11.2.3.5, "One Pulse Mode"](#)

2) See note 5 in [Section 11.2.3.5, "One Pulse Mode"](#)

3) See note 4 in [Section 11.2.3.6, "Pulse Width Modulation Mode"](#)

16-BIT TIMER (Cont'd)**11.2.7 Register Description**

Each Timer is associated with three control and status registers, and with six pairs of data registers (16-bit values) relating to the two input captures, the two output compares, the counter and the alternate counter.

CONTROL REGISTER 1 (CR1)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
ICIE	OCIE	TOIE	FOLV2	FOLV1	OLVL2	IEDG1	OLVL1

Bit 7 = **ICIE** *Input Capture Interrupt Enable*.

0: Interrupt is inhibited.

1: A timer interrupt is generated whenever the ICF1 or ICF2 bit of the SR register is set.

Bit 6 = **OCIE** *Output Compare Interrupt Enable*.

0: Interrupt is inhibited.

1: A timer interrupt is generated whenever the OCF1 or OCF2 bit of the SR register is set.

Bit 5 = **TOIE** *Timer Overflow Interrupt Enable*.

0: Interrupt is inhibited.

1: A timer interrupt is enabled whenever the TOF bit of the SR register is set.

Bit 4 = **FOLV2** *Forced Output Compare 2*.

This bit is set and cleared by software.

0: No effect on the OCMP2 pin.

1: Forces the OLVL2 bit to be copied to the OCMP2 pin, if the OC2E bit is set and even if there is no successful comparison.

Bit 3 = **FOLV1** *Forced Output Compare 1*.

This bit is set and cleared by software.

0: No effect on the OCMP1 pin.

1: Forces OLVL1 to be copied to the OCMP1 pin, if the OC1E bit is set and even if there is no successful comparison.

Bit 2 = **OLVL2** *Output Level 2*.

This bit is copied to the OCMP2 pin whenever a successful comparison occurs with the OC2R register and OCxE is set in the CR2 register. This value is copied to the OCMP1 pin in One Pulse mode and Pulse Width Modulation mode.

Bit 1 = **IEDG1** *Input Edge 1*.

This bit determines which type of level transition on the ICAP1 pin will trigger the capture.

0: A falling edge triggers the capture.

1: A rising edge triggers the capture.

Bit 0 = **OLVL1** *Output Level 1*.

The OLVL1 bit is copied to the OCMP1 pin whenever a successful comparison occurs with the OC1R register and the OC1E bit is set in the CR2 register.

16-BIT TIMER (Cont'd)**CONTROL REGISTER 2 (CR2)**

Read/Write

Reset Value: 0000 0000 (00h)

7							0
OC1E	OC2E	OPM	PWM	CC1	CC0	IEDG2	EXEDG

Bit 7 = **OC1E** *Output Compare 1 Pin Enable*.

This bit is used only to output the signal from the timer on the OCMP1 pin (OLV1 in Output Compare mode, both OLV1 and OLV2 in PWM and one-pulse mode). Whatever the value of the OC1E bit, the Output Compare 1 function of the timer remains active.

0: OCMP1 pin alternate function disabled (I/O pin free for general-purpose I/O).

1: OCMP1 pin alternate function enabled.

Bit 6 = **OC2E** *Output Compare 2 Pin Enable*.

This bit is used only to output the signal from the timer on the OCMP2 pin (OLV2 in Output Compare mode). Whatever the value of the OC2E bit, the Output Compare 2 function of the timer remains active.

0: OCMP2 pin alternate function disabled (I/O pin free for general-purpose I/O).

1: OCMP2 pin alternate function enabled.

Bit 5 = **OPM** *One Pulse Mode*.

0: One Pulse mode is not active.

1: One Pulse mode is active, the ICAP1 pin can be used to trigger one pulse on the OCMP1 pin; the active transition is given by the IEDG1 bit. The length of the generated pulse depends on the contents of the OC1R register.

Bit 4 = **PWM** *Pulse Width Modulation*.

0: PWM mode is not active.

1: PWM mode is active, the OCMP1 pin outputs a programmable cyclic signal; the length of the pulse depends on the value of OC1R register; the period depends on the value of OC2R register.

Bit 3, 2 = **CC[1:0]** *Clock Control*.

The timer clock mode depends on these bits:

Table 17. Clock Control Bits

Timer Clock	CC1	CC0
$f_{CPU} / 4$	0	0
$f_{CPU} / 2$		1
$f_{CPU} / 8$	1	0
External Clock (where available)		1

Note: If the external clock pin is not available, programming the external clock configuration stops the counter.

Bit 1 = **IEDG2** *Input Edge 2*.

This bit determines which type of level transition on the ICAP2 pin will trigger the capture.

0: A falling edge triggers the capture.

1: A rising edge triggers the capture.

Bit 0 = **EXEDG** *External Clock Edge*.

This bit determines which type of level transition on the external clock pin EXTCLK will trigger the counter register.

0: A falling edge triggers the counter register.

1: A rising edge triggers the counter register.

16-BIT TIMER (Cont'd)**CONTROL/STATUS REGISTER (CSR)**

Read/Write (bits 7:3 read only)

Reset Value: xxxx x0xx (xxh)

7			0				
ICF1	OCF1	TOF	ICF2	OCF2	TIMD	0	0

Bit 7 = ICF1 Input Capture Flag 1.

0: No input capture (reset value).

1: An input capture has occurred on the ICAP1 pin or the counter has reached the OC2R value in PWM mode. To clear this bit, first read the SR register, then read or write the low byte of the IC1R (IC1LR) register.

Bit 6 = OCF1 Output Compare Flag 1.

0: No match (reset value).

1: The content of the free running counter has matched the content of the OC1R register. To clear this bit, first read the SR register, then read or write the low byte of the OC1R (OC1LR) register.

Bit 5 = TOF Timer Overflow Flag.

0: No timer overflow (reset value).

1: The free running counter rolled over from FFFFh to 0000h. To clear this bit, first read the SR register, then read or write the low byte of the CR (CLR) register.

Note: Reading or writing the ACLR register does not clear TOF.

Bit 4 = ICF2 Input Capture Flag 2.

0: No input capture (reset value).

1: An input capture has occurred on the ICAP2 pin. To clear this bit, first read the SR register, then read or write the low byte of the IC2R (IC2LR) register.

Bit 3 = OCF2 Output Compare Flag 2.

0: No match (reset value).

1: The content of the free running counter has matched the content of the OC2R register. To clear this bit, first read the SR register, then read or write the low byte of the OC2R (OC2LR) register.

Bit 2 = TIMD Timer disable.

This bit is set and cleared by software. When set, it freezes the timer prescaler and counter and disabled the output functions (OCMP1 and OCMP2 pins) to reduce power consumption. Access to the timer registers is still available, allowing the timer configuration to be changed, or the counter reset, while it is disabled.

0: Timer enabled

1: Timer prescaler, counter and outputs disabled

Bits 1:0 = Reserved, must be kept cleared.

16-BIT TIMER (Cont'd)**INPUT CAPTURE 1 HIGH REGISTER (IC1HR)**

Read Only

Reset Value: Undefined

This is an 8-bit read only register that contains the high part of the counter value (transferred by the input capture 1 event).

7							0
MSB							LSB

INPUT CAPTURE 1 LOW REGISTER (IC1LR)

Read Only

Reset Value: Undefined

This is an 8-bit read only register that contains the low part of the counter value (transferred by the input capture 1 event).

7							0
MSB							LSB

OUTPUT COMPARE 1 HIGH REGISTER (OC1HR)

Read/Write

Reset Value: 1000 0000 (80h)

This is an 8-bit register that contains the high part of the value to be compared to the CHR register.

7							0
MSB							LSB

OUTPUT COMPARE 1 LOW REGISTER (OC1LR)

Read/Write

Reset Value: 0000 0000 (00h)

This is an 8-bit register that contains the low part of the value to be compared to the CLR register.

7							0
MSB							LSB

16-BIT TIMER (Cont'd)**OUTPUT COMPARE 2 HIGH REGISTER (OC2HR)**

Read/Write

Reset Value: 1000 0000 (80h)

This is an 8-bit register that contains the high part of the value to be compared to the CHR register.

7							0
MSB							LSB

OUTPUT COMPARE 2 LOW REGISTER (OC2LR)

Read/Write

Reset Value: 0000 0000 (00h)

This is an 8-bit register that contains the low part of the value to be compared to the CLR register.

7							0
MSB							LSB

COUNTER HIGH REGISTER (CHR)

Read Only

Reset Value: 1111 1111 (FFh)

This is an 8-bit register that contains the high part of the counter value.

7							0
MSB							LSB

COUNTER LOW REGISTER (CLR)

Read Only

Reset Value: 1111 1100 (FCh)

This is an 8-bit register that contains the low part of the counter value. A write to this register resets the counter. An access to this register after accessing the CSR register clears the TOF bit.

7							0
MSB							LSB

ALTERNATE COUNTER HIGH REGISTER (ACHR)

Read Only

Reset Value: 1111 1111 (FFh)

This is an 8-bit register that contains the high part of the counter value.

7							0
MSB							LSB

ALTERNATE COUNTER LOW REGISTER (ACLR)

Read Only

Reset Value: 1111 1100 (FCh)

This is an 8-bit register that contains the low part of the counter value. A write to this register resets the counter. An access to this register after an access to CSR register does not clear the TOF bit in the CSR register.

7							0
MSB							LSB

INPUT CAPTURE 2 HIGH REGISTER (IC2HR)

Read Only

Reset Value: Undefined

This is an 8-bit read only register that contains the high part of the counter value (transferred by the Input Capture 2 event).

7							0
MSB							LSB

INPUT CAPTURE 2 LOW REGISTER (IC2LR)

Read Only

Reset Value: Undefined

This is an 8-bit read only register that contains the low part of the counter value (transferred by the Input Capture 2 event).

7							0
MSB							LSB

16-BIT TIMER (Cont'd)**Table 18. 16-Bit Timer Register Map and Reset Values**

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
11	CR2 Reset Value	OC1E 0	OC2E 0	OPM 0	PWM 0	CC1 0	CC0 0	IEDG2 0	EXEDG 0
12	CR1 Reset Value	ICIE 0	OCIE 0	TOIE 0	FOLV2 0	FOLV1 0	OLVL2 0	IEDG1 0	OLVL1 0
13	CSR Reset Value	ICF1 0	OCF1 0	TOF 0	ICF2 0	OCF2 0	TIMD 0	0 0	0 0
14	IC1HR Reset Value	MSB							LSB
15	IC1LR Reset Value	MSB							LSB
16	OC1HR Reset Value	MSB 1	- 0	- 0	- 0	- 0	- 0	- 0	LSB 0
17	OC1LR Reset Value	MSB 0	- 0	- 0	- 0	- 0	- 0	- 0	LSB 0
18	CHR Reset Value	MSB 1	- 1	- 1	- 1	- 1	- 1	- 1	LSB 1
19	CLR Reset Value	MSB 1	- 1	- 1	- 1	- 1	- 1	- 0	LSB 0
1A	ACHR Reset Value	MSB 1	- 1	- 1	- 1	- 1	- 1	- 1	LSB 1
1B	ACLR Reset Value	MSB 1	- 1	- 1	- 1	- 1	- 1	- 0	LSB 0
1C	IC2HR Reset Value	MSB							LSB
1D	IC2LR Reset Value	MSB							LSB
1E	OC2HR Reset Value	MSB 1	- 0	- 0	- 0	- 0	- 0	- 0	LSB 0
1F	OC2LR Reset Value	MSB 0	- 0	- 0	- 0	- 0	- 0	- 0	LSB 0

11.3 SERIAL COMMUNICATIONS INTERFACE (SCI)

11.3.1 Introduction

The Serial Communications Interface (SCI) offers a flexible means of full-duplex data exchange with external equipment requiring an industry standard NRZ asynchronous serial data format. The SCI offers a very wide range of baud rates using two baud rate generator systems.

11.3.2 Main Features

- Full duplex, asynchronous communications
- NRZ standard format (Mark/Space)
- Independently programmable transmit and receive baud rates up to 250K baud.
- Programmable data word length (8 or 9 bits)
- Receive buffer full, Transmit buffer empty and End of Transmission flags
- Two receiver wake-up modes:
 - Address bit (MSB)
 - Idle line
- Muting function for multiprocessor configurations
- Separate enable bits for Transmitter and Receiver
- Four error detection flags:
 - Overrun error
 - Noise error
 - Frame error
 - Parity error
- Six interrupt sources with flags:
 - Transmit data register empty
 - Transmission complete
 - Receive data register full
 - Idle line received
 - Overrun error detected
 - Parity error
- Parity control:
 - Transmits parity bit
 - Checks parity of received data byte
- Reduced power consumption mode

11.3.3 General Description

The interface is externally connected to another device by two pins (see [Figure 36](#)):

- TDO: Transmit Data Output. When the transmitter and the receiver are disabled, the output pin returns to its I/O port configuration. When the transmitter and/or the receiver are enabled and nothing is to be transmitted, the TDO pin is at high level.
- RDI: Receive Data Input is the serial data input. Oversampling techniques are used for data recovery by discriminating between valid incoming data and noise.

Through these pins, serial data is transmitted and received as frames comprising:

- An Idle Line prior to transmission or reception
- A start bit
- A data word (8 or 9 bits) least significant bit first
- A Stop bit indicating that the frame is complete.

This interface uses two types of baud rate generator:

- A conventional type for commonly-used baud rates.

The diagram illustrates the internal architecture of the SCI module, organized into several functional blocks and registers:

- Registers and Shift Registers:**
 - CR1 (Control Register 1):** Contains bits R8, T8, SCID, M, WAKE, PCE, PS, and PIE.
 - CR2 (Control Register 2):** Contains bits TIE, TCIE, RIE, ILIE, TE, RE, RWU, and SBK.
 - SR (Status Register):** Contains bits TDRE, TC, RDRF, IDLE, OR, NF, FE, and PE.
 - BRR (Baud Rate Register):** Contains bits SCP1, SCP0, SCT2, SCT1, SCT0, SCR2, SCR1, and SCR0.
 - TDR (Transmit Data Register):** Connected to the Transmit Shift Register via a Write operation.
 - RDR (Received Data Register):** Connected to the Received Shift Register via a Read operation.
- Control and Status Blocks:**
 - Transmit Control:** Receives data from the Transmit Shift Register and manages transmission. It is controlled by TIE, TCIE, RIE, ILIE, TE, RE, RWU, and SBK.
 - Receiver Control:** Manages reception and is controlled by WAKE, PCE, PS, and PIE.
 - WAKE UP UNIT:** Receives the WAKE signal from CR1 and controls the RWU bit in CR2.
 - SCI INTERRUPT CONTROL:** Generates interrupt signals based on TIE, TCIE, RIE, and ILIE.
- Clocks and Timing:**
 - TRANSMITTER CLOCK:** Derived from f_{CPU} through a $/16$ divider and a $/PR$ prescaler.
 - RECEIVER CLOCK:** Provided as an external input to the Receiver Control.
- Baud Rate Generator (BRG):** A dashed box containing:
 - TRANSMITTER RATE CONTROL:** Receives the $/PR$ value and the BRR register to generate the transmit clock.
 - RECEIVER RATE CONTROL:** Receives the $/PR$ value and the BRR register to generate the receiver clock.
- External Signals:**
 - TDO (Transmit Data Output):** The output of the Transmit Shift Register.
 - RDI (Receive Data Input):** The input to the Received Shift Register.

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

11.3.4 Functional Description

The block diagram of the Serial Control Interface, is shown in [Figure 35](#) It contains 6 dedicated registers:

- Two control registers (SCICR1 & SCICR2)
- A status register (SCISR)
- A baud rate register (SCIBRR)

Refer to the register descriptions in [Section 11.3.7](#) for the definitions of each bit.

11.3.4.1 Serial Data Format

Word length may be selected as being either 8 or 9 bits by programming the M bit in the SCICR1 register (see [Figure 35](#)).

The TDO pin is in low state during the start bit.

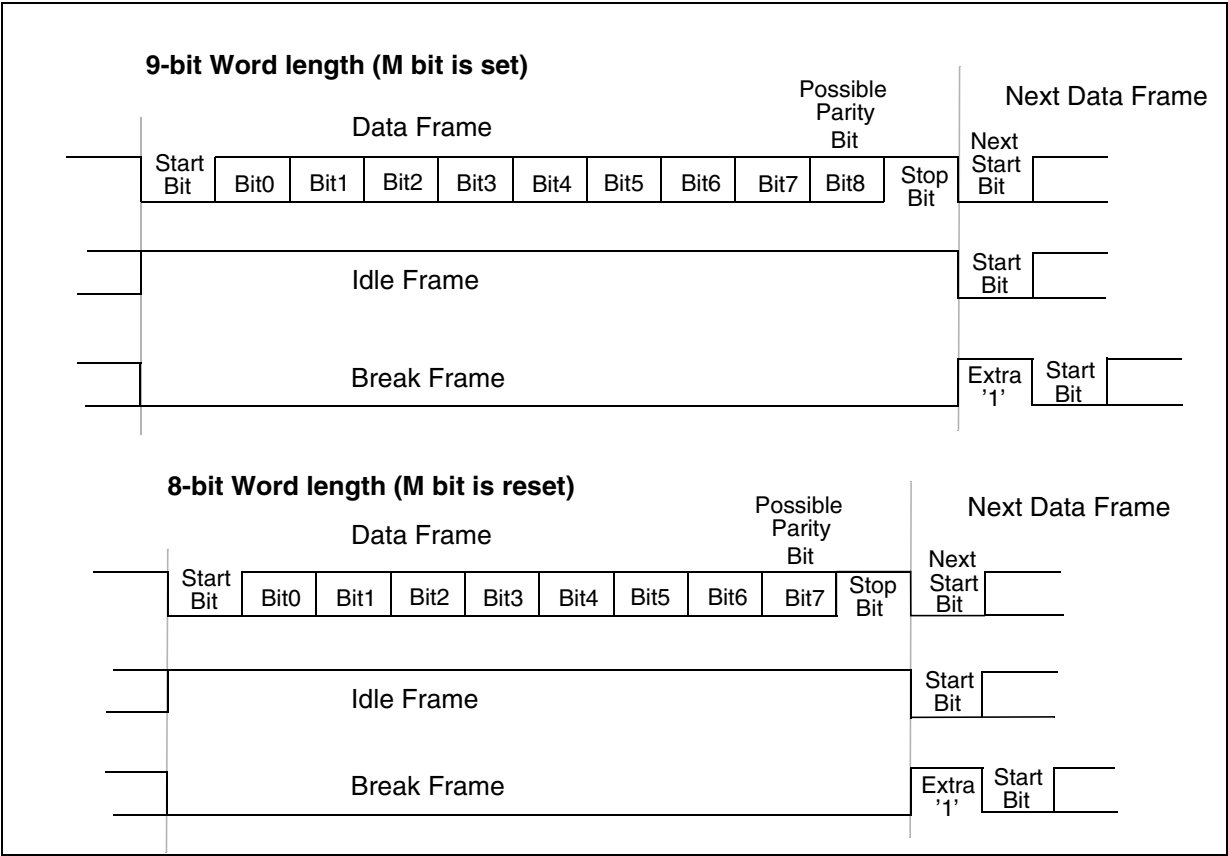
The TDO pin is in high state during the stop bit.

An Idle character is interpreted as an entire frame of “1”s followed by the start bit of the next frame which contains data.

A Break character is interpreted on receiving “0”s for some multiple of the frame period. At the end of the last break frame the transmitter inserts an extra “1” bit to acknowledge the start bit.

Transmission and reception are driven by their own baud rate generator.

Figure 36. Word Length Programming



SERIAL COMMUNICATIONS INTERFACE (Cont'd)

11.3.4.2 Transmitter

The transmitter can send data words of either 8 or 9 bits depending on the M bit status. When the M bit is set, word length is 9 bits and the 9th bit (the MSB) has to be stored in the T8 bit in the SCICR1 register.

Character Transmission

During an SCI transmission, data shifts out least significant bit first on the TDO pin. In this mode, the SCIDR register consists of a buffer (TDR) between the internal bus and the transmit shift register (see [Figure 35](#)).

Procedure

- Select the M bit to define the word length.
- Select the desired baud rate using the SCIBRR and the SCIETPR registers.
- Set the TE bit to assign the TDO pin to the alternate function and to send a idle frame as first transmission.
- Access the SCISR register and write the data to send in the SCIDR register (this sequence clears the TDRE bit). Repeat this sequence for each data to be transmitted.

Clearing the TDRE bit is always performed by the following software sequence:

1. An access to the SCISR register
2. A write to the SCIDR register

The TDRE bit is set by hardware and it indicates:

- The TDR register is empty.
- The data transfer is beginning.
- The next data can be written in the SCIDR register without overwriting the previous data.

This flag generates an interrupt if the TIE bit is set and the I bit is cleared in the CCR register.

When a transmission is taking place, a write instruction to the SCIDR register stores the data in the TDR register and which is copied in the shift register at the end of the current transmission.

When no transmission is taking place, a write instruction to the SCIDR register places the data directly in the shift register, the data transmission starts, and the TDRE bit is immediately set.

When a frame transmission is complete (after the stop bit or after the break frame) the TC bit is set and an interrupt is generated if the TCIE is set and the I bit is cleared in the CCR register.

Clearing the TC bit is performed by the following software sequence:

1. An access to the SCISR register
2. A write to the SCIDR register

Note: The TDRE and TC bits are cleared by the same software sequence.

Break Characters

Setting the SBK bit loads the shift register with a break character. The break frame length depends on the M bit (see [Figure 36](#)).

As long as the SBK bit is set, the SCI send break frames to the TDO pin. After clearing this bit by software the SCI insert a logic 1 bit at the end of the last break frame to guarantee the recognition of the start bit of the next frame.

Idle Characters

Setting the TE bit drives the SCI to send an idle frame before the first data frame.

Clearing and then setting the TE bit during a transmission sends an idle frame after the current word.

Note: Resetting and setting the TE bit causes the data in the TDR register to be lost. Therefore the best time to toggle the TE bit is when the TDRE bit is set i.e. before writing the next byte in the SCIDR.

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

11.3.4.3 Receiver

The SCI can receive data words of either 8 or 9 bits. When the M bit is set, word length is 9 bits and the MSB is stored in the R8 bit in the SCICR1 register.

Character reception

During a SCI reception, data shifts in least significant bit first through the RDI pin. In this mode, the SCIDR register consists of a buffer (RDR) between the internal bus and the received shift register (see [Figure 35](#)).

Procedure

- Select the M bit to define the word length.
- Select the desired baud rate using the SCIBRR and the SCIERPR registers.
- Set the RE bit, this enables the receiver which begins searching for a start bit.

When a character is received:

- The RDRF bit is set. It indicates that the content of the shift register is transferred to the RDR.
- An interrupt is generated if the RIE bit is set and the I bit is cleared in the CCR register.
- The error flags can be set if a frame error, noise or an overrun error has been detected during reception.

Clearing the RDRF bit is performed by the following software sequence done by:

1. An access to the SCISR register
2. A read to the SCIDR register.

The RDRF bit must be cleared before the end of the reception of the next character to avoid an overrun error.

Break Character

When a break character is received, the SCI handles it as a framing error.

Idle Character

When a idle frame is detected, there is the same procedure as a data received character plus an interrupt if the ILIE bit is set and the I bit is cleared in the CCR register.

Overrun Error

An overrun error occurs when a character is received when RDRF has not been reset. Data can not be transferred from the shift register to the

RDR register as long as the RDRF bit is not cleared.

When a overrun error occurs:

- The OR bit is set.
- The RDR content will not be lost.
- The shift register will be overwritten.
- An interrupt is generated if the RIE bit is set and the I bit is cleared in the CCR register.

The OR bit is reset by an access to the SCISR register followed by a SCIDR register read operation.

Noise Error

Oversampling techniques are used for data recovery by discriminating between valid incoming data and noise. Normal data bits are considered valid if three consecutive samples (8th, 9th, 10th) have the same bit value, otherwise the NF flag is set. In the case of start bit detection, the NF flag is set on the basis of an algorithm combining both valid edge detection and three samples (8th, 9th, 10th). Therefore, to prevent the NF flag getting set during start bit reception, there should be a valid edge detection as well as three valid samples.

When noise is detected in a frame:

- The NF flag is set at the rising edge of the RDRF bit.
- Data is transferred from the Shift register to the SCIDR register.
- No interrupt is generated. However this bit rises at the same time as the RDRF bit which itself generates an interrupt.

The NF flag is reset by a SCISR register read operation followed by a SCIDR register read operation.

During reception, if a false start bit is detected (e.g. 8th, 9th, 10th samples are 011,101,110), the frame is discarded and the receiving sequence is not started for this frame. There is no RDRF bit set for this frame and the NF flag is set internally (not accessible to the user). This NF flag is accessible along with the RDRF bit when a next valid frame is received.

Note: If the application Start Bit is not long enough to match the above requirements, then the NF Flag may get set due to the short Start Bit. In this case, the NF flag may be ignored by the application software when the first valid byte is received.

See also [Section 11.3.4.9](#).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

Framing Error

A framing error is detected when:

- The stop bit is not recognized on reception at the expected time, following either a de-synchronization or excessive noise.
- A break is received.

When the framing error is detected:

- the FE bit is set by hardware
- Data is transferred from the Shift register to the SCIDR register.
- No interrupt is generated. However this bit rises at the same time as the RDRF bit which itself generates an interrupt.

The FE bit is reset by a SCISR register read operation followed by a SCIDR register read operation.

11.3.4.4 Baud Rate Generation

The baud rate for the receiver and transmitter (Rx and Tx) are set independently and calculated as follows:

$$Tx = \frac{f_{CPU}}{(16 \cdot PR) \cdot TR} \quad Rx = \frac{f_{CPU}}{(16 \cdot PR) \cdot RR}$$

with:

PR = 1, 3, 4 or 13 (see SCP[1:0] bits)

TR = 1, 2, 4, 8, 16, 32, 64, 128

(see SCT[2:0] bits)

RR = 1, 2, 4, 8, 16, 32, 64, 128

(see SCR[2:0] bits)

All these bits are in the SCIBRR register.

Example: If f_{CPU} is 8 MHz (normal mode) and if PR=13 and TR=RR=1, the transmit and receive baud rates are 38400 baud.

Note: the baud rate registers **MUST NOT** be changed while the transmitter or the receiver is enabled.

11.3.4.5 Receiver Muting and Wake-up Feature

In multiprocessor configurations it is often desirable that only the intended message recipient should actively receive the full message contents, thus reducing redundant SCI service overhead for all non addressed receivers.

The non addressed devices may be placed in sleep mode by means of the muting function.

Setting the RWU bit by software puts the SCI in sleep mode:

All the reception status bits can not be set.

All the receive interrupts are inhibited.

A muted receiver may be awakened by one of the following two ways:

- by Idle Line detection if the WAKE bit is reset,
- by Address Mark detection if the WAKE bit is set.

Receiver wakes-up by Idle Line detection when the Receive line has recognised an Idle Frame. Then the RWU bit is reset by hardware but the IDLE bit is not set.

Receiver wakes-up by Address Mark detection when it received a "1" as the most significant bit of a word, thus indicating that the message is an address. The reception of this particular word wakes up the receiver, resets the RWU bit and sets the RDRF bit, which allows the receiver to receive this word normally and to use it as an address word.

Caution: In Mute mode, do not write to the SCICR2 register. If the SCI is in Mute mode during the read operation (RWU=1) and a address mark wake up event occurs (RWU is reset) before the write operation, the RWU bit will be set again by this write operation. Consequently the address byte is lost and the SCI is not woken up from Mute mode.

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**11.3.4.6 Parity Control**

Parity control (generation of parity bit in transmission and parity checking in reception) can be enabled by setting the PCE bit in the SCICR1 register. Depending on the frame length defined by the M bit, the possible SCI frame formats are as listed in Table 19.

Table 19. Frame Formats

M bit	PCE bit	SCI frame
0	0	SB 8 bit data STB
0	1	SB 7-bit data PB STB
1	0	SB 9-bit data STB
1	1	SB 8-bit data PB STB

Legend: SB = Start Bit, STB = Stop Bit,
PB = Parity Bit

Note: In case of wake up by an address mark, the MSB bit of the data is taken into account and not the parity bit

Even parity: the parity bit is calculated to obtain an even number of “1s” inside the frame made of the 7 or 8 LSB bits (depending on whether M is equal to 0 or 1) and the parity bit.

Ex: data=00110101; 4 bits set => parity bit will be 0 if even parity is selected (PS bit = 0).

Odd parity: the parity bit is calculated to obtain an odd number of “1s” inside the frame made of the 7 or 8 LSB bits (depending on whether M is equal to 0 or 1) and the parity bit.

Ex: data=00110101; 4 bits set => parity bit will be 1 if odd parity is selected (PS bit = 1).

Transmission mode: If the PCE bit is set then the MSB bit of the data written in the data register is not transmitted but is changed by the parity bit.

Reception mode: If the PCE bit is set then the interface checks if the received data byte has an

even number of “1s” if even parity is selected (PS=0) or an odd number of “1s” if odd parity is selected (PS=1). If the parity check fails, the PE flag is set in the SCISR register and an interrupt is generated if PIE is set in the SCICR1 register.

11.3.4.7 SCI Clock Tolerance

During reception, each bit is sampled 16 times. The majority of the 8th, 9th and 10th samples is considered as the bit value. For a valid bit detection, all the three samples should have the same value otherwise the noise flag (NF) is set. For example: if the 8th, 9th and 10th samples are 0, 1 and 1 respectively, then the bit value will be “1”, but the Noise Flag bit is set because the three samples values are not the same.

Consequently, the bit length must be long enough so that the 8th, 9th and 10th samples have the desired bit value. This means the clock frequency should not vary more than 6/16 (37.5%) within one bit. The sampling clock is resynchronized at each start bit, so that when receiving 10 bits (one start bit, 1 data byte, 1 stop bit), the clock deviation must not exceed 3.75%.

Note: The internal sampling clock of the microcontroller samples the pin value on every falling edge. Therefore, the internal sampling clock and the time the application expects the sampling to take place may be out of sync. For example: If the baud rate is 15.625 kbaud (bit length is 64µs), then the 8th, 9th and 10th samples will be at 28µs, 32µs & 36µs respectively (the first sample starting ideally at 0µs). But if the falling edge of the internal clock occurs just before the pin value changes, the samples would then be out of sync by ~4µs. This means the entire bit length must be at least 40µs (36µs for the 10th sample + 4µs for synchronization with the internal sampling clock).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**11.3.5 Low Power Modes**

Mode	Description
WAIT	No effect on SCI. SCI interrupts cause the device to exit from Wait mode.
HALT	SCI registers are frozen. In Halt mode, the SCI stops transmitting/receiving until Halt mode is exited.

11.3.6 Interrupts

The SCI interrupt events are connected to the same interrupt vector.

These events generate an interrupt if the corresponding Enable Control Bit is set and the inter-

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
Transmit Data Register Empty	TDRE	TIE	Yes	No
Transmission Complete	TC	TCIE	Yes	No
Received Data Ready to be Read	RDRF	RIE	Yes	No
Overrun Error Detected	OR		Yes	No
Idle Line Detected	IDLE	ILIE	Yes	No
Parity Error	PE	PIE	Yes	No

rupt mask in the CC register is reset (RIM instruction).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**11.3.7 Register Description****STATUS REGISTER (SCISR)**

Read Only

Reset Value: 1100 0000 (C0h)

7							0
TDRE	TC	RDRF	IDLE	OR	NF	FE	PE

Bit 7 = TDRE *Transmit data register empty.*

This bit is set by hardware when the content of the TDR register has been transferred into the shift register. An interrupt is generated if the TIE bit=1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a write to the SCIDR register).

0: Data is not transferred to the shift register

1: Data is transferred to the shift register

Note: Data will not be transferred to the shift register unless the TDRE bit is cleared.**Bit 6 = TC** *Transmission complete.*

This bit is set by hardware when transmission of a frame containing Data is complete. An interrupt is generated if TCIE=1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a write to the SCIDR register).

0: Transmission is not complete

1: Transmission is complete

Note: TC is not set after the transmission of a Preamble or a Break.**Bit 5 = RDRF** *Received data ready flag.*

This bit is set by hardware when the content of the RDR register has been transferred to the SCIDR register. An interrupt is generated if RIE=1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).

0: Data is not received

1: Received data is ready to be read

Bit 4 = IDLE *Idle line detect.*

This bit is set by hardware when an Idle Line is detected. An interrupt is generated if the ILIE=1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).

0: No Idle Line is detected

1: Idle Line is detected

Note: The IDLE bit will not be set again until the RDRF bit has been set itself (i.e. a new idle line occurs).**Bit 3 = OR** *Overrun error.*

This bit is set by hardware when the word currently being received in the shift register is ready to be transferred into the RDR register while RDRF=1. An interrupt is generated if RIE=1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).

0: No Overrun error

1: Overrun error is detected

Note: When this bit is set RDR register content will not be lost but the shift register will be overwritten.**Bit 2 = NF** *Noise flag.*

This bit is set by hardware when noise is detected on a received frame. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).

0: No noise is detected

1: Noise is detected

Note: This bit does not generate interrupt as it appears at the same time as the RDRF bit which itself generates an interrupt.**Bit 1 = FE** *Framing error.*

This bit is set by hardware when a de-synchronization, excessive noise or a break character is detected. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).

0: No Framing error is detected

1: Framing error or break character is detected

Note: This bit does not generate interrupt as it appears at the same time as the RDRF bit which itself generates an interrupt. If the word currently being transferred causes both frame error and overrun error, it will be transferred and only the OR bit will be set.**Bit 0 = PE** *Parity error.*

This bit is set by hardware when a parity error occurs in receiver mode. It is cleared by a software sequence (a read to the status register followed by an access to the SCIDR data register). An interrupt is generated if PIE=1 in the SCICR1 register.

0: No parity error

1: Parity error

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**CONTROL REGISTER 1 (SCICR1)**

Read/Write

Reset Value: x000 0000 (x0h)

7							0
R8	T8	SCID	M	WAKE	PCE	PS	PIE

Bit 7 = R8 *Receive data bit 8.*

This bit is used to store the 9th bit of the received word when M=1.

Bit 6 = T8 *Transmit data bit 8.*

This bit is used to store the 9th bit of the transmitted word when M=1.

Bit 5 = SCID *Disabled for low power consumption*

When this bit is set the SCI prescalers and outputs are stopped and the end of the current byte transfer in order to reduce power consumption. This bit is set and cleared by software.

0: SCI enabled

1: SCI prescaler and outputs disabled

Bit 4 = M *Word length.*

This bit determines the word length. It is set or cleared by software.

0: 1 Start bit, 8 Data bits, 1 Stop bit

1: 1 Start bit, 9 Data bits, 1 Stop bit

Note: The M bit must not be modified during a data transfer (both transmission and reception).**Bit 3 = WAKE** *Wake-Up method.*

This bit determines the SCI Wake-Up method, it is set or cleared by software.

0: Idle Line

1: Address Mark

Bit 2 = PCE *Parity control enable.*

This bit selects the hardware parity control (generation and detection). When the parity control is enabled, the computed parity is inserted at the MSB position (9th bit if M=1; 8th bit if M=0) and parity is checked on the received data. This bit is set and cleared by software. Once it is set, PCE is active after the current byte (in reception and in transmission).

0: Parity control disabled

1: Parity control enabled

Bit 1 = PS *Parity selection.*

This bit selects the odd or even parity when the parity generation/detection is enabled (PCE bit set). It is set and cleared by software. The parity will be selected after the current byte.

0: Even parity

1: Odd parity

Bit 0 = PIE *Parity interrupt enable.*

This bit enables the interrupt capability of the hardware parity control when a parity error is detected (PE bit set). It is set and cleared by software.

0: Parity error interrupt disabled

1: Parity error interrupt enabled.

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**CONTROL REGISTER 2 (SCICR2)**

Read/Write

Reset Value: 0000 0000 (00h)

7							0
TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK

Bit 7 = TIE *Transmitter interrupt enable.*

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An SCI interrupt is generated whenever TDRE=1 in the SCISR register

Bit 6 = TCIE *Transmission complete interrupt enable*

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An SCI interrupt is generated whenever TC=1 in the SCISR register

Bit 5 = RIE *Receiver interrupt enable.*

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An SCI interrupt is generated whenever OR=1 or RDRF=1 in the SCISR register

Bit 4 = ILIE *Idle line interrupt enable.*

This bit is set and cleared by software.

0: Interrupt is inhibited

1: An SCI interrupt is generated whenever IDLE=1 in the SCISR register.

Bit 3 = TE *Transmitter enable.*

This bit enables the transmitter. It is set and cleared by software.

0: Transmitter is disabled

1: Transmitter is enabled

Notes:

– During transmission, a “0” pulse on the TE bit (“0” followed by “1”) sends a preamble (idle line) after the current word.

– When TE is set there is a 1 bit-time delay before the transmission starts.

Caution: The TDO pin is free for general purpose I/O only when the TE and RE bits are both cleared (or if TE is never set).

Bit 2 = RE *Receiver enable.*

This bit enables the receiver. It is set and cleared by software.

0: Receiver is disabled

1: Receiver is enabled and begins searching for a start bit

Bit 1 = RWU *Receiver wake-up.*

This bit determines if the SCI is in mute mode or not. It is set and cleared by software and can be cleared by hardware when a wake-up sequence is recognized.

0: Receiver in Active mode

1: Receiver in Mute mode

Note: Before selecting Mute mode (setting the RWU bit), the SCI must receive some data first, otherwise it cannot function in Mute mode with wakeup by idle line detection.

Bit 0 = SBK *Send break.*

This bit set is used to send break characters. It is set and cleared by software.

0: No break character is transmitted

1: Break characters are transmitted

Note: If the SBK bit is set to “1” and then to “0”, the transmitter will send a BREAK word at the end of the current word.

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**DATA REGISTER (SCIDR)**

Read/Write

Reset Value: Undefined

Contains the Received or Transmitted data character, depending on whether it is read from or written to.

7							0
DR7	DR6	DR5	DR4	DR3	DR2	DR1	DR0

The Data register performs a double function (read and write) since it is composed of two registers, one for transmission (TDR) and one for reception (RDR).

The TDR register provides the parallel interface between the internal bus and the output shift register (see [Figure 35](#)).

The RDR register provides the parallel interface between the input shift register and the internal bus (see [Figure 35](#)).

BAUD RATE REGISTER (SCIBRR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
SCP1	SCP0	SCT2	SCT1	SCT0	SCR2	SCR1	SCR0

Bits 7:6= **SCP[1:0]** *First SCI Prescaler*

These 2 prescaling bits allow several standard clock division ranges:

PR Prescaling factor	SCP1	SCP0
1	0	0
3	0	1

PR Prescaling factor	SCP1	SCP0
4	1	0
13	1	1

Bits 5:3 = **SCT[2:0]** *SCI Transmitter rate divisor*

These 3 bits, in conjunction with the SCP1 & SCP0 bits define the total division applied to the bus clock to yield the transmit rate clock.

TR dividing factor	SCT2	SCT1	SCT0
1	0	0	0
2	0	0	1
4	0	1	0
8	0	1	1
16	1	0	0
32	1	0	1
64	1	1	0
128	1	1	1

Bits 2:0 = **SCR[2:0]** *SCI Receiver rate divisor*

These 3 bits, in conjunction with the SCP[1:0] bits define the total division applied to the bus clock to yield the receive rate clock.

RR Dividing factor	SCR2	SCR1	SCR0
1	0	0	0
2	0	0	1
4	0	1	0
8	0	1	1
16	1	0	0
32	1	0	1
64	1	1	0
128	1	1	1

Table 20. SCI Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
20	SCISR Reset Value	TDRE 1	TC 1	RDRF 0	IDLE 0	OR 0	NF 0	FE 0	PE 0
21	SCIDR Reset Value	DR7 x	DR6 x	DR5 x	DR4 x	DR3 x	DR2 x	DR1 x	DR0 x
22	SCIBRR Reset Value	SCP1 0	SCP0 0	SCT2 x	SCT1 x	SCT0 x	SCR2 x	SCR1 x	SCR0 x
23	SCICR1 Reset Value	R8 x	T8 x	SCID 0	M x	WAKE x	PCE 0	PS 0	PIE 0
24	SCICR2 Reset Value	TIE 0	TCIE 0	RIE 0	ILIE 0	TE 0	RE 0	RWU 0	SBK 0

11.4 USB INTERFACE (USB)

11.4.1 Introduction

The USB Interface implements a low-speed function interface between the USB and the ST7 microcontroller. It is a highly integrated circuit which includes the transceiver, 3.3 voltage regulator, SIE and DMA. No external components are needed apart from the external pull-up on USBDM for low speed recognition by the USB host. The use of DMA architecture allows the endpoint definition to be completely flexible. Endpoints can be configured by software as in or out.

11.4.2 Main Features

- USB Specification Version 1.1 Compliant
- Supports Low-Speed USB Protocol
- Two or Three Endpoints (including default one) depending on the device (see device feature list and register map)
- CRC generation/checking, NRZI encoding/decoding and bit-stuffing
- USB Suspend/Resume operations
- DMA Data transfers
- On-Chip 3.3V Regulator
- On-Chip USB Transceiver

11.4.3 Functional Description

The block diagram in [Figure 38](#), gives an overview of the USB interface hardware.

For general information on the USB, refer to the “Universal Serial Bus Specifications” document available at <http://www.usb.org>.

Serial Interface Engine

The SIE (Serial Interface Engine) interfaces with the USB, via the transceiver.

The SIE processes tokens, handles data transmission/reception, and handshaking as required by the USB standard. It also performs frame formatting, including CRC generation and checking.

Endpoints

The Endpoint registers indicate if the microcontroller is ready to transmit/receive, and how many bytes need to be transmitted.

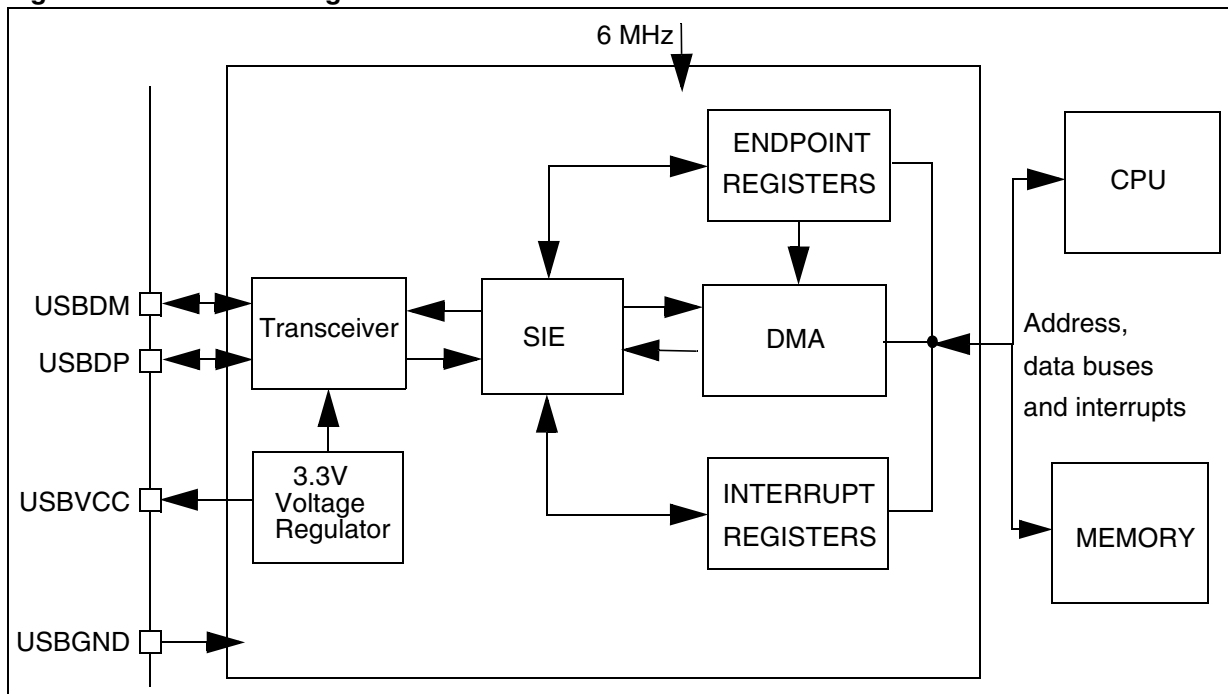
DMA

When a token for a valid Endpoint is recognized by the USB interface, the related data transfer takes place, using DMA. At the end of the transaction, an interrupt is generated.

Interrupts

By reading the Interrupt Status register, application software can know which USB event has occurred.

Figure 38. USB Block Diagram



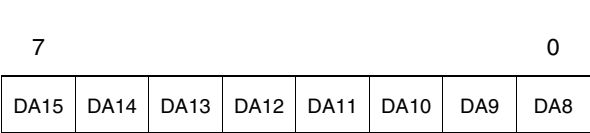
USB INTERFACE (Cont'd)

11.4.4 Register Description

DMA ADDRESS REGISTER (DMAR)

Read / Write

Reset Value: Undefined

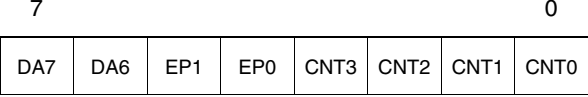


Bits 7:0=**DA[15:8]** *DMA address bits 15-8*.
Software must write the start address of the DMA memory area whose most significant bits are given by DA15-DA6. The remaining 6 address bits are set by hardware. See the description of the IDR register and [Figure 39](#).

INTERRUPT/DMA REGISTER (IDR)

Read / Write

Reset Value: xxxx 0000 (x0h)



Bits 7:6 = **DA[7:6]** *DMA address bits 7-6*.
Software must reset these bits. See the description of the DMAR register and [Figure 39](#).

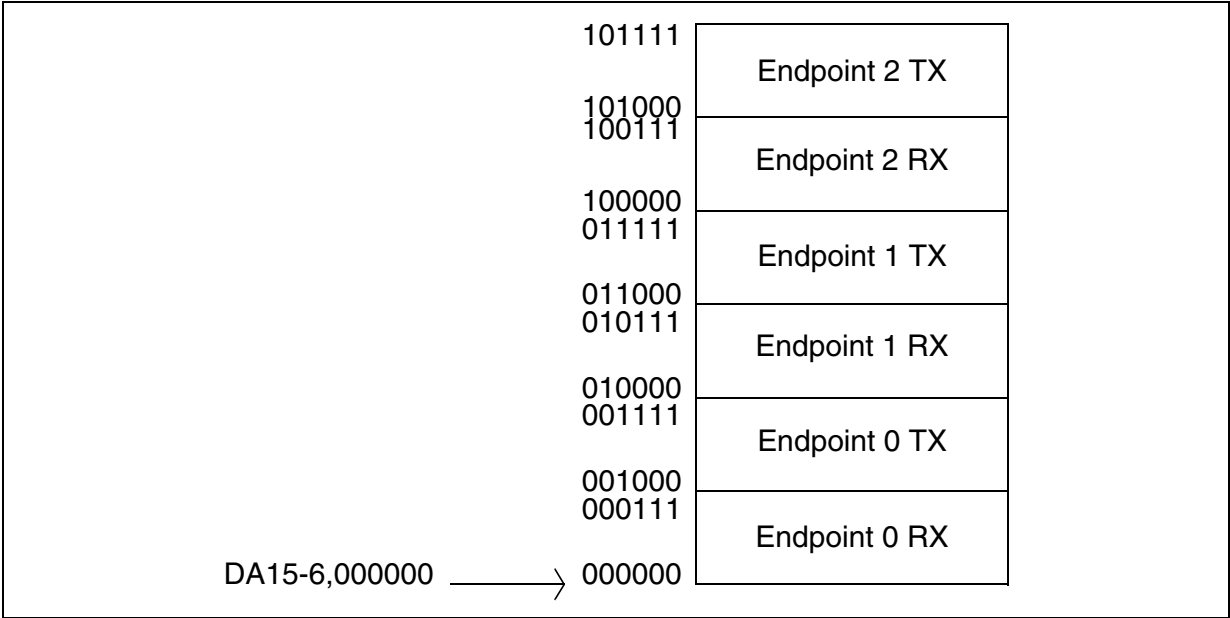
Bits 5:4 = **EP[1:0]** *Endpoint number* (read-only).
These bits identify the endpoint which required attention.
00: Endpoint 0
01: Endpoint 1
10: Endpoint 2

When a CTR interrupt occurs (see register ISTR) the software should read the EP bits to identify the endpoint which has sent or received a packet.

Bits 3:0 = **CNT[3:0]** *Byte count* (read only).
This field shows how many data bytes have been received during the last data reception.

Note: Not valid for data transmission.

Figure 39. DMA Buffers



USB INTERFACE (Cont'd)**PID REGISTER (PIDR)**

Read only

Reset Value: xx00 0000 (x0h)

7							0
TP3	TP2	0	0	0	RX_SEZ	RXD	0

Bits 7:6 = **TP[3:2]** *Token PID bits 3 & 2.*
 USB token PIDs are encoded in four bits. **TP[3:2]** correspond to the variable token PID bits 3 & 2.

Note: PID bits 1 & 0 have a fixed value of 01.
 When a CTR interrupt occurs (see register ISTR) the software should read the TP3 and TP2 bits to retrieve the PID name of the token received.
 The USB standard defines TP bits as:

TP3	TP2	PID Name
0	0	OUT
1	0	IN
1	1	SETUP

Bits 5:3 Reserved. Forced by hardware to 0.

Bit 2 = **RX_SEZ** *Received single-ended zero*
 This bit indicates the status of the RX_SEZ transceiver output.

0: No SE0 (single-ended zero) state
 1: USB lines are in SE0 (single-ended zero) state

Bit 1 = **RXD** *Received data*

0: No K-state
 1: USB lines are in K-state

This bit indicates the status of the RXD transceiver output (differential receiver output).

Note: If the environment is noisy, the RX_SEZ and RXD bits can be used to secure the application. By interpreting the status, software can distinguish a valid End Suspend event from a spurious wake-up due to noise on the external USB line. A valid End Suspend is followed by a Resume or Reset sequence. A Resume is indicated by RXD=1, a Reset is indicated by RX_SEZ=1.

Bit 0 = Reserved. Forced by hardware to 0.

INTERRUPT STATUS REGISTER (ISTR)

Read / Write

Reset Value: 0000 0000 (00h)

7							0
SUSP	DOVR	CTR	ERR	IOVR	ESUSP	RESET	SOF

When an interrupt occurs these bits are set by hardware. Software must read them to determine the interrupt type and clear them after servicing.
Note: These bits cannot be set by software.

Bit 7 = **SUSP** *Suspend mode request.*

This bit is set by hardware when a constant idle state is present on the bus line for more than 3 ms, indicating a suspend mode request from the USB bus. The suspend request check is active immediately after each USB reset event and its disabled by hardware when suspend mode is forced (FSUSP bit of CTLR register) until the end of resume sequence.

Bit 6 = **DOVR** *DMA over/underrun.*

This bit is set by hardware if the ST7 processor can't answer a DMA request in time.

0: No over/underrun detected
 1: Over/underrun detected

Bit 5 = **CTR** *Correct Transfer.* This bit is set by hardware when a correct transfer operation is performed. The type of transfer can be determined by looking at bits TP3-TP2 in register PIDR. The End-point on which the transfer was made is identified by bits EP1-EP0 in register IDR.

0: No Correct Transfer detected
 1: Correct Transfer detected

Note: A transfer where the device sent a NAK or STALL handshake is considered not correct (the host only sends ACK handshakes). A transfer is considered correct if there are no errors in the PID and CRC fields, if the DATA0/DATA1 PID is sent as expected, if there were no data overruns, bit stuffing or framing errors.

Bit 4 = **ERR** *Error.*

This bit is set by hardware whenever one of the errors listed below has occurred:

0: No error detected
 1: Timeout, CRC, bit stuffing or nonstandard framing error detected

USB INTERFACE (Cont'd)

Bit 3 = **IOVR** *Interrupt overrun.*

This bit is set when hardware tries to set ERR, or SOF before they have been cleared by software.

0: No overrun detected

1: Overrun detected

Bit 2 = **ESUSP** *End suspend mode.*

This bit is set by hardware when, during suspend mode, activity is detected that wakes the USB interface up from suspend mode.

This interrupt is serviced by a specific vector, in order to wake up the ST7 from HALT mode.

0: No End Suspend detected

1: End Suspend detected

Bit 1 = **RESET** *USB reset.*

This bit is set by hardware when the USB reset sequence is detected on the bus.

0: No USB reset signal detected

1: USB reset signal detected

Note: The DADDR, EP0RA, EP0RB, EP1RA, EP1RB, EP2RA and EP2RB registers are reset by a USB reset.

Bit 0 = **SOF** *Start of frame.*

This bit is set by hardware when a low-speed SOF indication (keep-alive strobe) is seen on the USB bus. It is also issued at the end of a resume sequence.

0: No SOF signal detected

1: SOF signal detected

Note: To avoid spurious clearing of some bits, it is recommended to clear them using a load instruction where all bits which must not be altered are set, and all bits to be cleared are reset. Avoid read-modify-write instructions like AND, XOR..

INTERRUPT MASK REGISTER (IMR)

Read / Write

Reset Value: 0000 0000 (00h)

7				0			
SUS PM	DOV RM	CTR M	ERR M	IOVR M	ESU SPM	RES ETM	SOF M

Bits 7:0 = These bits are mask bits for all interrupt condition bits included in the ISTR. Whenever one of the IMR bits is set, if the corresponding ISTR bit is set, and the I bit in the CC register is cleared, an interrupt request is generated. For an explanation

of each bit, please refer to the corresponding bit description in ISTR.

CONTROL REGISTER (CTLR)

Read / Write

Reset Value: 0000 0110 (06h)

7				0			
0	0	0	0	RESUME	PDWN	FSUSP	FRES

Bits 7:4 = Reserved. Forced by hardware to 0.

Bit 3 = **RESUME** *Resume.*

This bit is set by software to wake-up the Host when the ST7 is in suspend mode.

0: Resume signal not forced

1: Resume signal forced on the USB bus.

Software should clear this bit after the appropriate delay.

Bit 2 = **PDWN** *Power down.*

This bit is set by software to turn off the 3.3V on-chip voltage regulator that supplies the external pull-up resistor and the transceiver.

0: Voltage regulator on

1: Voltage regulator off

Note: After turning on the voltage regulator, software should allow at least 3 µs for stabilisation of the power supply before using the USB interface.

Bit 1 = **FSUSP** *Force suspend mode.*

This bit is set by software to enter Suspend mode. The ST7 should also be halted allowing at least 600 ns before issuing the HALT instruction.

0: Suspend mode inactive

1: Suspend mode active

When the hardware detects USB activity, it resets this bit (it can also be reset by software).

Bit 0 = **FRES** *Force reset.*

This bit is set by software to force a reset of the USB interface, just as if a RESET sequence came from the USB.

0: Reset not forced

1: USB interface reset forced.

The USB is held in RESET state until software clears this bit, at which point a "USB-RESET" interrupt will be generated if enabled.

USB INTERFACE (Cont'd)**DEVICE ADDRESS REGISTER (DADDR)**

Read / Write

Reset Value: 0000 0000 (00h)

7							0
0	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0

Bit 7 = Reserved. Forced by hardware to 0.

Bits 6:0 = **ADD[6:0]** *Device address, 7 bits.*

Software must write into this register the address sent by the host during enumeration.

Note: This register is also reset when a USB reset is received from the USB bus or forced through bit FRES in the CTLR register.**ENDPOINT n REGISTER A (EPnRA)**

Read / Write

Reset Value: 0000 xxxx (0xh)

7							0
ST_OUT	DTOG_TX	STAT_TX1	STAT_TX0	TBC 3	TBC 2	TBC 1	TBC 0

These registers (**EP0RA**, **EP1RA** and **EP2RA**) are used for controlling data transmission. They are also reset by the USB bus reset.**Note:** Endpoint 2 and the EP2RA register are not available on some devices (see device feature list and register map).Bit 7 = **ST_OUT** *Status out.*

This bit is set by software to indicate that a status out packet is expected: in this case, all nonzero OUT data transfers on the endpoint are STALLED instead of being ACKed. When ST_OUT is reset, OUT transactions can have any number of bytes, as needed.

Bit 6 = **DTOG_TX** *Data Toggle, for transmission transfers.*

It contains the required value of the toggle bit (0=DATA0, 1=DATA1) for the next transmitted data packet. This bit is set by hardware at the reception of a SETUP PID. DTOG_TX toggles only when the transmitter has received the ACK signal from the USB host. DTOG_TX and also DTOG_RX (see EPnRB) are normally updated by hardware, at the receipt of a relevant PID. They can be also written by software.

Bits 5:4 = **STAT_TX[1:0]** *Status bits, for transmission transfers.*

These bits contain the information about the endpoint status, which are listed below:

STAT_TX1	STAT_TX0	Meaning
0	0	DISABLED: transmission transfers cannot be executed.
0	1	STALL: the endpoint is stalled and all transmission requests result in a STALL handshake.
1	0	NAK: the endpoint is naked and all transmission requests result in a NAK handshake.
1	1	VALID: this endpoint is enabled for transmission.

These bits are written by software. Hardware sets the STAT_TX bits to NAK when a correct transfer has occurred (CTR=1) related to a IN or SETUP transaction addressed to this endpoint; this allows the software to prepare the next set of data to be transmitted.

Bits 3:0 = **TBC[3:0]** *Transmit byte count for Endpoint n.*

Before transmission, after filling the transmit buffer, software must write in the TBC field the transmit packet size expressed in bytes (in the range 0-8).

Warning: Any value outside the range 0-8 will induce undesired effects (such as continuous data transmission).

USB INTERFACE (Cont'd)**ENDPOINT n REGISTER B (EPnRB)**

Read / Write

Reset Value: 0000 xxxx (0xh)

7				0			
CTRL	DTOG_RX	STAT_RX1	STAT_RX0	EA3	EA2	EA1	EA0

These registers (**EP1RB** and **EP2RB**) are used for controlling data reception on Endpoints 1 and 2. They are also reset by the USB bus reset.

Note: Endpoint 2 and the EP2RB register are not available on some devices (see device feature list and register map).

Bit 7 = **CTRL** *Control*.
This bit should be 0.

Note: If this bit is 1, the Endpoint is a control endpoint. (Endpoint 0 is always a control Endpoint, but it is possible to have more than one control Endpoint).

Bit 6 = **DTOG_RX** *Data toggle, for reception transfers*.

It contains the expected value of the toggle bit (0=DATA0, 1=DATA1) for the next data packet. This bit is cleared by hardware in the first stage (Setup Stage) of a control transfer (SETUP transactions start always with DATA0 PID). The receiver toggles DTOG_RX only if it receives a correct data packet and the packet's data PID matches the receiver sequence bit.

Bits 5:4 = **STAT_RX [1:0]** *Status bits, for reception transfers*.

These bits contain the information about the endpoint status, which are listed below:

STAT_RX1	STAT_RX0	Meaning
0	0	DISABLED: reception transfers cannot be executed.
0	1	STALL: the endpoint is stalled and all reception requests result in a STALL handshake.

STAT_RX1	STAT_RX0	Meaning
1	0	NAK: the endpoint is naked and all reception requests result in a NAK handshake.
1	1	VALID: this endpoint is enabled for reception.

These bits are written by software. Hardware sets the STAT_RX bits to NAK when a correct transfer has occurred (CTR=1) related to an OUT or SETUP transaction addressed to this endpoint, so the software has the time to elaborate the received data before acknowledging a new transaction.

Bits 3:0 = **EA[3:0]** *Endpoint address*.

Software must write in this field the 4-bit address used to identify the transactions directed to this endpoint. Usually EP1RB contains "0001" and EP2RB contains "0010".

ENDPOINT 0 REGISTER B (EP0RB)

Read / Write

Reset Value: 1000 0000 (80h)

7				0			
1	DTOG_RX	STAT_RX1	STAT_RX0	0	0	0	0

This register is used for controlling data reception on Endpoint 0. It is also reset by the USB bus reset.

Bit 7 = Forced by hardware to 1.

Bits 6:4 = Refer to the EPnRB register for a description of these bits.

Bits 3:0 = Forced by hardware to 0.

USB INTERFACE (Cont'd)

11.4.5 Programming Considerations

The interaction between the USB interface and the application program is described below. Apart from system reset, action is always initiated by the USB interface, driven by one of the USB events associated with the Interrupt Status Register (ISTR) bits.

11.4.5.1 Initializing the Registers

At system reset, the software must initialize all registers to enable the USB interface to properly generate interrupts and DMA requests.

1. Initialize the DMAR, IDR, and IMR registers (choice of enabled interrupts, address of DMA buffers). Refer the paragraph titled initializing the DMA Buffers.
2. Initialize the EP0RA and EP0RB registers to enable accesses to address 0 and endpoint 0 to support USB enumeration. Refer to the paragraph titled Endpoint Initialization.
3. When addresses are received through this channel, update the content of the DADDR.
4. If needed, write the endpoint numbers in the EA fields in the EP1RB and EP2RB register.

11.4.5.2 Initializing DMA buffers

The DMA buffers are a contiguous zone of memory whose maximum size is 48 bytes. They can be placed anywhere in the memory space to enable the reception of messages. The 10 most significant bits of the start of this memory area are specified by bits DA15-DA6 in registers DMAR and IDR, the remaining bits are 0. The memory map is shown in [Figure 39](#).

Each buffer is filled starting from the bottom (last 3 address bits=000) up.

11.4.5.3 Endpoint Initialization

To be ready to receive:

Set STAT_RX to VALID (11b) in EP0RB to enable reception.

To be ready to transmit:

1. Write the data in the DMA transmit buffer.
2. In register EPnRA, specify the number of bytes to be transmitted in the TBC field
3. Enable the endpoint by setting the STAT_TX bits to VALID (11b) in EPnRA.

Note: Once transmission and/or reception are enabled, registers EPnRA and/or EPnRB (respec-

tively) must not be modified by software, as the hardware can change their value on the fly.

When the operation is completed, they can be accessed again to enable a new operation.

11.4.5.4 Interrupt Handling

Start of Frame (SOF)

The interrupt service routine may monitor the SOF events for a 1 ms synchronization event to the USB bus. This interrupt is generated at the end of a resume sequence and can also be used to detect this event.

USB Reset (RESET)

When this event occurs, the DADDR register is reset, and communication is disabled in all endpoint registers (the USB interface will not respond to any packet). Software is responsible for reenabling endpoint 0 within 10 ms of the end of reset. To do this, set the STAT_RX bits in the EP0RB register to VALID.

Suspend (SUSP)

The CPU is warned about the lack of bus activity for more than 3 ms, which is a suspend request. The software should set the USB interface to suspend mode and execute an ST7 HALT instruction to meet the USB-specified power constraints.

End Suspend (ESUSP)

The CPU is alerted by activity on the USB, which causes an ESUSP interrupt. The ST7 automatically terminates HALT mode.

Correct Transfer (CTR)

1. When this event occurs, the hardware automatically sets the STAT_TX or STAT_RX to NAK.

Note: Every valid endpoint is NAKED until software clears the CTR bit in the ISTR register, independently of the endpoint number addressed by the transfer which generated the CTR interrupt.

Note: If the event triggering the CTR interrupt is a SETUP transaction, both STAT_TX and STAT_RX are set to NAK.

2. Read the PIDR to obtain the token and the IDR to get the endpoint number related to the last transfer.

Note: When a CTR interrupt occurs, the TP3-TP2 bits in the PIDR register and EP1-EP0 bits in the IDR register stay unchanged until the CTR bit in the ISTR register is cleared.

3. Clear the CTR bit in the ISTR register.

USB INTERFACE (Cont'd)

Table 21. USB Register Map and Reset Values

Address (Hex.)	Register Name	7	6	5	4	3	2	1	0
25	PIDR	TP3	TP2	0	0	0	RX_SEZ	RXD	0
	Reset Value	x	x	0	0	0	0	0	0
26	DMAR	DA15	DA14	DA13	DA12	DA11	DA10	DA9	DA8
	Reset Value	x	x	x	x	x	x	x	x
27	IDR	DA7	DA6	EP1	EP0	CNT3	CNT2	CNT1	CNT0
	Reset Value	x	x	x	x	0	0	0	0
28	ISTR	SUSP	DOVR	CTR	ERR	IOVR	ESUSP	RESET	SOF
	Reset Value	0	0	0	0	0	0	0	0
29	IMR	SUSPM	DOVRM	CTRM	ERRM	IOVRM	ESUSPM	RESETM	SOFM
	Reset Value	0	0	0	0	0	0	0	0
2A	CTLR	0	0	0	0	RESUME	PDWN	FSUSP	FRES
	Reset Value	0	0	0	0	0	1	1	0
2B	DADDR	0	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0
	Reset Value	0	0	0	0	0	0	0	0
2C	EP0RA	ST_OUT	DTOG_TX	STAT_TX1	STAT_TX0	TBC3	TBC2	TBC1	TBC0
	Reset Value	0	0	0	0	x	x	x	x
2D	EP0RB	1	DTOG_RX	STAT_RX1	STAT_RX0	0	0	0	0
	Reset Value	1	0	0	0	0	0	0	0
2E	EP1RA	ST_OUT	DTOG_TX	STAT_TX1	STAT_TX0	TBC3	TBC2	TBC1	TBC0
	Reset Value	0	0	0	0	x	x	x	x
2F	EP1RB	CTRL	DTOG_RX	STAT_RX1	STAT_RX0	EA3	EA2	EA1	EA0
	Reset Value	0	0	0	0	x	x	x	x
30	EP2RA	ST_OUT	DTOG_TX	STAT_TX1	STAT_TX0	TBC3	TBC2	TBC1	TBC0
	Reset Value	0	0	0	0	x	x	x	x
31	EP2RB	CTRL	DTOG_RX	STAT_RX1	STAT_RX0	EA3	EA2	EA1	EA0
	Reset Value	0	0	0	0	x	x	x	x

12 INSTRUCTION SET

12.1 ST7 ADDRESSING MODES

The ST7 Core features 17 different addressing modes which can be classified in 7 main groups:

Addressing Mode	Example
Inherent	nop
Immediate	ld A, #55
Direct	ld A, \$55
Indexed	ld A, (\$55, X)
Indirect	ld A, ([55], X)
Relative	jrne loop
Bit operation	bset byte, #5

The ST7 Instruction set is designed to minimize the number of bytes required per instruction: To do

so, most of the addressing modes may be subdivided in two sub-modes called long and short:

- Long addressing mode is more powerful because it can use the full 64 Kbyte address space, however it uses more bytes and more CPU cycles.
- Short addressing mode is less powerful because it can generally only access page zero (0000h - 00FFh range), but the instruction size is more compact, and faster. All memory to memory instructions use short addressing modes only (CLR, CPL, NEG, BSET, BRES, BTJT, BTJF, INC, DEC, RLC, RRC, SLL, SRL, SRA, SWAP)

The ST7 Assembler optimizes the use of long and short addressing modes.

Table 22. ST7 Addressing Mode Overview

Mode			Syntax	Destination/ Source	Pointer Address (Hex.)	Pointer Size (Hex.)	Length (Bytes)
Inherent			nop				+ 0
Immediate			ld A, #55				+ 1
Short	Direct		ld A, \$10	00..FF			+ 1
Long	Direct		ld A, \$1000	0000..FFFF			+ 2
No Offset	Direct	Indexed	ld A, (X)	00..FF			+ 0 (with X register) + 1 (with Y register)
Short	Direct	Indexed	ld A, (\$10, X)	00..1FE			+ 1
Long	Direct	Indexed	ld A, (\$1000, X)	0000..FFFF			+ 2
Short	Indirect		ld A, [\$10]	00..FF	00..FF	byte	+ 2
Long	Indirect		ld A, [\$10.w]	0000..FFFF	00..FF	word	+ 2
Short	Indirect	Indexed	ld A, ([10], X)	00..1FE	00..FF	byte	+ 2
Long	Indirect	Indexed	ld A, ([10.w], X)	0000..FFFF	00..FF	word	+ 2
Relative	Direct		jrne loop	PC-128/PC+127 ¹⁾			+ 1
Relative	Indirect		jrne [\$10]	PC-128/PC+127 ¹⁾	00..FF	byte	+ 2
Bit	Direct		bset \$10, #7	00..FF			+ 1
Bit	Indirect		bset [\$10], #7	00..FF	00..FF	byte	+ 2
Bit	Direct	Relative	btjt \$10, #7, skip	00..FF			+ 2
Bit	Indirect	Relative	btjt [\$10], #7, skip	00..FF	00..FF	byte	+ 3

Note 1. At the time the instruction is executed, the Program Counter (PC) points to the instruction following JRxx.

ST7 ADDRESSING MODES (Cont'd)

12.1.1 Inherent

All Inherent instructions consist of a single byte. The opcode fully specifies all the required information for the CPU to process the operation.

Inherent Instruction	Function
NOP	No operation
TRAP	S/W Interrupt
WFI	Wait For Interrupt (Low Power Mode)
HALT	Halt Oscillator (Lowest Power Mode)
RET	Sub-routine Return
IRET	Interrupt Sub-routine Return
SIM	Set Interrupt Mask
RIM	Reset Interrupt Mask
SCF	Set Carry Flag
RCF	Reset Carry Flag
RSP	Reset Stack Pointer
LD	Load
CLR	Clear
PUSH/POP	Push/Pop to/from the stack
INC/DEC	Increment/Decrement
TNZ	Test Negative or Zero
CPL, NEG	1 or 2 Complement
MUL	Byte Multiplication
SLL, SRL, SRA, RLC, RRC	Shift and Rotate Operations
SWAP	Swap Nibbles

12.1.2 Immediate

Immediate instructions have two bytes, the first byte contains the opcode, the second byte contains the operand value.

Immediate Instruction	Function
LD	Load
CP	Compare
BCP	Bit Compare
AND, OR, XOR	Logical Operations
ADC, ADD, SUB, SBC	Arithmetic Operations

12.1.3 Direct

In Direct instructions, the operands are referenced by their memory address.

The direct addressing mode consists of two sub-modes:

Direct (short)

The address is a byte, thus requires only one byte after the opcode, but only allows 00 - FF addressing space.

Direct (long)

The address is a word, thus allowing 64 Kbyte addressing space, but requires 2 bytes after the opcode.

12.1.4 Indexed (No Offset, Short, Long)

In this mode, the operand is referenced by its memory address, which is defined by the unsigned addition of an index register (X or Y) with an offset.

The indirect addressing mode consists of three sub-modes:

Indexed (No Offset)

There is no offset, (no extra byte after the opcode), and allows 00 - FF addressing space.

Indexed (Short)

The offset is a byte, thus requires only one byte after the opcode and allows 00 - 1FE addressing space.

Indexed (long)

The offset is a word, thus allowing 64 Kbyte addressing space and requires 2 bytes after the opcode.

12.1.5 Indirect (Short, Long)

The required data byte to do the operation is found by its memory address, located in memory (pointer).

The pointer address follows the opcode. The indirect addressing mode consists of two sub-modes:

Indirect (short)

The pointer address is a byte, the pointer size is a byte, thus allowing 00 - FF addressing space, and requires 1 byte after the opcode.

Indirect (long)

The pointer address is a byte, the pointer size is a word, thus allowing 64 Kbyte addressing space, and requires 1 byte after the opcode.

ST7 ADDRESSING MODES (Cont'd)**12.1.6 Indirect Indexed (Short, Long)**

This is a combination of indirect and short indexed addressing modes. The operand is referenced by its memory address, which is defined by the unsigned addition of an index register value (X or Y) with a pointer value located in memory. The pointer address follows the opcode.

The indirect indexed addressing mode consists of two sub-modes:

Indirect Indexed (Short)

The pointer address is a byte, the pointer size is a byte, thus allowing 00 - 1FE addressing space, and requires 1 byte after the opcode.

Indirect Indexed (Long)

The pointer address is a byte, the pointer size is a word, thus allowing 64 Kbyte addressing space, and requires 1 byte after the opcode.

Table 23. Instructions Supporting Direct, Indexed, Indirect and Indirect Indexed Addressing Modes

Long and Short Instructions	Function
LD	Load
CP	Compare
AND, OR, XOR	Logical Operations
ADC, ADD, SUB, SBC	Arithmetic Addition/subtraction operations
BCP	Bit Compare

Short Instructions Only	Function
CLR	Clear
INC, DEC	Increment/Decrement
TNZ	Test Negative or Zero
CPL, NEG	1 or 2 Complement
BSET, BRES	Bit Operations
BTJT, BTJF	Bit Test and Jump Operations
SLL, SRL, SRA, RLC, RRC	Shift and Rotate Operations

SWAP	Swap Nibbles
CALL, JP	Call or Jump subroutine

12.1.7 Relative Mode (Direct, Indirect)

This addressing mode is used to modify the PC register value by adding an 8-bit signed offset to it.

Available Relative Direct/Indirect Instructions	Function
JRxx	Conditional Jump
CALLR	Call Relative

The relative addressing mode consists of two sub-modes:

Relative (Direct)

The offset follows the opcode.

Relative (Indirect)

The offset is defined in memory, of which the address follows the opcode.

12.2 INSTRUCTION GROUPS

The ST7 family devices use an Instruction Set consisting of 63 instructions. The instructions may

be subdivided into 13 main groups as illustrated in the following table:

Load and Transfer	LD	CLR						
Stack operation	PUSH	POP	RSP					
Increment/Decrement	INC	DEC						
Compare and Tests	CP	TNZ	BCP					
Logical operations	AND	OR	XOR	CPL	NEG			
Bit Operation	BSET	BRES						
Conditional Bit Test and Branch	BTJT	BTJF						
Arithmetic operations	ADC	ADD	SUB	SBC	MUL			
Shift and Rotates	SLL	SRL	SRA	RLC	RRC	SWAP	SLA	
Unconditional Jump or Call	JRA	JRT	JRF	JP	CALL	CALLR	NOP	RET
Conditional Branch	JRxx							
Interrupt management	TRAP	WFI	HALT	IRET				
Condition Code Flag modification	SIM	RIM	SCF	RCF				

Using a pre-byte

The instructions are described with one to four bytes.

In order to extend the number of available opcodes for an 8-bit CPU (256 opcodes), three different prebyte opcodes are defined. These prebytes modify the meaning of the instruction they precede.

The whole instruction becomes:

PC-2 End of previous instruction

PC-1 Prebyte

PC Opcode

PC+1 Additional word (0 to 2) according to the number of bytes required to compute the effective address

These prebytes enable instruction in Y as well as indirect addressing modes to be implemented. They precede the opcode of the instruction in X or the instruction using direct addressing mode. The prebytes are:

PDY 90 Replace an X based instruction using immediate, direct, indexed, or inherent addressing mode by a Y one.

PIX 92 Replace an instruction using direct, direct bit, or direct relative addressing mode to an instruction using the corresponding indirect addressing mode. It also changes an instruction using X indexed addressing mode to an instruction using indirect X indexed addressing mode.

PIY 91 Replace an instruction using X indirect indexed addressing mode by a Y one.

INSTRUCTION GROUPS (Cont'd)

Mnemo	Description	Function/Example	Dst	Src	H	I	N	Z	C
ADC	Add with Carry	A = A + M + C	A	M	H		N	Z	C
ADD	Addition	A = A + M	A	M	H		N	Z	C
AND	Logical And	A = A . M	A	M			N	Z	
BCP	Bit compare A, Memory	tst (A . M)	A	M			N	Z	
BRES	Bit Reset	bres Byte, #3	M						
BSET	Bit Set	bset Byte, #3	M						
BTJF	Jump if bit is false (0)	btjf Byte, #3, Jmp1	M						C
BTJT	Jump if bit is true (1)	btjt Byte, #3, Jmp1	M						C
CALL	Call subroutine								
CALLR	Call subroutine relative								
CLR	Clear		reg, M				0	1	
CP	Arithmetic Compare	tst(Reg - M)	reg	M			N	Z	C
CPL	One Complement	A = FFH-A	reg, M				N	Z	1
DEC	Decrement	dec Y	reg, M				N	Z	
HALT	Halt					0			
IRET	Interrupt routine return	Pop CC, A, X, PC			H	I	N	Z	C
INC	Increment	inc X	reg, M				N	Z	
JP	Absolute Jump	jp [TBL.w]							
JRA	Jump relative always								
JRT	Jump relative								
JRF	Never jump	jrf *							
JRIH	Jump if ext. interrupt = 1								
JRIL	Jump if ext. interrupt = 0								
JRH	Jump if H = 1	H = 1 ?							
JRNH	Jump if H = 0	H = 0 ?							
JRM	Jump if I = 1	I = 1 ?							
JRNM	Jump if I = 0	I = 0 ?							
JRMI	Jump if N = 1 (minus)	N = 1 ?							
JRPL	Jump if N = 0 (plus)	N = 0 ?							
JREQ	Jump if Z = 1 (equal)	Z = 1 ?							
JRNE	Jump if Z = 0 (not equal)	Z = 0 ?							
JRC	Jump if C = 1	C = 1 ?							
JRNC	Jump if C = 0	C = 0 ?							
JRULT	Jump if C = 1	Unsigned <							
JRUGE	Jump if C = 0	Jmp if unsigned >=							
JRUGT	Jump if (C + Z = 0)	Unsigned >							

INSTRUCTION GROUPS (Cont'd)

Mnemo	Description	Function/Example	Dst	Src	H	I	N	Z	C
JRULE	Jump if (C + Z = 1)	Unsigned <=							
LD	Load	dst <= src	reg, M	M, reg			N	Z	
MUL	Multiply	X,A = X * A	A, X, Y	X, Y, A	0				0
NEG	Negate (2's compl)	neg \$10	reg, M				N	Z	C
NOP	No Operation								
OR	OR operation	A = A + M	A	M			N	Z	
POP	Pop from the Stack	pop reg pop CC	reg CC	M M					
					H	I	N	Z	C
PUSH	Push onto the Stack	push Y	M	reg, CC					
RCF	Reset carry flag	C = 0							0
RET	Subroutine Return								
RIM	Enable Interrupts	I = 0				0			
RLC	Rotate left true C	C <= Dst <= C	reg, M				N	Z	C
RRC	Rotate right true C	C => Dst => C	reg, M				N	Z	C
RSP	Reset Stack Pointer	S = Max allowed							
SBC	Subtract with Carry	A = A - M - C	A	M			N	Z	C
SCF	Set carry flag	C = 1							1
SIM	Disable Interrupts	I = 1				1			
SLA	Shift left Arithmetic	C <= Dst <= 0	reg, M				N	Z	C
SLL	Shift left Logic	C <= Dst <= 0	reg, M				N	Z	C
SRL	Shift right Logic	0 => Dst => C	reg, M				0	Z	C
SRA	Shift right Arithmetic	Dst7 => Dst => C	reg, M				N	Z	C
SUB	Subtraction	A = A - M	A	M			N	Z	C
SWAP	SWAP nibbles	Dst[7..4] <=> Dst[3..0]	reg, M				N	Z	
TNZ	Test for Neg & Zero	tnz lbl1					N	Z	
TRAP	S/W trap	S/W interrupt				1			
WFI	Wait for Interrupt					0			
XOR	Exclusive OR	A = A XOR M	A	M			N	Z	

13 ELECTRICAL CHARACTERISTICS

13.1 PARAMETER CONDITIONS

Unless otherwise specified, all voltages are referred to V_{SS} .

13.1.1 Minimum and Maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at $T_A=25^{\circ}\text{C}$ and $T_A=T_{A\text{max}}$ (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation ($\text{mean} \pm 3\sigma$).

13.1.2 Typical values

Unless otherwise specified, typical data are based on $T_A=25^{\circ}\text{C}$, $V_{DD}=5\text{V}$. They are given only as design guidelines and are not tested.

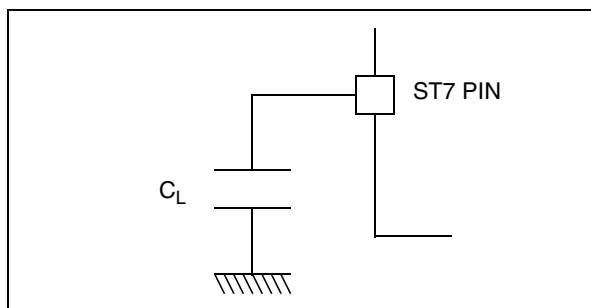
13.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

13.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in [Figure 40](#).

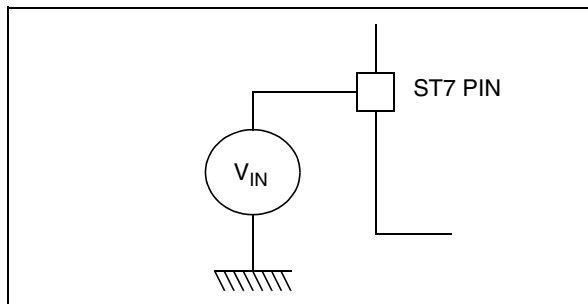
Figure 40. Pin loading conditions



13.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in [Figure 41](#).

Figure 41. Pin input voltage



13.2 ABSOLUTE MAXIMUM RATINGS

Stresses above those listed as “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these condi-

tions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.2.1 Voltage Characteristics

Symbol	Ratings	Maximum value	Unit
V _{DD} - V _{SS}	Supply voltage	6.0	V
V _{IN} ^{1) & 2)}	Input voltage on true open drain pins	V _{SS} -0.3 to 6.0	
	Input voltage on any other pin	V _{SS} -0.3 to V _{DD} +0.3	
V _{ESD(HBM)}	Electro-static discharge voltage (Human Body Model)	See “Absolute Maximum Ratings (Electrical Sensitivity)” on page 94.	

13.2.2 Current Characteristics

Symbol	Ratings	Maximum value	Unit
I_{VDD}	Total current into V_{DD} power lines (source) ³⁾	80	mA
I_{VSS}	Total current out of V_{SS} ground lines (sink) ³⁾	80	
I_{IO}	Output current sunk by any standard I/O and control pin	25	
	Output current sunk by any high sink I/O pin	50	
	Output current source by any I/Os and control pin	- 25	
$I_{INJ(PIN)}^{2)}$	Injected current on V_{PP} pin	± 5	
	Injected current on $\overline{RESET}$ pin	± 5	
	Injected current on OSCIN and OSCOUT pins	± 5	
	Injected current on any other pin ^{4) \& 5)}	± 5	
$\Sigma I_{INJ(PIN)}^{2)}$	Total injected current (sum of all I/O and control pins) ⁴⁾	± 20	
$I_{INJ(PIN)}^{2)}$	Negative injected current to PB0(10mA)/AIN0 pin	- 80	μA

Notes:

1. Directly connecting the $\overline{RESET}$ and I/O pins to V_{DD} or V_{SS} could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical: 4.7k Ω for $\overline{RESET}$, 10k Ω for I/Os). Unused I/O pins must be tied in the same way to V_{DD} or V_{SS} according to their reset configuration.

2. $I_{INJ(PIN)}$ must never be exceeded. This is implicitly insured if V_{IN} maximum is respected. If V_{IN} maximum cannot be respected, the injection current must be limited externally to the $I_{INJ(PIN)}$ value. A positive injection is induced by $V_{IN} > V_{DD}$ while a negative injection is induced by $V_{IN} < V_{SS}$. For true open-drain pads, there is no positive injection current, and the corresponding V_{IN} maximum must always be respected

3. All power (V_{DD}) and ground (V_{SS}) lines must always be connected to the external supply.

4. When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterization with $\Sigma I_{INJ(PIN)}$ maximum current injection on four I/O port pins of the device.

5. True open drain I/O port pins do not accept positive injection.

13.2.3 Thermal Characteristics

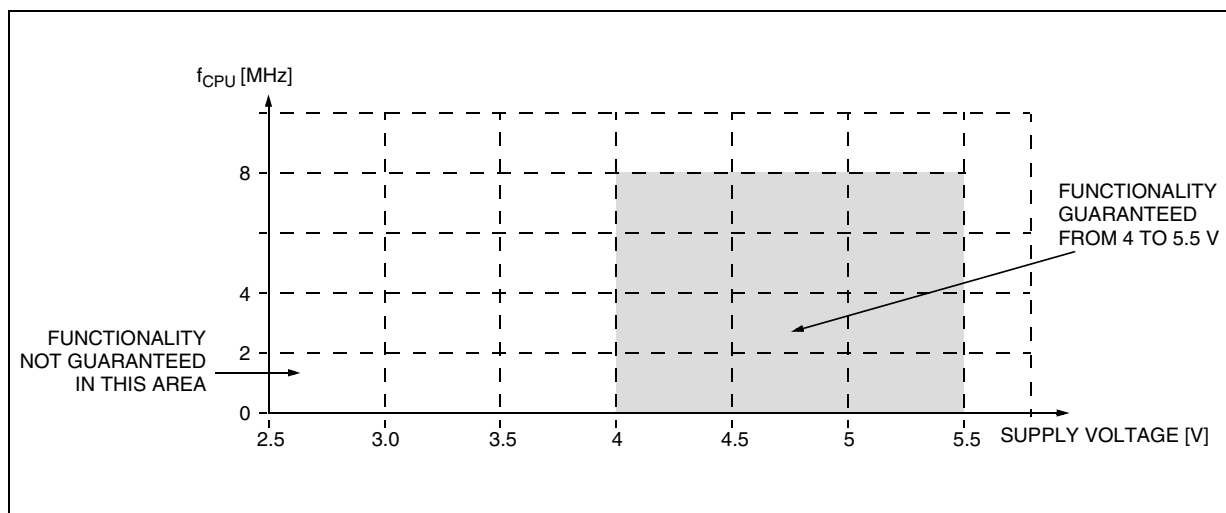
Symbol	Ratings	Value	Unit
T_{STG}	Storage temperature range	-65 to +150	$^{\circ}C$
T_J	Maximum junction temperature: See section 14.2 on page 105 for T_{Jmax}		

13.3 OPERATING CONDITIONS

13.3.1 General Operating Conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	Operating Supply Voltage	$f_{CPU} = 8 \text{ MHz}$	4	5	5.5	V
V_{DDA}	Analog supply voltage		V_{DD}		V_{DD}	
V_{SSA}	Analog supply voltage		V_{SS}		V_{SS}	
f_{CPU}	Operating frequency	$f_{OSC} = 24 \text{ MHz}$			8	MHz
		$f_{OSC} = 12 \text{ MHz}$			4	
T_A	Ambient temperature range		0		70	°C

Figure 42. f_{CPU} Maximum Operating Frequency Versus V_{DD} Supply Voltage



13.3.2 Operating Conditions with Low Voltage Detector (LVD)

Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A . Refer to [Figure 9 on page 20](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IT+}	Low Voltage Reset Threshold (V_{DD} rising)	V_{DD} Max. Variation 50V/ms	3.4	3.7	4.0	V
V_{IT-}	Low Voltage Reset Threshold (V_{DD} falling)	V_{DD} Max. Variation 50V/ms	3.2	3.5	3.8	V
V_{hyst}	Hysteresis ($V_{IT+} - V_{IT-}$) ²⁾		100	175	220	mV
V_{tPOR}	V_{DD} rise time rate ¹⁾		0.5		50	V/ms

Notes:

1. The V_{DD} rise time rate condition is needed to insure a correct device power-on and LVD reset. Not tested in production.
2. Guaranteed by characterization - not tested in production

13.4 SUPPLY CURRENT CHARACTERISTICS

The following current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To get the total device consumption, the two current values must be

added (except for HALT mode for which the clock is stopped).

Symbol	Parameter	Conditions	Typ	Max	Unit
$\Delta I_{DD}(\Delta T_a)$	Supply current variation vs. temperature	Constant V_{DD} and f_{CPU}		$10^{(3)}$	%
I_{DD}	CPU RUN mode	I/Os in input mode	$f_{CPU} = 4 \text{ MHz}$	7.5	9 ¹⁾³⁾
			$f_{CPU} = 8 \text{ MHz}$	10.5	
	CPU WAIT mode		$f_{CPU} = 4 \text{ MHz}$	6	8 ³⁾
			$f_{CPU} = 8 \text{ MHz}$	8.5	
	CPU HALT mode ²⁾	LVD disabled	25	40 ³⁾	μA
	USB Suspend mode ⁴⁾	LVD disabled	100	120	μA
		LVD enabled	230		

Notes:

1. Oscillator and watchdog running. All others peripherals disabled.
2. USB Transceiver is powered down.
3. Not tested in production, guaranteed by characterization.
4. CPU in HALT mode. Current consumption of external pull-up (1.5Kohms to USBVCC) and pull-down (15Kohms to V_{SSA}) not included.

Figure 43. Typ. I_{DD} in RUN at 4 and 8 MHz f_{CPU}

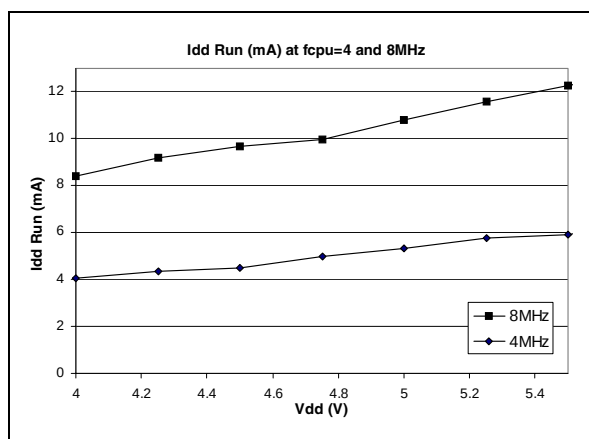
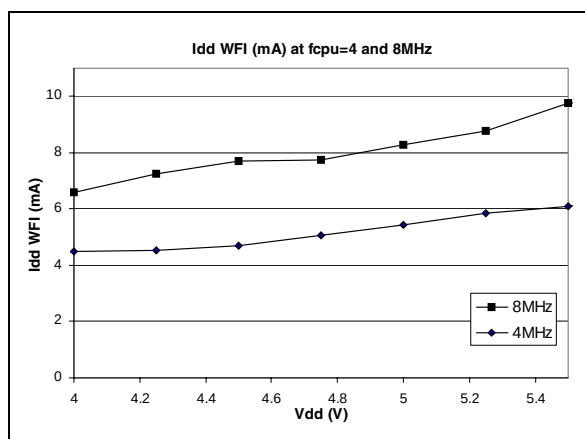


Figure 44. Typ. I_{DD} in WAIT at 4 and 8 MHz f_{CPU}



13.5 CLOCK AND TIMING CHARACTERISTICS

Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A .

13.5.1 General Timings

Symbol	Parameter	Conditions	Min	Typ ¹⁾	Max	Unit
$t_{c(INST)}$	Instruction cycle time	$f_{CPU}=8MHz$	2	3	12	t_{CPU}
			250	375	1500	ns
$t_{V(IT)}$	Interrupt reaction time ²⁾ $t_{V(IT)} = \Delta t_{c(INST)} + 10 t_{CPU}$	$f_{CPU}=8MHz$	10		22	t_{CPU}
			1.25		2.75	μs

Notes:

1. Data based on typical application software.

2. Time measured between interrupt event and interrupt vector fetch. $\Delta t_{c(INST)}$ is the number of t_{CPU} cycles needed to finish the current instruction execution.

13.5.2 CONTROL TIMING CHARACTERISTICS

CONTROL TIMINGS						
Symbol	Parameter	Conditions	Value			Unit
			Min	Typ.	Max	
f_{OSC}	Oscillator Frequency				24	MHz
f_{CPU}	Operating Frequency				8	MHz
t_{RL}	External RESET Input pulse Width		2520			ns
t_{PORL}	Internal Power Reset Duration		4096			t_{CPU}
T_{DOGL}	Watchdog or Low Voltage Reset Output Pulse Width		200	300		ns
t_{DOG}	Watchdog Time-out	$f_{cpu} = 8MHz$	49152 6.144		3145728 393.216	t_{CPU} ms
t_{OXOV}	Crystal Oscillator Start-up Time		20 ¹⁾	30	40 ¹⁾	ms
t_{DDR}	Power up rise time	from $V_{DD} = 0$ to 4V			100 ¹⁾	ms

Note:

1. Not tested in production, guaranteed by characterization.

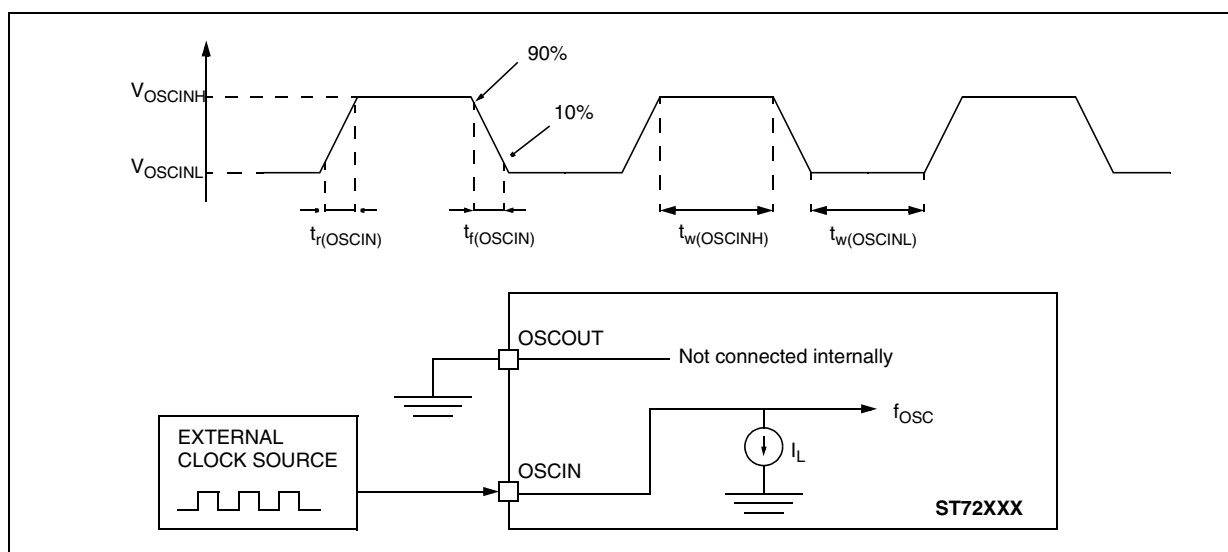
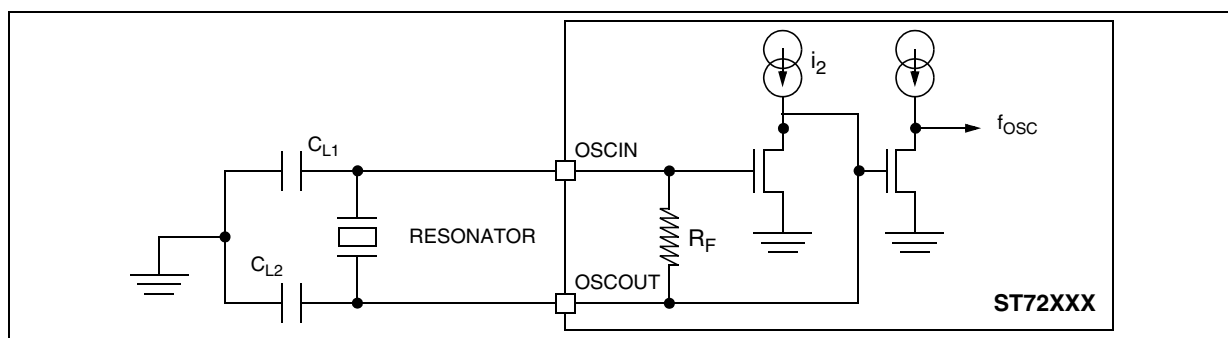
CLOCK AND TIMING CHARACTERISTICS (Cont'd)

13.5.3 External Clock Source

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OSCINH}	OSCIN input pin high level voltage	see Figure 45	$0.7 \times V_{\text{DD}}$		V_{DD}	V
V_{OSCINL}	OSCIN input pin low level voltage		V_{SS}		$0.3 \times V_{\text{DD}}$	
$t_{\text{w}}(\text{OSCINH})$ $t_{\text{w}}(\text{OSCINL})$	OSCIN high or low time ¹⁾		15			ns
$t_{\text{r}}(\text{OSCIN})$ $t_{\text{f}}(\text{OSCIN})$	OSCIN rise or fall time ¹⁾				15	
I_{L}	OSCx Input leakage current	$V_{\text{SS}} \leq V_{\text{IN}} \leq V_{\text{DD}}$			± 1	μA

Note:

1. Data based on design simulation and/or technology characteristics, not tested in production.

Figure 45. Typical Application with an External Clock Source**Figure 46. Typical Application with a Crystal Resonator**

13.6 MEMORY CHARACTERISTICS

Subject to general operating conditions for f_{CPU} , and T_{A} unless otherwise specified.

13.6.1 RAM and Hardware Registers

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RM}	Data retention mode ¹⁾	HALT mode (or RESET)	2.0			V

Note:

1. Guaranteed by design. Not tested in production.

13.6.2 Flash Memory

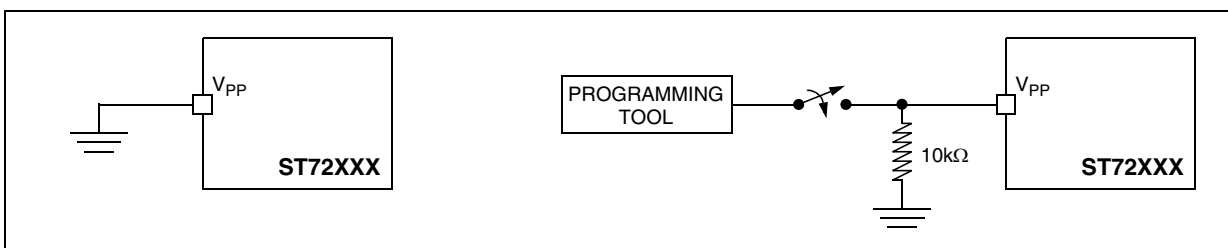
Operating Conditions: $f_{\text{CPU}} = 8 \text{ MHz}$.

DUAL VOLTAGE FLASH MEMORY ¹⁾						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{CPU}	Operating Frequency	Read mode			8	MHz
		Write / Erase mode, $T_{\text{A}}=25^{\circ}\text{C}$			8	
V_{PP}	Programming Voltage	$4.0\text{V} \leq V_{\text{DD}} \leq 5.5\text{V}$	11.4		12.6	V
I_{PP}	V_{PP} Current	Write / Erase		30		mA
t_{VPP}	Internal V_{PP} Stabilization Time			10		μs
t_{RET}	Data Retention	$T_{\text{A}} \leq 55^{\circ}\text{C}$	40			years
N_{RW}	Write Erase Cycles	$T_{\text{A}}=25^{\circ}\text{C}$	100			cycles

Note:

1. Refer to the Flash Programming Reference Manual for the typical HDFlash programming and erase timing values.

Figure 47. Two typical Applications with V_{PP} Pin¹⁾



Note:

1. When the ICP mode is not required by the application, V_{PP} pin must be tied to V_{SS} .

13.7 EMC CHARACTERISTICS

Susceptibility tests are performed on a sample basis during product characterization.

13.7.1 Functional EMS (Electro Magnetic Susceptibility)

Based on a simple running application on the product (toggling 2 LEDs through I/O ports), the product is stressed by two electro magnetic events until a failure occurs (indicated by the LEDs).

- **ESD:** Electro-Static Discharge (positive and negative) is applied on all pins of the device until a functional disturbance occurs. This test conforms with the IEC 1000-4-2 standard.
- **FTB:** A Burst of Fast Transient voltage (positive and negative) is applied to V_{DD} and V_{SS} through a 100pF capacitor, until a functional disturbance occurs. This test conforms with the IEC 1000-4-4 standard.

A device reset allows normal operations to be resumed. The test results are given in the table below based on the EMS levels and classes defined in application note AN1709.

13.7.1.1 Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical applica-

tion environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

Software recommendations:

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

Prequalification trials:

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the RESET pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behaviour is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015).

Symbol	Parameter	Conditions	Level/Class
V_{FESD}	Voltage limits to be applied on any I/O pin to induce a functional disturbance	$V_{DD}=5\text{ V}$, $T_A=+25\text{ }^{\circ}\text{C}$, $f_{OSC}=8\text{ MHz}$, conforms to IEC 1000-4-2	4B
V_{FFTB}	Fast transient voltage burst limits to be applied through 100pF on V_{DD} and V_{DD} pins to induce a functional disturbance	$V_{DD}=5\text{ V}$, $T_A=+25\text{ }^{\circ}\text{C}$, $f_{OSC}=8\text{ MHz}$, conforms to IEC 1000-4-4	4A

13.7.2 Electro Magnetic Interference (EMI)

Based on a simple application running on the product (toggling 2 LEDs through the I/O ports), the product is monitored in terms of emission. This emission test is in line with the norm SAE J 1752/3 which specifies the board and the loading of each pin.

Symbol	Parameter	Conditions	Monitored Frequency Band	Max vs. $[f_{osc}/f_{cpu}]$	Unit
				16/8 MHz	
S_{EMI}	Peak level ¹⁾	$V_{DD}=5\text{V}$, $T_A=+25^{\circ}\text{C}$, conforming to SAE J 1752/3 Note: Refer to Application Note AN1709 for data on other package types.	0.1MHz to 30MHz	36	dBμV
			30MHz to 130MHz	39	
			130MHz to 1GHz	26	
			SAE EMI Level	3.5	-

Note:

1. Data based on characterization results, not tested in production.

EMC CHARACTERISTICS (Cont'd)**13.7.3 Absolute Maximum Ratings (Electrical Sensitivity)**

Based on three different tests (ESD, LU and DLU) using specific measurement methods, the product is stressed in order to determine its performance in terms of electrical sensitivity. For more details, refer to the application note AN1181.

13.7.3.1 Electro-Static Discharge (ESD)

Electro-Static Discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts*(n+1) supply pin). This test conforms to the JESD22-A114A/A115A standard.

Absolute Maximum Ratings

Symbol	Ratings	Conditions	Maximum value ¹⁾	Unit
$V_{ESD(HBM)}$	Electro-static discharge voltage (Human Body Model)	$T_A=+25^{\circ}C$	2000	V

Note:

1. Data based on characterization results, not tested in production.

13.7.3.2 Static and Dynamic Latch-Up

■ **LU:** 3 complementary static tests are required on 10 parts to assess the latch-up performance. A supply overvoltage (applied to each power supply pin) and a current injection (applied to each input, output and configurable I/O pin) are performed on each sample. This test conforms to the EIA/JESD 78 IC latch-up standard. For more details, refer to the application note AN1181.

■ **DLU:** Electro-Static Discharges (one positive then one negative test) are applied to each pin of 3 samples when the micro is running to assess the latch-up performance in dynamic mode. Power supplies are set to the typical values, the oscillator is connected as near as possible to the pins of the micro and the component is put in reset mode. This test conforms to the IEC1000-4-2 and SAEJ1752/3 standards. For more details, refer to the application note AN1181.

Electrical Sensitivities

Symbol	Parameter	Conditions	Class ¹⁾
LU	Static latch-up class	$T_A=+25^{\circ}C$	A
DLU	Dynamic latch-up class	$V_{DD}=5.5V$, $f_{OSC}=4MHz$, $T_A=+25^{\circ}C$	A

Note:

1. Class description: A Class is an STMicroelectronics internal specification. All its limits are higher than the JEDEC specifications, that means when a device belongs to Class A it exceeds the JEDEC standard. B Class strictly covers all the JEDEC criteria (international standard).

13.8 I/O PORT PIN CHARACTERISTICS

13.8.1 General Characteristics

Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IL}	Input low level voltage				$0.3 \times V_{DD}$	V
V_{IH}	Input high level voltage		$0.7 \times V_{DD}$			
V_{IN}	Input voltage	True open drain I/O pins	V_{SS}		6.0	V
		Other I/O pins			V_{DD}	
V_{hys}	Schmitt trigger voltage hysteresis			400		mV
I_L	Input leakage current	$V_{SS} \leq V_{IN} \leq V_{DD}$			± 1	μA
I_S	Static current consumption induced by each floating input pin ¹⁾	Floating input mode		400		
R_{PU}	Weak pull-up equivalent resistor ²⁾	$V_{IN}=V_{SS}$ $V_{DD}=5\text{ V}$	50	90	120	$k\Omega$
C_{IO}	I/O pin capacitance			5		pF
$t_{f(I/O)out}$	Output high to low level fall time	$C_L=50\text{ pF}$ Between 10% and 90%		25		ns
$t_{r(I/O)out}$	Output low to high level rise time			25		
$t_{w(IT)in}$	External interrupt pulse time ³⁾		1			t_{CPU}

Notes:

- Configuration not recommended, all unused pins must be kept at a fixed voltage: using the output mode of the I/O for example or an external pull-up or pull-down resistor (see [Figure 48](#)). Static peak current value taken at a fixed V_{IN} value, based on design simulation and technology characteristics, not tested in production. This value depends on V_{DD} and temperature values.
- The R_{PU} pull-up equivalent resistor is based on a resistive transistor (corresponding I_{PU} current characteristics described in [Figure 49](#)).
- To generate an external interrupt, a minimum pulse width has to be applied on an I/O port pin configured as an external interrupt source.

Figure 48. Two typical Applications with unused I/O Pin

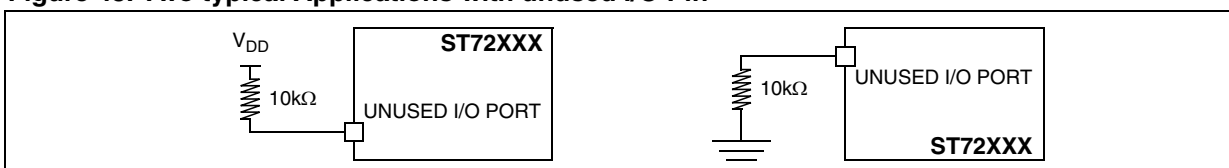


Figure 49. Typ. I_{PU} vs. V_{DD}

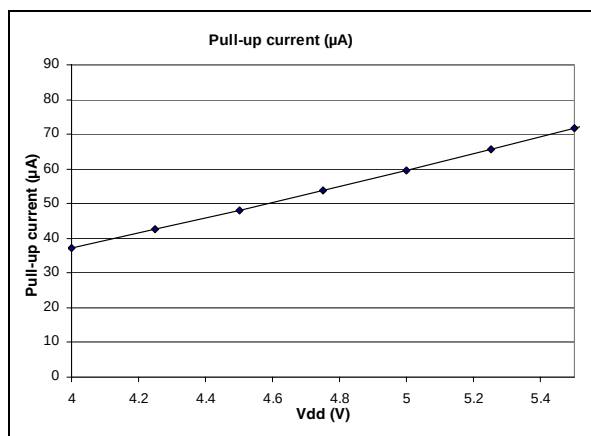
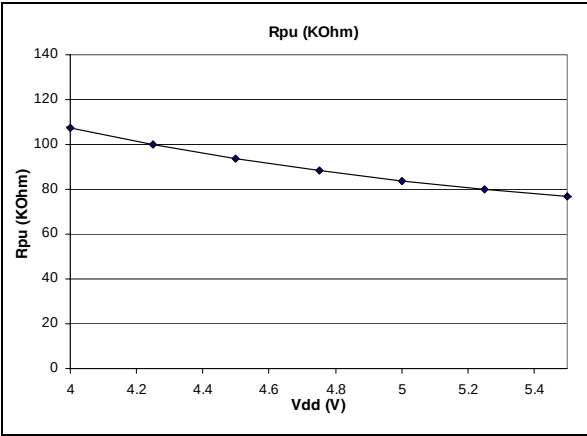


Figure 50. Typ. R_{PU} vs. V_{DD}



13.8.2 Output Driving Current

Subject to general operating condition for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{OL}^{1)}$	Output low level voltage for a standard I/O pin when up to 8 pins are sunk at the same time, Port A0, Port A(3:7), Port C(0:2)	$V_{DD}=5\text{ V}$ $I_{IO}=+1.6\text{ mA}$		0.4	V
	Output low level voltage for a high sink I/O pin when up to 4 pins are sunk at the same time, Port B(0:7)	$I_{IO}=+10\text{ mA}$		1.3	
	Output low level voltage for a very high sink I/O pin when up to 2 pins are sunk at the same time, Port A1, Port A2	$I_{IO}=+25\text{ mA}$		1.5	
$V_{OH}^{2)}$	Output high level voltage for an I/O pin when up to 8 pins are sourced at same time	$I_{IO}=-10\text{ mA}$	$V_{DD}-1.3$		
		$I_{IO}=-1.6\text{ mA}$	$V_{DD}-0.8$		

Notes:

- 1. The I_{IO} current sunk must always respect the absolute maximum rating specified in Section 13.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS} .
- 2. The I_{IO} current sourced must always respect the absolute maximum rating specified in Section 13.2 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VDD} . True open drain I/O pins does not have V_{OH} .

Figure 51. V_{OL} standard $V_{DD}=5\text{ V}$

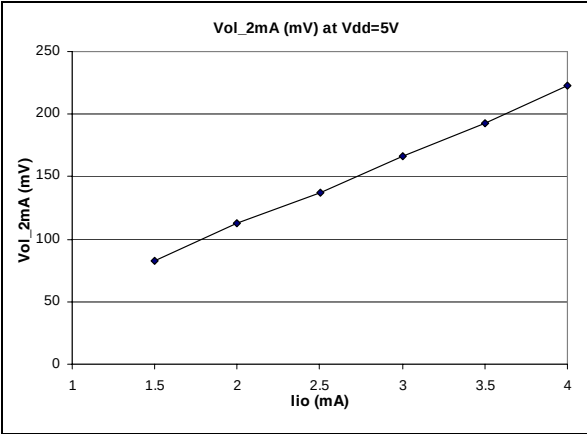


Figure 52. V_{OL} high sink $V_{DD}=5\text{ V}$

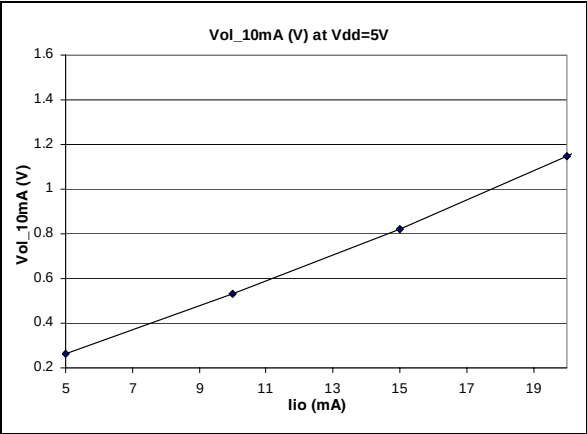


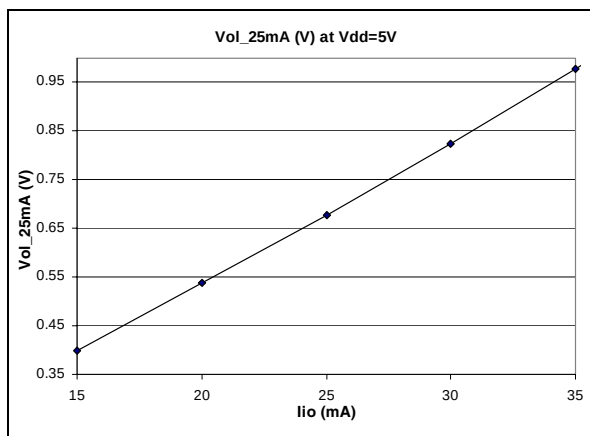
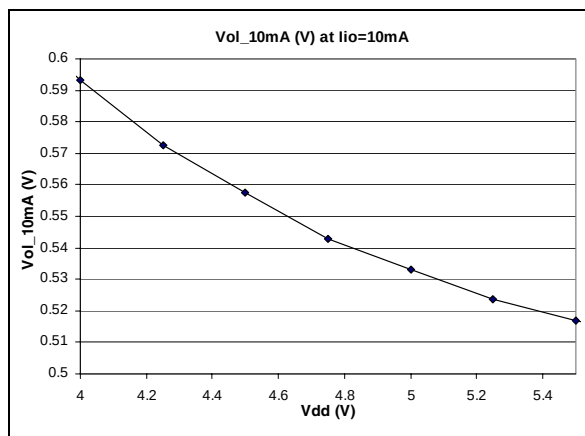
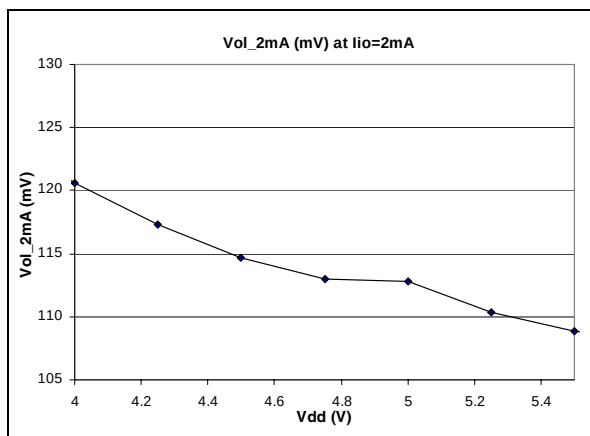
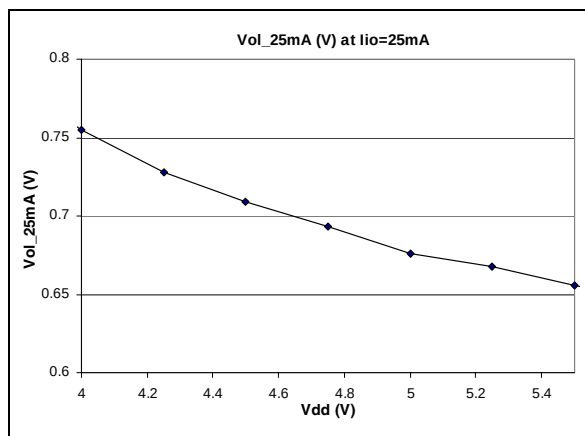
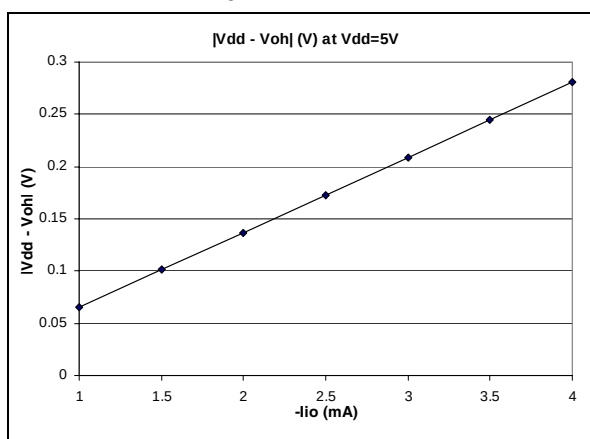
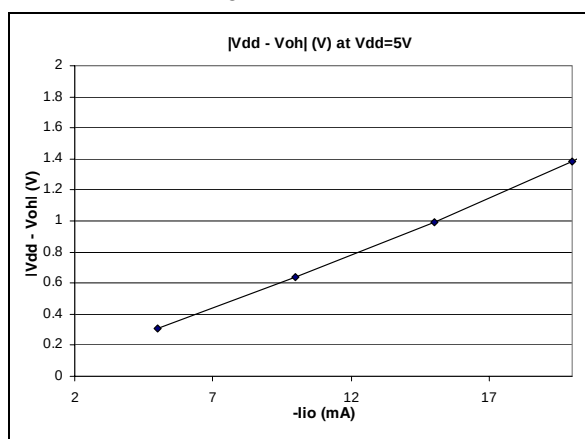
Figure 53. V_{OL} very high sink $V_{DD}=5\text{ V}$ Figure 55. V_{OL} high sink vs. V_{DD} Figure 54. V_{OL} standard vs. V_{DD} Figure 56. V_{OL} very high sink vs. V_{DD} Figure 57. $|V_{DD}-V_{OH}|$ @ $V_{DD}=5\text{ V}$ (low current)Figure 58. $|V_{DD}-V_{OH}|$ @ $V_{DD}=5\text{ V}$ (high current)

Figure 59. $|V_{DD}-V_{OH}|$ @ $I_{IO}=2\text{ mA}$ (low current)

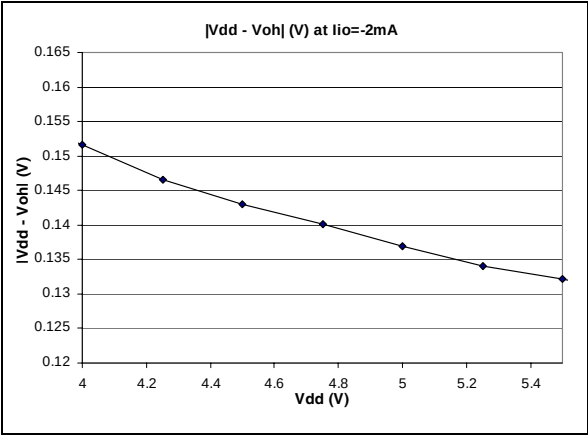
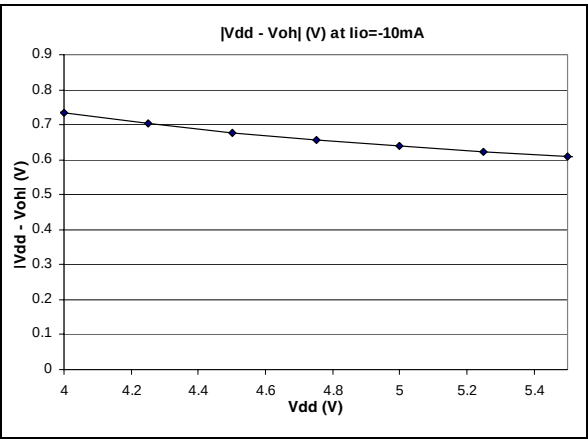


Figure 60. $|V_{DD}-V_{OH}|$ @ $I_{IO}=10\text{mA}$ (high current)



13.9 CONTROL PIN CHARACTERISTICS

13.9.1 Asynchronous $\overline{\text{RESET}}$ Pin

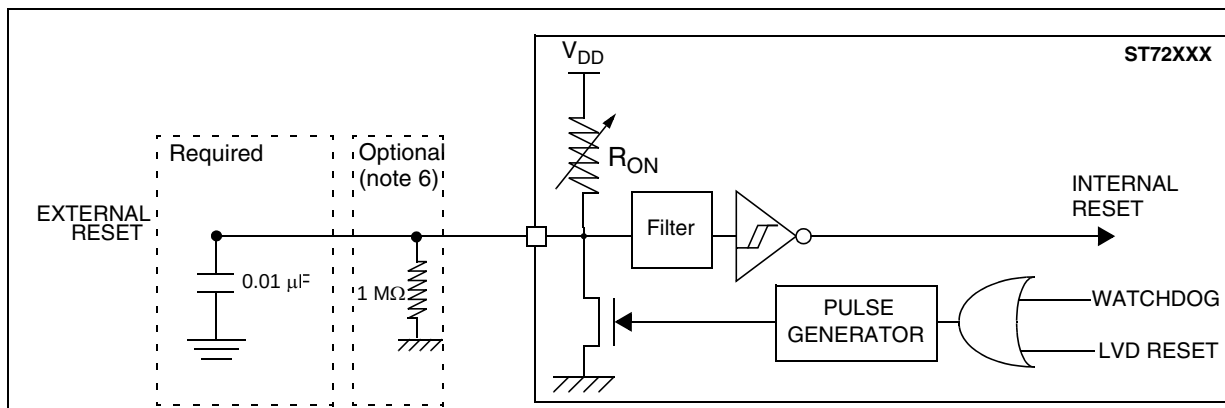
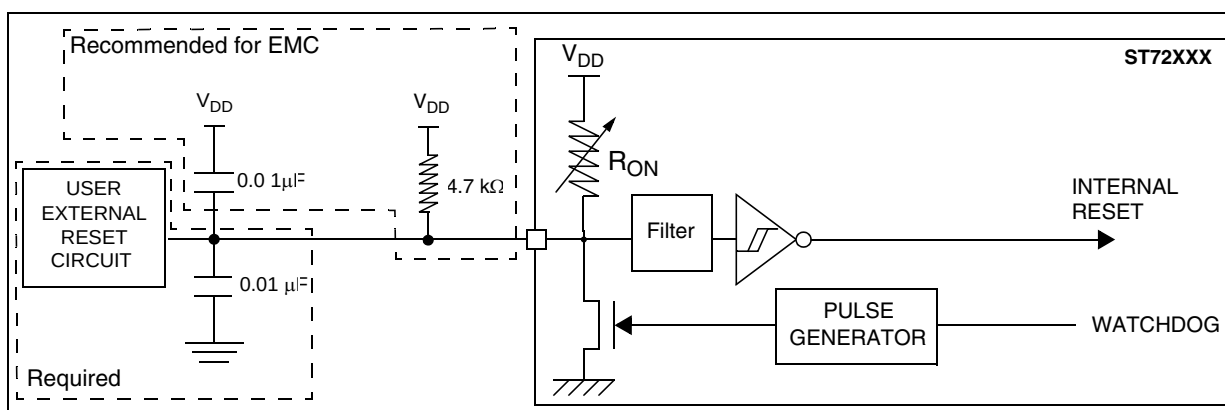
Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IH}	Input High Level Voltage			$0.7 \times V_{DD}$		V_{DD}	V
V_{IL}	Input Low Voltage			V_{SS}		$0.3 \times V_{DD}$	V
V_{hys}	Schmitt trigger voltage hysteresis ¹⁾				400		mV
V_{OL}	Output low level voltage ²⁾	$V_{DD}=5V$	$I_{IO}=5 \text{ mA}$			0.8	V
			$I_{IO}=7.5 \text{ mA}$			1.3	
R_{ON}	Weak pull-up equivalent resistor ³⁾	$V_{IN}=V_{SS}$	$V_{DD}=5 \text{ V}$	50	80	100	$k\Omega$
$t_{w(RSTL)out}$	Generated reset pulse duration	External pin or internal reset sources			6 30		$1/f_{SFOSC}$ μs
$t_{h(RSTL)in}$	External reset pulse hold time ⁴⁾			5			μs

Notes:

1. Hysteresis voltage between Schmitt trigger switching levels. Based on characterization results, not tested.
2. The I_{IO} current sunk must always respect the absolute maximum rating specified in [Section 13.2](#) and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS} .
3. The R_{ON} pull-up equivalent resistor is based on a resistive transistor. This data is based on characterization results, not tested in production.
4. To guarantee the reset of the device, a minimum pulse has to be applied to $\overline{\text{RESET}}$ pin. All short pulses applied on $\overline{\text{RESET}}$ pin with a duration below $t_{h(RSTL)in}$ can be ignored.

CONTROL PIN CHARACTERISTICS (Cont'd)

Figure 61. $\overline{\text{RESET}}$ pin protection when LVD is enabled.¹⁾²⁾³⁾⁴⁾Figure 62. $\overline{\text{RESET}}$ pin protection when LVD is disabled.¹⁾

Note 1:

- The reset network protects the device against parasitic resets.
- The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).
- Whatever the reset source is (internal or external), the user must ensure that the level on the $\overline{\text{RESET}}$ pin can go below the V_{IL} max. level specified in [section 13.9.1 on page 99](#). Otherwise the reset will not be taken into account internally.
- Because the reset circuit is designed to allow the internal RESET to be output in the $\overline{\text{RESET}}$ pin, the user must ensure that the current sunk on the RESET pin is less than the absolute maximum value specified for $I_{INJ}(\text{RESET})$ in [section 13.2.2 on page 87](#).

Note 2: When the LVD is enabled, it is recommended not to connect a pull-up resistor or capacitor. A 10nF pull-down capacitor is required to filter noise on the reset line.

Note 3: In case a capacitive power supply is used, it is recommended to connect a 1 MΩ pull-down resistor to the $\overline{\text{RESET}}$ pin to discharge any residual voltage induced by the capacitive effect of the power supply (this will add 5µA to the power consumption of the MCU).

Note 4: Tips when using the LVD:

- 1. Check that all recommendations related to ICCCLK and reset circuit have been applied (see notes above).
- 2. Check that the power supply is properly decoupled (100 nF + 10 µF close to the MCU). Refer to AN1709 and AN2017. If this cannot be done, it is recommended to put a 100 nF + 1MΩ pull-down on the RESET pin.
- 3. The capacitors connected on the RESET pin and also the power supply are key to avoid any start-up marginality. In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: replace 10 nF pull-down on the RESET pin with a 5 µF to 20 µF capacitor."

13.10 COMMUNICATION INTERFACE CHARACTERISTICS

13.10.1 USB - Universal Bus Interface

(Operating conditions $T_A = 0$ to $+70^\circ\text{C}$, $V_{DD} = 4.0$ to 5.25V unless otherwise specified)

USB DC Electrical Characteristics					
Symbol	Parameter	Conditions	Min.	Max.	Unit
VDI	Differential Input Sensitivity	$I(D+, D-)$	0.2		$V^{(2)}$
VCM	Differential Common Mode Range	Includes VDI range	0.8	2.5	
VSE	Single Ended Receiver Threshold		0.8	2.0	
VOL	Static Output Low	$R_L^{(1)}$ of 1.5 Kohms to 3.6v		0.3	
VOH	Static Output High	$R_L^{(1)}$ of 15 Kohms to V_{SS}	2.8	3.6	
USBV	USBVCC: voltage level ³⁾	$V_{DD}=5\text{ V}$	3.00	3.60	

Notes:

1. R_L is the load connected on the USB drivers.
2. All the voltages are measured from the local ground potential.
3. To improve EMC performance (noise immunity), it is recommended to connect a 100nF capacitor to the USBVCC pin.

Figure 63. USB: Data Signal Rise and Fall Time

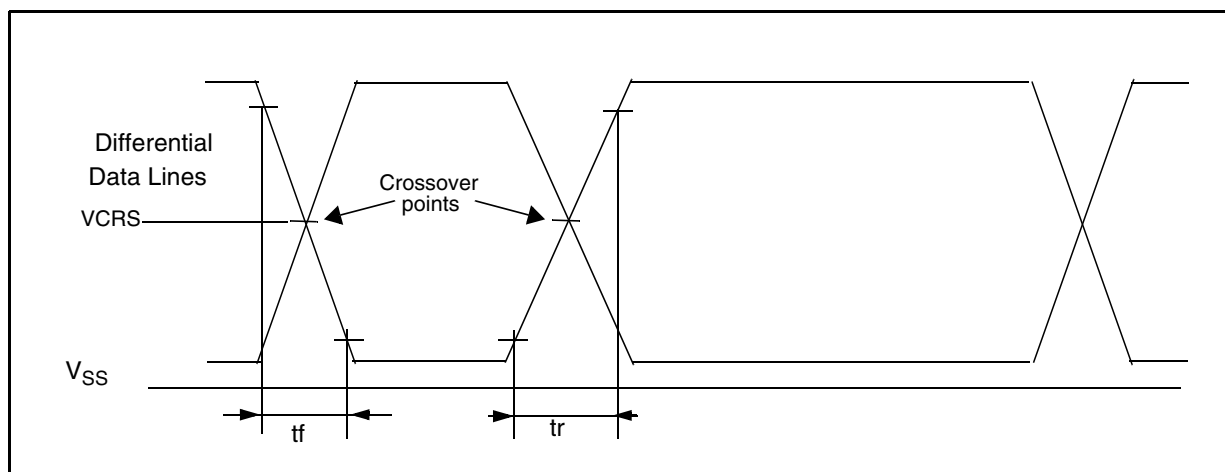


Table 24. USB: Low-speed Electrical Characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
	Driver characteristics:				
t_r	Rise time	$CL=50\text{ pF}^{(1)}$	75		ns
		$CL=600\text{ pF}^{(1)}$		300	ns
t_f	Fall Time	$CL=50\text{ pF}^{(1)}$	75		ns
		$CL=600\text{ pF}^{(1)}$		300	ns
trfm	Rise/ Fall Time matching	t_r/t_f	80	120	%
VCRS	Output signal Crossover Voltage		1.3	2.0	V

Note:

1. For more detailed information, please refer to Chapter 7 (Electrical) of the USB specification (version 1.1).

COMMUNICATION INTERFACE CHARACTERISTICS (Cont'd)**13.10.2 SCI - Serial Communications Interface**

Subject to general operating condition for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Refer to I/O port characteristics for more details on the input/output alternate function characteristics (RDI and TDO).

Symbol	Parameter	Conditions			Standard	Baud Rate	Unit
		f_{CPU}	Accuracy vs. Standard	Prescaler			
f_{Tx} f_{Rx}	Communication frequency	8 MHz	~0.16%	Conventional Mode TR (or RR)=128, PR=13 TR (or RR)= 32, PR=13 TR (or RR)= 16, PR=13 TR (or RR)= 8, PR=13 TR (or RR)= 4, PR=13 TR (or RR)= 16, PR= 3 TR (or RR)= 2, PR=13 TR (or RR)= 1, PR=13	300 1200 2400 4800 9600 10400 19200 38400	~300.48 ~1201.92 ~2403.84 ~4807.69 ~9615.38 ~10416.67 ~19230.77 ~38461.54	Hz

14 PACKAGE CHARACTERISTICS

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard

JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

14.1 PACKAGE MECHANICAL DATA

Figure 64. 24-Pin Plastic Small Outline Package, 300-mil Width

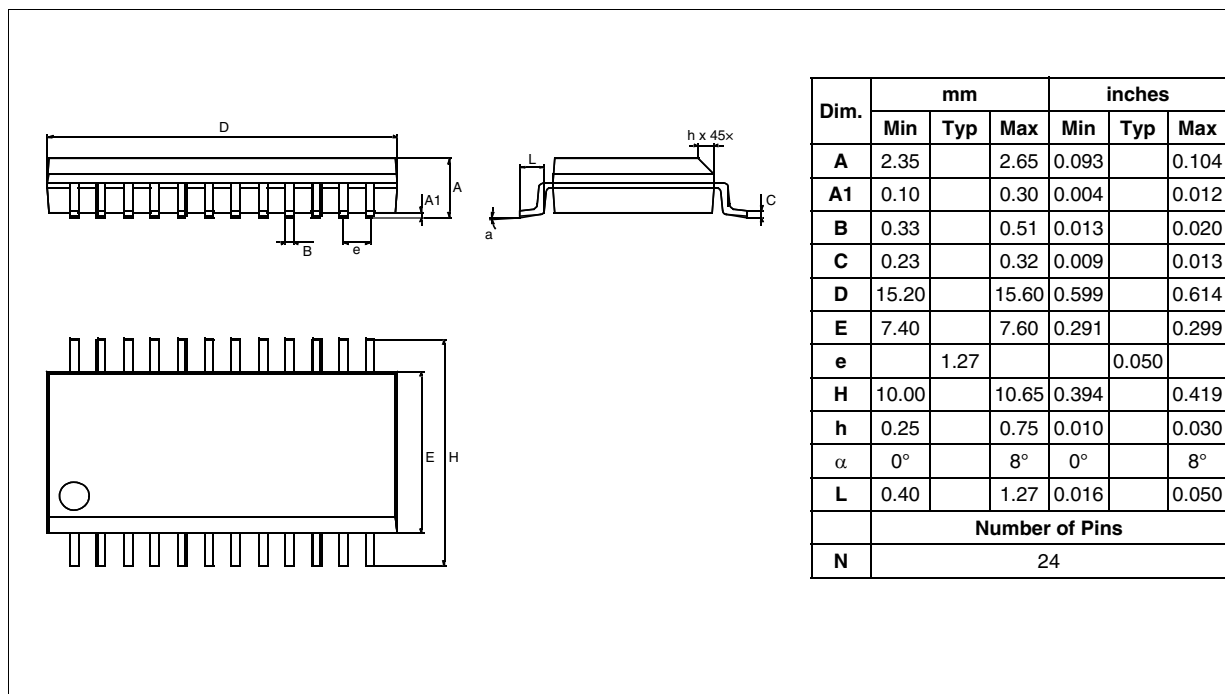
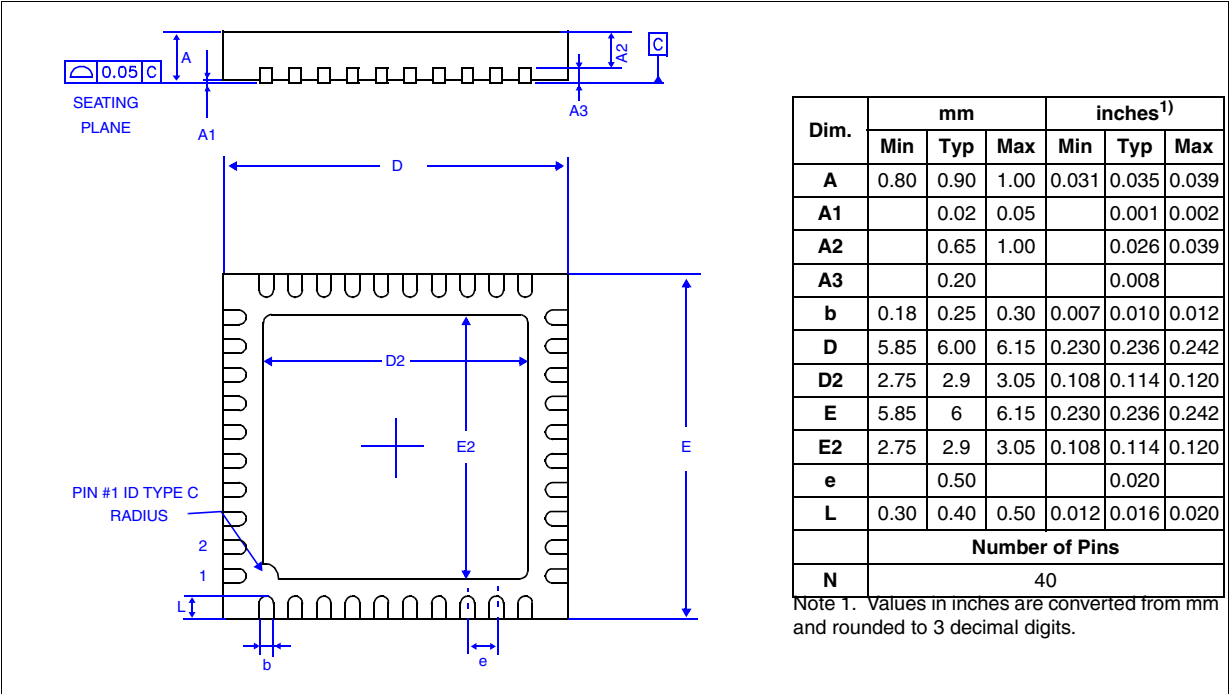


Figure 65. 40-Lead Very thin Fine pitch Quad Flat No-Lead Package



14.2 THERMAL CHARACTERISTICS

Symbol	Ratings	Value	Unit
R_{thJA}	Package thermal resistance (junction to ambient)		
	SO24 QFN40	70 34	°C/W
P_D	Power dissipation ¹⁾	500	mW
T_{Jmax}	Maximum junction temperature ²⁾	150	°C

Notes:

1. The power dissipation is obtained from the formula $P_D = P_{INT} + P_{PORT}$ where P_{INT} is the chip internal power ($I_{DD} \times V_{DD}$) and P_{PORT} is the port power dissipation determined by the user.

2. The average chip-junction temperature can be obtained from the formula $T_J = T_A + P_D \times R_{thJA}$.

14.3 SOLDERING AND GLUEABILITY INFORMATION

Recommended soldering information given only as design guidelines in [Figure 66](#) and [Figure 67](#).

Recommended glue for SMD plastic packages dedicated to molding compound with silicone:

- Heraeus: PD945, PD955
- Loctite: 3615, 3298

Figure 66. Recommended Wave Soldering Profile (with 37% Sn and 63% Pb)

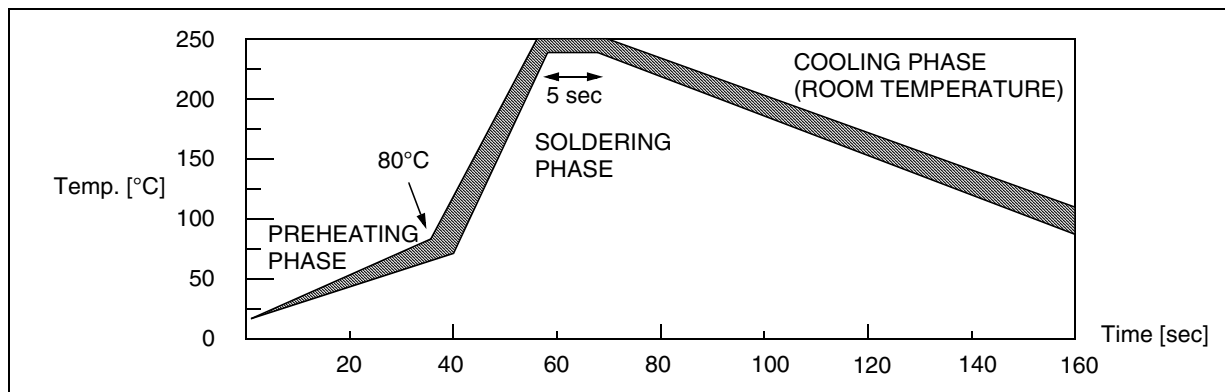
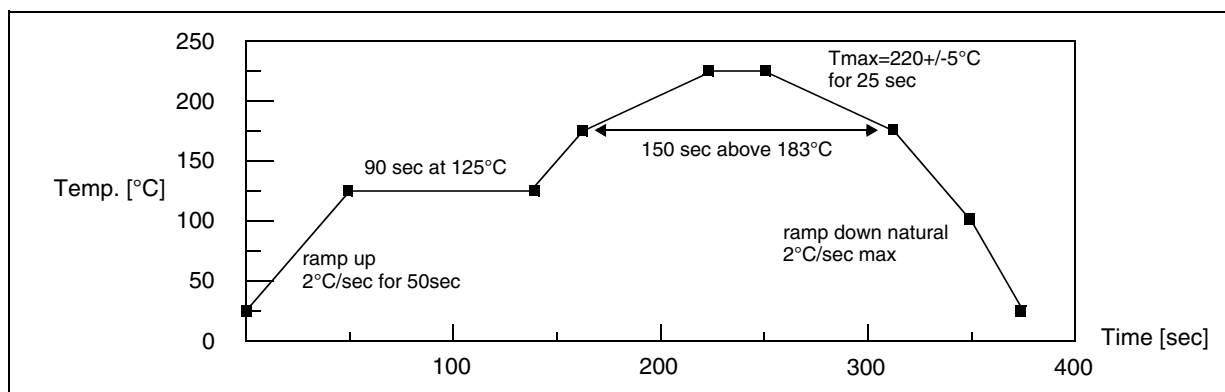


Figure 67. Recommended Reflow Soldering Oven Profile (MID JEDEC)



15 DEVICE CONFIGURATION AND ORDERING INFORMATION

Each device is available for production in user programmable versions (High Density FLASH) as well as in factory coded versions (FASTROM).

ST72P60 devices are Factory Advanced Service Technique ROM (FASTROM) versions: they are factory programmed FLASH devices.

ST72F60 FLASH devices are shipped to customers with a default content (FFh).

This implies that FLASH devices have to be configured by the customer using the Option Byte while the ROM devices are factory-configured.

15.1 OPTION BYTE

The Option Byte allows the hardware configuration of the microcontroller to be selected.

The Option Byte has no address in the memory map and can be accessed only in programming mode using a standard ST7 programming tool. The default contents of the FLASH is fixed to F7h. This means that all the options have "1" as their default value, except LVD.

In ROM devices, the Option Byte is fixed in hardware by the ROM code.

OPTION BYTE

7				0			
--	--	WDG SW	WD HALT	LVD	--	OSC 24/12	FMP_ R

OPT 7:6 = Reserved.

OPT 5 = **WDGSW** *Hardware or Software Watchdog*

This option bit selects the watchdog type.

0: Hardware enabled

1: Software enabled

OPT 4 = **WDHALT** *Watchdog and HALT mode*

This option bit determines if a RESET is generated

when entering HALT mode while the Watchdog is active.

0: No Reset generation when entering Halt mode

1: Reset generation when entering Halt mode

OPT 3 = **LVD** *Low Voltage Detector selection*

This option bit selects the LVD.

0: LVD enabled

1: LVD disabled

Important note: on ROM devices this option bit is forced by ST to 0 (LVD always enabled):

OPT 2 = Reserved.

OPT 1 = **OSC24/12** *Oscillator Selection*

This option bit selects the clock divider used to drive the USB interface at 6MHz.

0: 24 MHz oscillator

1: 12 Mhz oscillator

OPT 0 = **FMP_R** *Flash memory read-out protection*

This option indicates if the user flash memory is protected against read-out. Read-out protection, when selected, provides a protection against Program Memory content extraction and against write access to Flash memory. Erasing the option bytes when the FMP_R option is selected, causes the whole user memory to be erased first and the device can be reprogrammed. Refer to the ST7 Flash Programming Reference Manual and [section 4.3.1 on page 14](#) for more details.

0: Read-out protection enabled

1: Read-out protection disabled

15.2 DEVICE ORDERING INFORMATION AND TRANSFER OF CUSTOMER CODE

Customer code is made up of the FASTROM contents and the list of the selected options (if any). The FASTROM contents are to be sent on diskette, or by electronic means, with the hexadecimal file in .S19 format generated by the development tool. All unused bytes must be set to FFh.

The selected options are communicated to STMicroelectronics using the correctly completed OPTION LIST appended. See [page 110](#).

Refer to application note AN1635 for information on the counter listing returned by ST after code has been transferred.

The STMicroelectronics Sales Organization will be pleased to provide detailed information on contractual points.

Table 25. Supported Part Numbers

Sales Type ¹⁾	Program Memory (bytes)	RAM (bytes)	Package
ST72F60K2U1	8 K Flash	384	QFN40
ST72F60E2M1		384	SO24
ST72F60K1U1	4 K Flash	384	QFN40
ST72F60E1M1		384	SO24
ST7260K2U1/xxx	8 K ROM	384	QFN40
ST7260E2M1/xxx		384	SO24
ST7260K1U1/xxx	4 K ROM	384	QFN40
ST7260E1M1/xxx		384	SO24
ST72P60K2U1	8 K FASTROM	384	QFN40
ST72P60E2M1		384	SO24
ST72P60K1U1	4 K FASTROM	384	QFN40
ST72P60E1M1		384	SO24

Note:

☐ Contact ST sales office for product availability

1. /xxx stands for the ROM code name assigned by STMicroelectronics

15.3 DEVELOPMENT TOOLS

STMicroelectronics offers a range of hardware and software development tools for the ST7 microcontroller family. Full details of tools available for the ST7 from third party manufacturers can be obtained from the STMicroelectronics Internet site:

➡ <http://www.st.com>.

Tools from these manufacturers include C compilers, emulators and gang programmers.

STMicroelectronics Tools

Three types of development tool are offered by ST see [Table 26](#) and [Table 27](#) for more details.

Table 26. STMicroelectronics Tools Features

	In-Circuit Emulation	Programming Capability ¹⁾	Software Included
ST7 Emulator	Yes, powerful emulation features including trace/logic analyzer	No	ST7 CD ROM with: – ST7 Assembly toolchain – STVD7 powerful Source Level Debugger for Win 3.1, Win 9x and NT
ST7 Programming Board	No	Yes (All packages)	– C compiler demo versions – Windows Programming Tools for Win 3.1, Win 9x and NT

Note:

1. In-Circuit Programming (ICP) interface for FLASH devices.

Table 27. Dedicated STMicroelectronics Development Tools

Supported Products	Evaluation Board	ST7 Emulator	ST7 Programming Board
ST7260	ST7MDTULS-EVAL	ST7MDTU3-EMU3	ST7MDTU3-EPB ¹⁾

Note:

1. Add Suffix /EU or /US for the power supply for your region.

ST7260 MICROCONTROLLER OPTION LIST

(Last update: Oct 2006)

Customer:
 Address:
 Contact:
 Phone No:
 Reference:

ROM or FASTROM code must be sent in .S19 format.

Hex extension cannot be processed.

STMicroelectronics references:

Device Type/Memory Size/Package (check only one option):

ROM DEVICE:	4K	8K
SO24:	☐ ST7260E1M1	☐ ST7260E2M1
QFN40:	☐ ST7260K1U1	☐ ST7260K2U1
FASTROM:	4K	8K
SO24:	☐ ST72P60E1M1	☐ ST72P60E2M1
QFN40:	☐ ST72P60K1U1	☐ ST72P60K2U1
DIE FORM:	4K	8K
24-pin:	☐ (as E1M1)	☐ (as E2M1)
40-pin:	☐ (as K1U1)	☐ (as K2U1)

Conditioning (check only one option):

Packaged Product	Die Product (ROM only. Dice tested at 25°C only)
☐ Tape & Reel (SO package only)	☐ Tape & Reel
☐ Tube	☐ Inked wafer
	☐ Sawn wafer on sticky foil

Special Marking (ROM only): ☐ No ☐ Yes " _ _ _ _ _ _ _ _ _ _ _ _ _ _ _ _ "

Authorized characters are letters, digits, '.', '-', '/' and spaces only.

For marking, one line is possible with a maximum of 13 characters.

Watchdog Selection: ☐ Software activation ☐ Hardware activation
 Halt when Watchdog on: ☐ Reset ☐ No reset
 LVD Reset * ☐ Disabled* ☐ Enabled*

* LVD is forced to 0 (LVD always enabled) on ROM devices

Oscillator Selection: ☐ 24 MHz. ☐ 12 MHz.
 Readout Protection: ☐ Disabled ☐ Enabled

Date

Signature

Please download the latest version of this option list from:

<http://www.st.com/mcu> > downloads > ST7 microcontrollers > Option list

15.4 ST7 APPLICATION NOTES

Table 28. ST7 Application Notes

IDENTIFICATION	DESCRIPTION
APPLICATION EXAMPLES	
AN1658	SERIAL NUMBERING IMPLEMENTATION
AN1720	MANAGING THE READ-OUT PROTECTION IN FLASH MICROCONTROLLERS
AN1755	A HIGH RESOLUTION/PRECISION THERMOMETER USING ST7 AND NE555
AN1756	CHOOSING A DALI IMPLEMENTATION STRATEGY WITH ST7DALI
AN1812	A HIGH PRECISION, LOW COST, SINGLE SUPPLY ADC FOR POSITIVE AND NEGATIVE INPUT VOLTAGES
EXAMPLE DRIVERS	
AN 969	SCI COMMUNICATION BETWEEN ST7 AND PC
AN 970	SPI COMMUNICATION BETWEEN ST7 AND EEPROM
AN 971	I ² C COMMUNICATION BETWEEN ST7 AND M24CXX EEPROM
AN 972	ST7 SOFTWARE SPI MASTER COMMUNICATION
AN 973	SCI SOFTWARE COMMUNICATION WITH A PC USING ST72251 16-BIT TIMER
AN 974	REAL TIME CLOCK WITH ST7 TIMER OUTPUT COMPARE
AN 976	DRIVING A BUZZER THROUGH ST7 TIMER PWM FUNCTION
AN 979	DRIVING AN ANALOG KEYBOARD WITH THE ST7 ADC
AN 980	ST7 KEYPAD DECODING TECHNIQUES, IMPLEMENTING WAKE-UP ON KEYSTROKE
AN1017	USING THE ST7 UNIVERSAL SERIAL BUS MICROCONTROLLER
AN1041	USING ST7 PWM SIGNAL TO GENERATE ANALOG OUTPUT (SINUSOID)
AN1042	ST7 ROUTINE FOR I ² C SLAVE MODE MANAGEMENT
AN1044	MULTIPLE INTERRUPT SOURCES MANAGEMENT FOR ST7 MCUS
AN1045	ST7 S/W IMPLEMENTATION OF I ² C BUS MASTER
AN1046	UART EMULATION SOFTWARE
AN1047	MANAGING RECEPTION ERRORS WITH THE ST7 SCI PERIPHERALS
AN1048	ST7 SOFTWARE LCD DRIVER
AN1078	PWM DUTY CYCLE SWITCH IMPLEMENTING TRUE 0% & 100% DUTY CYCLE
AN1082	DESCRIPTION OF THE ST72141 MOTOR CONTROL PERIPHERALS REGISTERS
AN1083	ST72141 BLDC MOTOR CONTROL SOFTWARE AND FLOWCHART EXAMPLE
AN1105	ST7 PCAN PERIPHERAL DRIVER
AN1129	PWM MANAGEMENT FOR BLDC MOTOR DRIVES USING THE ST72141
AN1130	AN INTRODUCTION TO SENSORLESS BRUSHLESS DC MOTOR DRIVE APPLICATIONS WITH THE ST72141
AN1148	USING THE ST7263 FOR DESIGNING A USB MOUSE
AN1149	HANDLING SUSPEND MODE ON A USB MOUSE
AN1180	USING THE ST7263 KIT TO IMPLEMENT A USB GAME PAD
AN1276	BLDC MOTOR START ROUTINE FOR THE ST72141 MICROCONTROLLER
AN1321	USING THE ST72141 MOTOR CONTROL MCU IN SENSOR MODE
AN1325	USING THE ST7 USB LOW-SPEED FIRMWARE V4.X
AN1445	EMULATED 16-BIT SLAVE SPI
AN1475	DEVELOPING AN ST7265X MASS STORAGE APPLICATION
AN1504	STARTING A PWM SIGNAL DIRECTLY AT HIGH LEVEL USING THE ST7 16-BIT TIMER
AN1602	16-BIT TIMING OPERATIONS USING ST7262 OR ST7263B ST7 USB MCUS
AN1633	DEVICE FIRMWARE UPGRADE (DFU) IMPLEMENTATION IN ST7 NON-USB APPLICATIONS
AN1712	GENERATING A HIGH RESOLUTION SINEWAVE USING ST7 PWMART
AN1713	SMBUS SLAVE DRIVER FOR ST7 I ² C PERIPHERALS
AN1753	SOFTWARE UART USING 12-BIT ART

Table 28. ST7 Application Notes

IDENTIFICATION	DESCRIPTION
AN1947	ST7MC PMAC SINE WAVE MOTOR CONTROL SOFTWARE LIBRARY
GENERAL PURPOSE	
AN1476	LOW COST POWER SUPPLY FOR HOME APPLIANCES
AN1526	ST7FLITE0 QUICK REFERENCE NOTE
AN1709	EMC DESIGN FOR ST MICROCONTROLLERS
AN1752	ST72324 QUICK REFERENCE NOTE
PRODUCT EVALUATION	
AN 910	PERFORMANCE BENCHMARKING
AN 990	ST7 BENEFITS VS INDUSTRY STANDARD
AN1077	OVERVIEW OF ENHANCED CAN CONTROLLERS FOR ST7 AND ST9 MCUS
AN1086	U435 CAN-DO SOLUTIONS FOR CAR MULTIPLEXING
AN1103	IMPROVED B-EMF DETECTION FOR LOW SPEED, LOW VOLTAGE WITH ST72141
AN1150	BENCHMARK ST72 VS PC16
AN1151	PERFORMANCE COMPARISON BETWEEN ST72254 & PC16F876
AN1278	LIN (LOCAL INTERCONNECT NETWORK) SOLUTIONS
PRODUCT MIGRATION	
AN1131	MIGRATING APPLICATIONS FROM ST72511/311/214/124 TO ST72521/321/324
AN1322	MIGRATING AN APPLICATION FROM ST7263 REV.B TO ST7263B
AN1365	GUIDELINES FOR MIGRATING ST72C254 APPLICATIONS TO ST72F264
AN1604	HOW TO USE ST7MDT1-TRAIN WITH ST72F264
AN2200	GUIDELINES FOR MIGRATING ST7LITE1X APPLICATIONS TO ST7FLITE1XB
PRODUCT OPTIMIZATION	
AN 982	USING ST7 WITH CERAMIC RESONATOR
AN1014	HOW TO MINIMIZE THE ST7 POWER CONSUMPTION
AN1015	SOFTWARE TECHNIQUES FOR IMPROVING MICROCONTROLLER EMC PERFORMANCE
AN1040	MONITORING THE VBUS SIGNAL FOR USB SELF-POWERED DEVICES
AN1070	ST7 CHECKSUM SELF-CHECKING CAPABILITY
AN1181	ELECTROSTATIC DISCHARGE SENSITIVE MEASUREMENT
AN1324	CALIBRATING THE RC OSCILLATOR OF THE ST7FLITE0 MCU USING THE MAINS
AN1502	EMULATED DATA EEPROM WITH ST7 HDFLASH MEMORY
AN1529	EXTENDING THE CURRENT & VOLTAGE CAPABILITY ON THE ST7265 VDDF SUPPLY
AN1530	ACCURATE TIMEBASE FOR LOW-COST ST7 APPLICATIONS WITH INTERNAL RC OSCILLATOR
AN1605	USING AN ACTIVE RC TO WAKEUP THE ST7LITE0 FROM POWER SAVING MODE
AN1636	UNDERSTANDING AND MINIMIZING ADC CONVERSION ERRORS
AN1828	PIR (PASSIVE INFRARED) DETECTOR USING THE ST7FLITE05/09/SUPERLITE
AN1946	SENSORLESS BLDC MOTOR CONTROL AND BEMF SAMPLING METHODS WITH ST7MC
AN1953	PFC FOR ST7MC STARTER KIT
AN1971	ST7LITE0 MICROCONTROLLED BALLAST
PROGRAMMING AND TOOLS	
AN 978	ST7 VISUAL DEVELOP SOFTWARE KEY DEBUGGING FEATURES
AN 983	KEY FEATURES OF THE COSMIC ST7 C-COMPILER PACKAGE
AN 985	EXECUTING CODE IN ST7 RAM
AN 986	USING THE INDIRECT ADDRESSING MODE WITH ST7
AN 987	ST7 SERIAL TEST CONTROLLER PROGRAMMING
AN 988	STARTING WITH ST7 ASSEMBLY TOOL CHAIN
AN1039	ST7 MATH UTILITY ROUTINES

Table 28. ST7 Application Notes

IDENTIFICATION	DESCRIPTION
AN1071	HALF DUPLEX USB-TO-SERIAL BRIDGE USING THE ST72611 USB MICROCONTROLLER
AN1106	TRANSLATING ASSEMBLY CODE FROM HC05 TO ST7
AN1179	PROGRAMMING ST7 FLASH MICROCONTROLLERS IN REMOTE ISP MODE (IN-SITU PROGRAMMING)
AN1446	USING THE ST72521 EMULATOR TO DEBUG AN ST72324 TARGET APPLICATION
AN1477	EMULATED DATA EEPROM WITH XFLASH MEMORY
AN1527	DEVELOPING A USB SMARTCARD READER WITH ST7SCR
AN1575	ON-BOARD PROGRAMMING METHODS FOR XFLASH AND HDFLASH ST7 MCUS
AN1576	IN-APPLICATION PROGRAMMING (IAP) DRIVERS FOR ST7 HDFLASH OR XFLASH MCUS
AN1577	DEVICE FIRMWARE UPGRADE (DFU) IMPLEMENTATION FOR ST7 USB APPLICATIONS
AN1601	SOFTWARE IMPLEMENTATION FOR ST7DALI-EVAL
AN1603	USING THE ST7 USB DEVICE FIRMWARE UPGRADE DEVELOPMENT KIT (DFU-DK)
AN1635	ST7 CUSTOMER ROM CODE RELEASE INFORMATION
AN1754	DATA LOGGING PROGRAM FOR TESTING ST7 APPLICATIONS VIA ICC
AN1796	FIELD UPDATES FOR FLASH BASED ST7 APPLICATIONS USING A PC COMM PORT
AN1900	HARDWARE IMPLEMENTATION FOR ST7DALI-EVAL
AN1904	ST7MC THREE-PHASE AC INDUCTION MOTOR CONTROL SOFTWARE LIBRARY
AN1905	ST7MC THREE-PHASE BLDC MOTOR CONTROL SOFTWARE LIBRARY
SYSTEM OPTIMIZATION	
AN1711	SOFTWARE TECHNIQUES FOR COMPENSATING ST7 ADC ERRORS
AN1827	IMPLEMENTATION OF SIGMA-DELTA ADC WITH ST7FLITE05/09
AN2009	PWM MANAGEMENT FOR 3-PHASE BLDC MOTOR DRIVES USING THE ST7FMC
AN2030	BACK EMF DETECTION DURING PWM ON TIME BY ST7MC

16 KNOWN LIMITATIONS

16.1 PA2 LIMITATION WITH OCMP1 ENABLED

Description

This limitation affects only Rev B Flash devices (with Internal Sales Type 72F60xxxxx\$7); it has been corrected in Rev W Flash devices (with Internal Sales Type 72F60xxxxx\$9).

Note: Refer to [Figure 68 on page 115](#)

When Output Compare 1 function (OCMP1) on pin PA6 is enabled by setting the OC1E bit in the TCR2 register, pin PA2 is also affected.

In particular, the PA2 pin is forced to be floating even if port configuration (PADDR+PADR) has set it as output low. However, it can be still used as an input.

16.2 UNEXPECTED RESET FETCH

If an interrupt request occurs while a "POP CC" instruction is executed, the interrupt controller does not recognise the source of the interrupt and, by default, passes the RESET vector address to the CPU.

Workaround

To solve this issue, a "POP CC" instruction must always be preceded by a "SIM" instruction.

16.3 SCI WRONG BREAK DURATION

Description

A single break character is sent by setting and re-setting the SBK bit in the SCICR2 register. In some cases, the break character may have a longer duration than expected:

- 20 bits instead of 10 bits if M=0

- 22 bits instead of 11 bits if M=1.

In the same way, as long as the SBK bit is set, break characters are sent to the TDO pin. This may lead to generate one break more than expected.

Occurrence

The occurrence of the problem is random and proportional to the baudrate. With a transmit frequency of 19200 baud (fCPU=8MHz and SCI-BRR=0xC9), the wrong break duration occurrence is around 1%.

Workaround

If this wrong duration is not compliant with the communication protocol in the application, software can request that an Idle line be generated before the break character. In this case, the break duration is always correct assuming the application is not doing anything between the idle and the break. This can be ensured by temporarily disabling interrupts.

The exact sequence is:

- Disable interrupts
- Reset and Set TE (IDLE request)
- Set and Reset SBK (Break Request)
- Re-enable interrupts

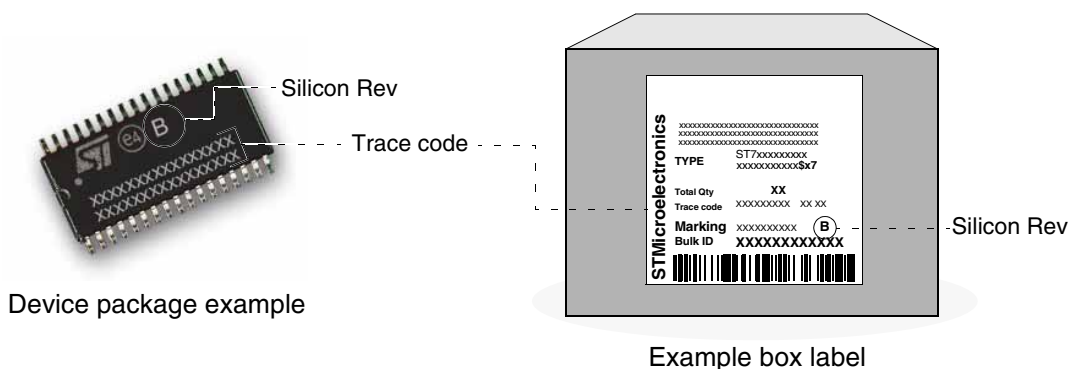
16.4 USB Behavior with LVD Disabled

On ROM devices, if the LVD is disabled, the USB is disabled by hardware. So, the LVD is forced by ST to 0 (LVD enabled). Refer to the ST7260 option list for details.

Figure 68. Identifying Silicon Revision from Device Marking and Box Label

The silicon revision can be identified either by Rev letter or obtained via a trace code. Follow the procedure below:

1. Identify the silicon revision letter from either the device package or the box label. For example, “B”, etc.
2. If the revision letter is not present, obtain the silicon revision by contacting your local ST office with the trace code information printed on either the box label or the device package.



17 REVISION HISTORY

Date	Revision	Main Changes
13-Feb-2006	1	Initial release
02-Nov-2006	2	Added Known Limitations section (with new PA2 limitation)

Notes:**Please Read Carefully:**

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